Scanning	LIB.

Safety

RoHS

SPECIFICATION FOR APPROVAL

- **CUSTOMER : LG Electronics inc.**
- **ITEM : Power Supply Unit.**
- **P/NO**

Model Name	Customer	Supplier
LGP55-13LPB	EAY62811001	PLDK-L212A

- **DATE : 2013. 08. 07**
- **Revision : 3.0**
- **Remark : MP (PCB REV 3.0)**

Producing District : YANTAI, CHINA (중국 연태)
(생산지) WROCLAW, POLAND (폴란드 브루츠와프)

★ Safety Standard Parts [안전규격부품 List]

Power Cord, Power Plug, X/Y-Capacitor, Power Switch, Fuse, SMPS Trans, Stand-By Trans, Photo coupler, Insulation(절연) Resistor, Discharge(방전) Resistor, Fusing Resistor, FBT.CPT, CPT Socket, DY, D-Coil, Line Filter, PCB Material, Front / Back-cover Material Relay(1-2차간), Varistor, Adapter

★ EMC Standard Parts [전자규격 부품 List]

Power Plug, Line Filter, X-Capacitor, Y-Capacitor, SMPS Trans, Tuner, Saw-Filter, Shield Case, Oscillator, Pattern Change

★ Green [유해물질 확인사항]

This item must meet the standards of LG Electronics for six major substances as designated by RoHS for control.

(Cd: 10ppm under, Pb/Hg/Cr+6/PBB/PBDE: 100 ppm under)

LG Innotek

LG Innotek Co., Ltd
LG Twin Tower 33/34F, Yeouido-dong,
Yeongdeungpo-gu, Seoul, Korea
Tel. : +82-2-3777-1114
Fax. : +82-2-3777-0082

Documentation For Approval

Model Name	Customer	Supplier
LGP55-13LPB	EAY62811001	PLDK-L212A

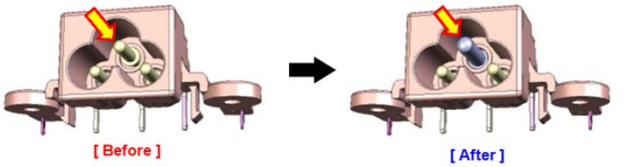
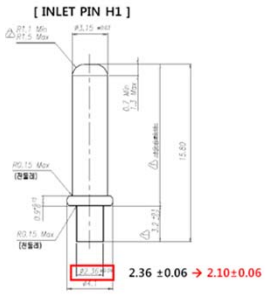
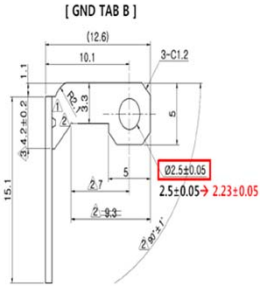
Written	Checked		Approved
J.S Lee	K.T Choi		S.H JANG

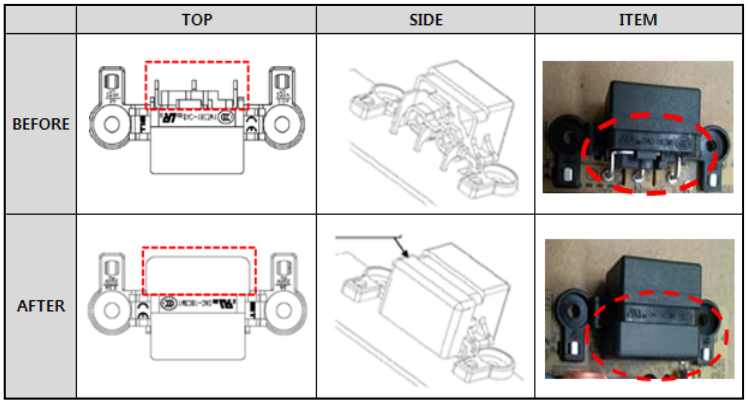
Contents

Revision History

Rev No.	Contents	Date of Approval	Checked	Remark
0.1	Apply to PV (PCB REV 0.2) PCB P/No. EAX64905801(1.4) Micom Ver : 0.99a (Checksum : 0x1F7D) PV 1st Edition.	12.10.19	K.T Choi	
0.2	Apply to PV (PCB REV 0.22) PCB P/No. EAX64905801(1.6) Micom Ver : 0.99a (Checksum : 0x1F7D)	12.11.26	K.T Choi	
1.0	Apply to MP (PCB REV 1.0) PCB P/No. EAX64905801(1.8) Micom Ver : 1.00a (Checksum : 0x1F8D) MP 1st Edition - Add UL Mark	12.12.17	K.T Choi	
1.1	Apply to MP (PCB REV 1.0) PCB P/No. EAX64905801(1.8) Micom Ver : 1.00a (Checksum : 0x1F8D) 1.Change production site of LGIT Trans - LGIT Yantai → CLOVER Mundeung OEM	13.01.10	K.T Choi	
1.2	Apply to MP (PCB REV 1.0) PCB P/No. EAX64905801(1.8) Micom Ver : 1.00a (Checksum : 0x1F8D) 1. Delete the POLYESTER FILM TAPE company of Transformer : METAL LINE CO., LTD	13.01.29	K.T Choi	
1.3	Apply to MP (PCB REV 1.0) PCB P/No. EAX64905801(1.8) Micom Ver : 1.00a (Checksum : 0x1F8D) 1. Improve Audio Noise : Change Bonding position & Side Bond Material - Item : 13S-DD02 - Location : L801 1) Before : Silicon bond 4 Point + Center Bond 	13.02.07	K.T Choi	

Rev No.	Contents	Date of Approval	Checked	Remark
1.3	**Apply to MP (PCB REV 1.0)** **PCB P/No. EAX64905801(1.8)** **Micom Ver : 1.00a (Checksum : 0x1F8D)** **2) After : Silicon bond 2 Point + Three bond 6 Point**  **4M Change process** **1) Responsibility of 4M change : LGE** **2) Running Change : YES (Minor)** **3) Goods of Stock : No Re-Work**	13.02.07	K.T Choi	
1.4	**Apply to MP (PCB REV 1.0)** **PCB P/No. EAX64905801(1.8)** **Micom Ver : 1.00a (Checksum : 0x1F8D)** **1. Update Part list** **: Resister components vendors which LGIT can use.** **2. Update CCL** **: Resister PCB vendors which LGIT can use.** **3. Change supplier company from SENSITRON to SMC** **4M Change process** **1) Responsibility of 4M change : LGE** **2) Running Change : Apply immediately** **3) Goods of Stock : No Re-Work** **4. Improve Driver on signal Line noise** **- J39 : Jumper wire → Resistor Axial 470K J 1/4W** **- R722 : SMD Resistor 470KΩ J 1608 → 0Ω J 1608** **4M Change process** **1) Responsibility of 4M change : LGE** **2) Running Change : No (Apply on April 1st)** **3) Goods of Stock : No Re-Work**	13.03.29	K.T Choi	

Rev No.	Contents	Date of Approval	Checked	Remark
2.0	**Apply to MP (PCB REV 2.0)** **PCB P/No. EAX64905801(1.9)** **Micom Ver : 1.00a (Checksum : 0x1F8D)** **1. Change of PCB (Revision 1.0 → 2.0)** **: To improve productivity** **: To ensure safety distance** **: To improve Diode Forming productivity** **< Change List >** **- SK101 insert hole shape change (circle → oval)** **- J1 move 1.25mm up** **- Ready HD101 SMD Supporter on PCB only** **- Cap holder move 1.5mm** **2. Improve Driver on signal Line noise** **1) C705 : Add MLCC 0.1uF 50V 1608** **2) J39 : Resistor Axial 470K J 1/4W → Jumper wire** **3) R722 : SMD Resistor 0Ω J 1608 → 470KΩ J 1608** **3. Improve mechanical matching for Ground Pin and Ground Tab Spec.** **- Item : AC socket (DAC-18C3M1)** **- Location : SK100** **- Issue : Change Ground Pin and Ground Tab Spec.** **1) Ground PIN Spec : 2.36 ± 0.06 → 2.10 ± 0.06** **2) Ground TAP Spec : 2.5 ± 0.06 → 2.23 ± 0.06**  [Before] [After] **1-1. Ground Pin Spec.**  [INLET PIN H1] 2.36 ±0.06 → 2.10±0.06 **1-2. Ground Tab Spec**  [GND TAB B] Ø2.5±0.05 2.5±0.05→ 2.23±0.05 **4M Change process** **1) Responsibility of 4M change : LGE** **2) Running Change : NO (on April 30th)** **3) Goods of Stock : No Re-Work**	13.04.22	K.T Choi	

Rev No.	Contents	Date of Approval	Checked	Remark
2.1	**Apply to MP (PCB REV 2.0)** **PCB P/No. EAX64905801(1.9)** **Micom Ver : 1.00a (Checksum : 0x1F8D)** **1. Change AC socket to prevent PL (Product liability) problem** **- Location : SK100** **- DAC-18C3M1 → DAC-18C3M1C (with cover)**  **4M Change process** **1) Responsibility of 4M change : LGE** **2) Running Change : YES** **3) Goods of Stock : No Re-Work**	13.07.12	K.T Choi	
2.2	**Apply to MP (PCB REV 2.0)** **PCB P/No. EAX64905801(1.9)** **Micom Ver : 1.00a (Checksum : 0x1F8D)** **1. Add RTV Bond Maker** **- Maker : DAEHEUNG CHEMICAL CO.,LTD.** **- Specification : SR-9000** **2. Change Packing Drawing** **: Change LG INNOTEK Logo size** **4M Change process** **1) Responsibility of 4M change : LGIT** **2) Running Change : YES** **3) Goods of Stock : No Re-Work**	13.07.16	K.T Choi	

Rev No.	Contents	Date of Approval	Checked	Remark
3.0	**Apply to MP (PCB REV 3.0)** **PCB P/No. EAX64905801(2.0)** **Micom Ver : 1.00a (Checksum : 0x1F8D)** **1.Change Diode to prevent RENESAS PFC IC #5 CS Pin dead** **- Change Location : D607 → ZD602** **- SMD Diode (SOD-123) → SMD Zener Diode (SOD-123)** **- Change PCB only silk** **1) Top Silk : Revision (2.0 → 3.0)** **2) Bottom Silk : Location Number (D607 → ZD602)** **4M Change process** **1) Responsibility of 4M change : LGE** **2) Running Change : NO (Apply Immediately)** **3) Goods of Stock : No Re-Work**	13.08.07	K.T.Choi	

Software Revision History

No.	Firmware Revision Contents	Date of Approval	Checked	Remark
1	**- Firmware Version 1.00a** **Checksum 0x1F8D**	12.12.17	K.T Choi	

CTQ Management

Specification

1. INTRODUCTION

1.1 Scope

This approval is the description related to every electrical and structural specifications and reliability For Power Supply Unit used on 55 inch LGE LED TV.

1.2 Customers product related items

Product : Power Supply Unit
Part code : EAY62811001

1.3 Product name

Product name : PLDK-L212A
Revision code : 3.0

2. SPECIFICATION

2.1 Input Requirements

Nominal Input Voltage	AC 100V to AC 240V
Input Voltage Variation	AC 90V to AC 264V
Input Current	Under 2.0Arms . (at 100Vac & Nominal Load) Under 1.2Arms . (at 240Vac & Nominal Load)
Nominal Frequency	50 / 60 Hz
Frequency Variation Range	47 Hz to 63 Hz
Phase	Single
Leakage Current	0.35mA_peak. (100Vac ~ 240Vac)
Surge Immunity	± 4kV / 1000ns / 0˚ to 360˚
Hold-up Time	More than 20ms at 100Vac and maximum output load ※When it doesn't meet 20ms hold up time, 1. PSU restarts. 2. No hardware failure.(All components)
Lightning Surge	2kA Normal, Common Mode
Inrush Current	80A zero-peak max at cold start and any specified line, load, temperature conditions.

2.1.1 Power Factor

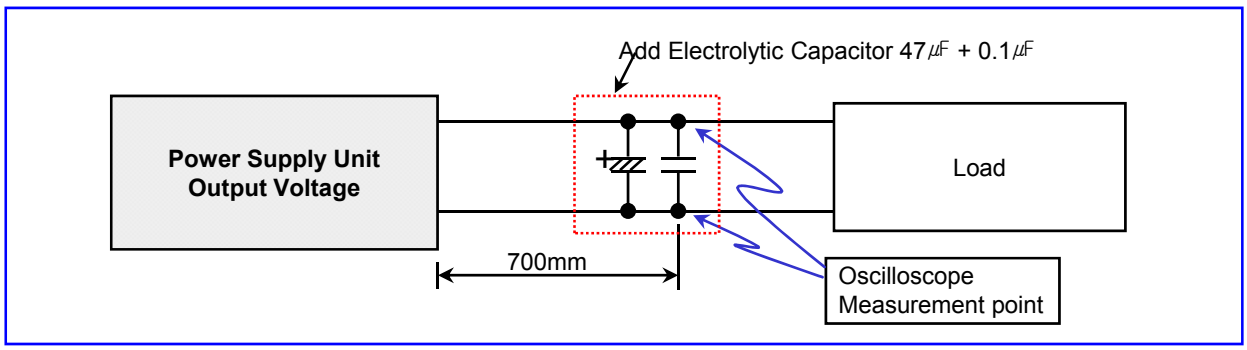
over than 0.9 at 90 – 264Vac & max load condition

2.2 Power Output Characteristics

Output	Voltage Variable range [V]	Rated Current (Min, Max) [Amean]	Voltage Regulation [V]	Ripple Voltage [mVp_p]
3.5V (STBY)	3.325V ~ 3.675V	0.3W Under(15mA)	-	-
		1.5A(0.2~1.5A) (ON condition)	± 5%	250 mVp_p
12V	11.4V ~ 12.6V	2.0A (0.2~2.0A)	± 5%	350 mVp_p
24V	22.8V ~ 25.2V	0.8A (0.1~0.8A)	± 5%	500 mVp_p
LED B+	68.5V ~ 89.5V	0.15A(0.142~0.158A) × 6Ch	± 5%	-

* On Condition : In a moment of Power_ON Signal activated, the current of 3.5V output should be limited within 40mA(Max) at LCD TV condition for stability.
Do not turn “Power_ON” Signal on at the load condition of 3.5V output, more than 40mA.
* Total regulation for each output circuit includes the results of input voltage variation, load variation, warm-up drift and temperature change.
* The following instruments shall be used for measuring ripple noise.
1. Probe having impedance ratio of 1:1.
2. Oscilloscope having frequency characteristic of 100MHz or more.

Test Point : power output each pin



※ Ripple and noise are measured at the end of output cable which are added a 0.1uF ceramic capacitor and 47uF electrolytic capacitor. (connected parallel)

2.2.1 Stand By Power Consumption

Output Voltage	3.5V (STBY)	12V	24V
Load [A]	0.015	Don’t Care (Power-Off)	
Wattage [W]	Less than 0.3W Under (230Vac / 50Hz)		

2.3 Environment Requirement

Operating Temperature Range	-10℃ to 40℃ (60℃:No Hardware Failure, TV SET Condition)
Operating Humidity Range	30 to 85 %
Storage Temperature Range	-25 to 85 deg.
Storage humidity Range	5 to 90 %
MTBF (Mean Time Between Failure)	50,000 hour
Cooling Condition	Natural Air
Shock	98 ㎨ Shock test consists of pivoting the power supply, from one edge of it's bottom side, on a flat surface (such as wood having thickness of 10mm or more) and allowing the opposite edge to fall from a height of 50mm to this surface. The test is performed three times on each edge of the bottom side of the power supply

2.4 Dielectric Strength Voltage and Insulation Resistance

Safety

Dielectric Strength Voltage	AC 1.5KV or DC 2,121V 1Min 10mA (Test SPEC) AC 1.8KV 1 SEC 10 mA.(PSU Mass Production) Between Primary and All Secondary Circuits.

Insulation Resistance	Insulation resistance shall be more than 8M ohm (at DC 500V) Between Primary Live, Neutral line and Secondary.

* Above tests are performed at room temperature in non-condensing atmospheric conditions
* Frame grounds are connected to secondary circuits.

2.5 Burn-in

More than 2 hours at 45℃(±5℃), Normal input voltage.
AC on/off must be test 1 time after burn-in.
80% Load (except LED String current : 150mA) of specification.

2.6 Interface

Appellation	Explanation	Signal Direction	Action
POWER ON	Vcc Circuit ON/OFF	Input	High : Vcc ON Low : Vcc OFF

2.7 Product Safety

Safety Standards to be applied	Design to meet the requirements as follows UL60950, IEC60950, IEC60065 and 60950
EMI/RFI Standards to be applied	Design to meet the requirements as follows FCC and EN55020, EN55013 Class B with 4dB minimum margin.

2.8 Construction

Weight	Less than 450g
Unit Size (typ.)	159(W) X 270(D) X 19.6(H)

2.9 Function of protection

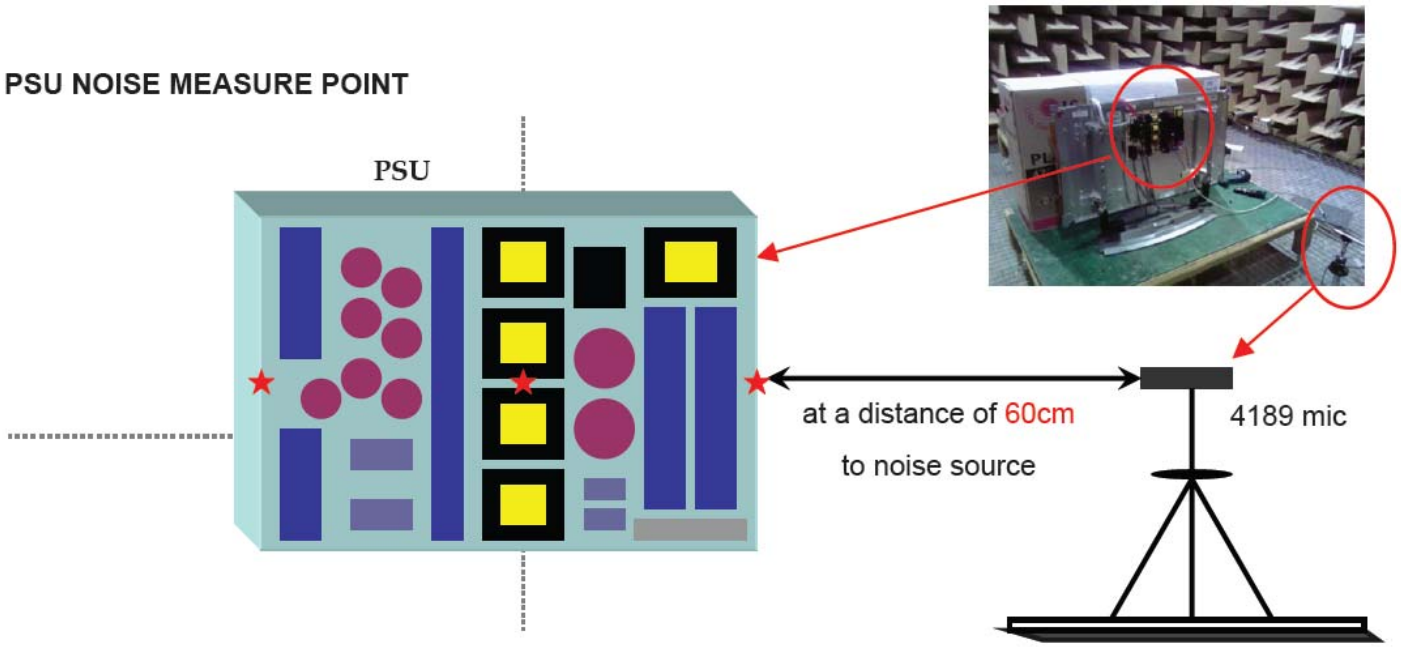
Protection	Output Circuit	Trip point		Notes
		Min	Max	
Over Current	STBY 3.5V	1.8A	5.0A	Auto Re-start
	12V	3.0A	18.0A	Latch
	24V	2.0A	11.0A	Latch
Short Circuit	STBY 3.5V	-	-	Auto Re-start
	12V	-	-	Latch
	24V	-	-	Latch

* This Power Supply has above-mentioned protections.
* Short circuit protection between different output terminals is not considered.
* Trip point for over voltage indicates the operating point when the output voltage slowly increases.
* The conditions of Over Current measurement
  Multi output(3.5V,12V,24V) is nominal load state except an over current measurement.

2.10 Sound Noise Characteristics.

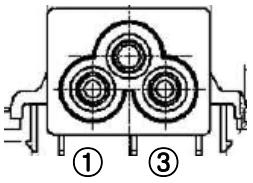
PSU Noise Specification
22.5 dB(a) / 20.u Pa 2.0E-5 Pa
(1/1 octave, A-weighting, to 1khz ~ 16khz Total overall

Measure Location : Anechoic Room
Measure Condition : At a distance of 60cm mic
Full white pattern, at AC 110V/220V
The max specification
(measure 3 points, at PSU center and left & right on the side)



2.11 Connector Specification

2.11.1 Connectors Usage



SK100 (DAC-18C3M1)

SK100 (DAC-18C3M1)

No	Name
1	LIVE
2	GND
3	NEUTRAL

P702 (20010WR-06A03)

No	Name
1	MICOM_VDD
2	RXD
3	TXD
4	TOOL 0
5	RESET
6	GND

P201 (SMAW200-H24S2)

P201			
1	Power on	2	DRV-ON
3	3.5V	4	P-DIM
5	3.5V	6	P-DIM 2
7	GND	8	GND
9	24V	10	24V
11	GND	12	GND
13	12V	14	12V
15	12V	16	24V
17	GND	18	GND
19	GND	20	GND
21	GND	22	V-SYNC
23	SPI-SIN	24	SPI-SCLK

P801 (IS100-L08T-C46) (BLACK)

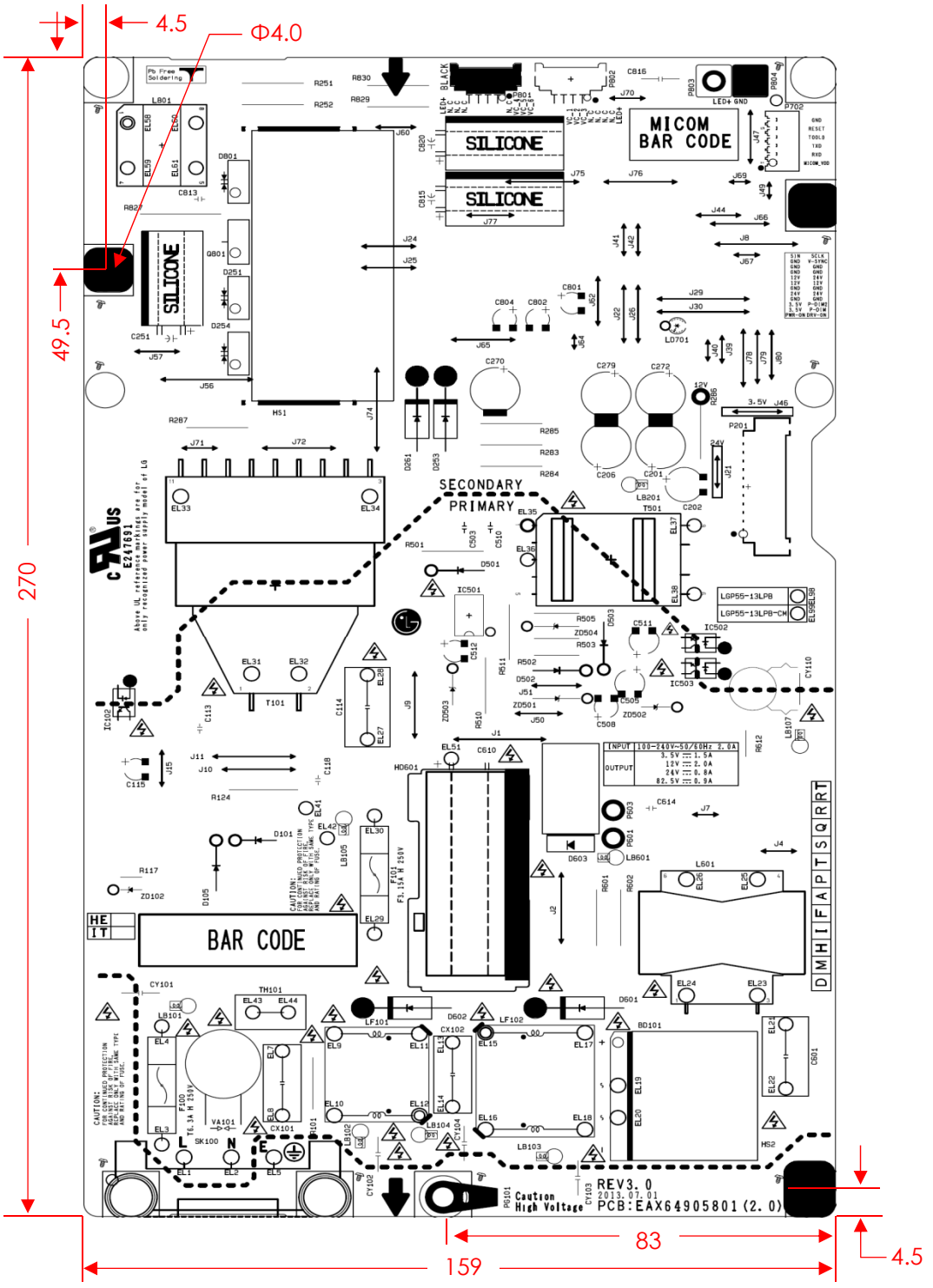
No	Name
1	VC_6
2	VC_5
3	VC_4
4	N.C
5	N.C
6	N.C
7	N.C
8	LED +

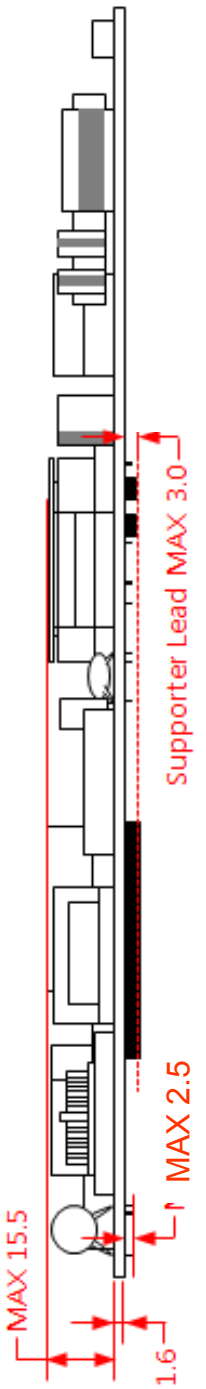
P802 (IS100-L08T-C46-A) (WHITE)

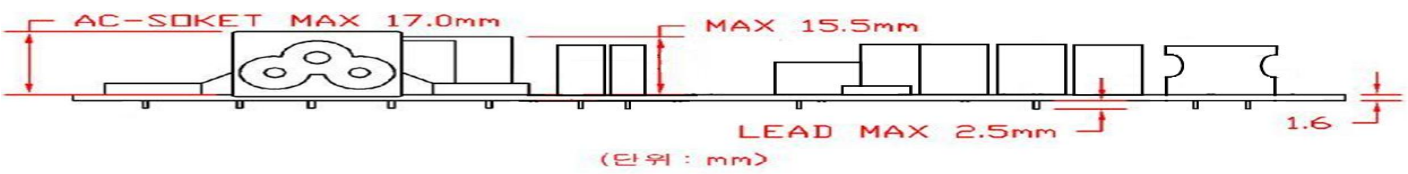
No	Name
1	LED +
2	N.C
3	N.C
4	N.C
5	N.C
6	VC_3
7	VC_2
8	VC_1

2.12 PCB Dimension.

1) Power board PCB : 159mm X 270mm X 1.6(T)mm
2) Component height : Max 15.5mm (Except SK100 : Max 17.0mm)
3) Lead Cutting : Max 2.5mm
4) PCB Material : FR-1,KB,DS,L,R-8700 CTI-600



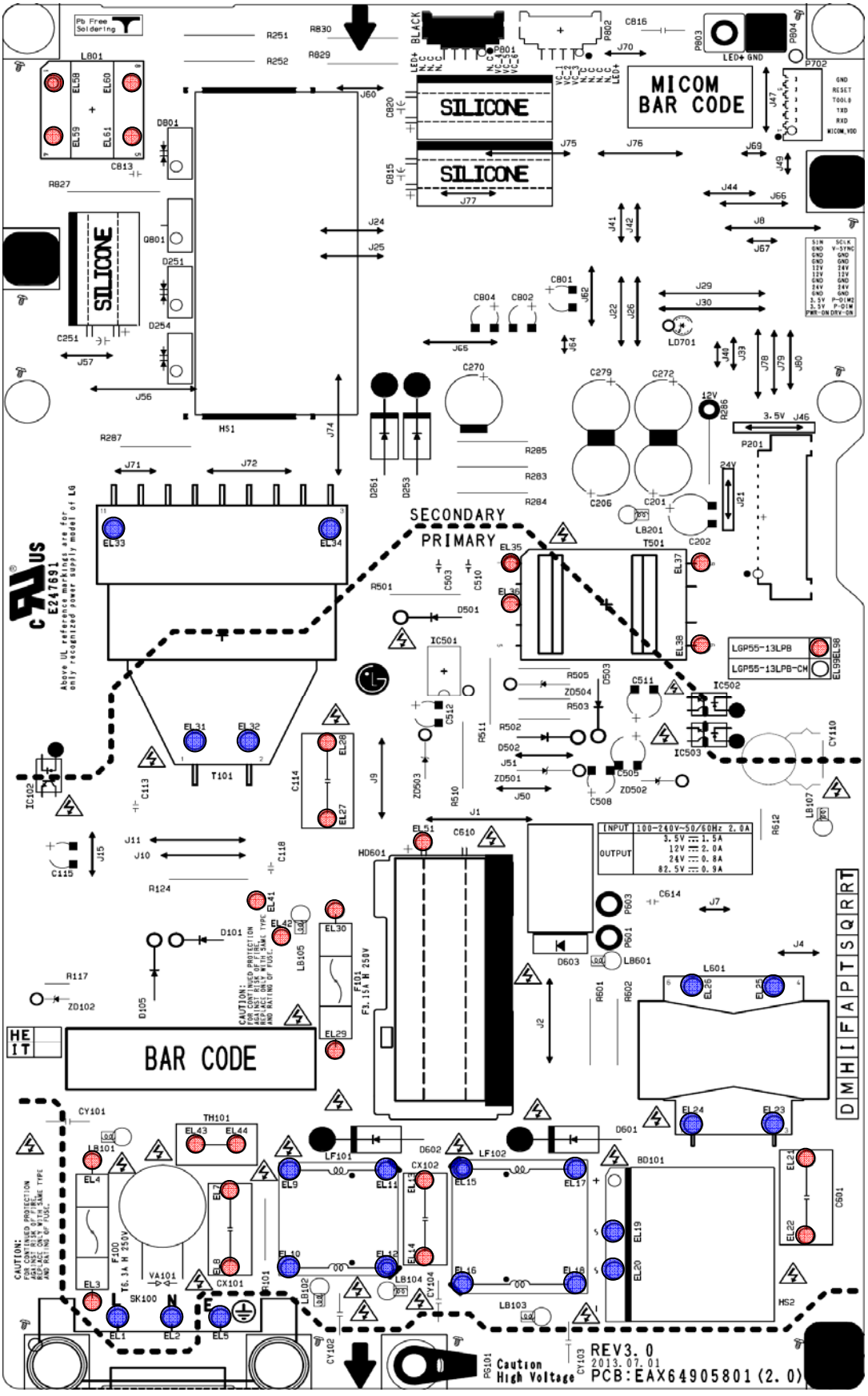




2.13 Apply to the Eyelet point.

Apply to the Eyelet point 2.0Φ : EL1,EL2,EL5,EL9,EL10,EL11,EL12,EL15,EL16,EL17,EL18,EL19,EL20,EL23, EL24,EL25,EL26,EL31,EL32,EL33,EL34 (21EA)

Apply to the small Eyelet point 1.6Φ : EL3,EL4,EL7,EL8,EL13,EL14,EL21,EL22,EL27,EL28,EL29,EL30,EL35,EL36, EL37,EL38,EL41,EL42,EL43,EL44,EL51,EL58,EL59,EL60,EL61,EL98 (26EA)



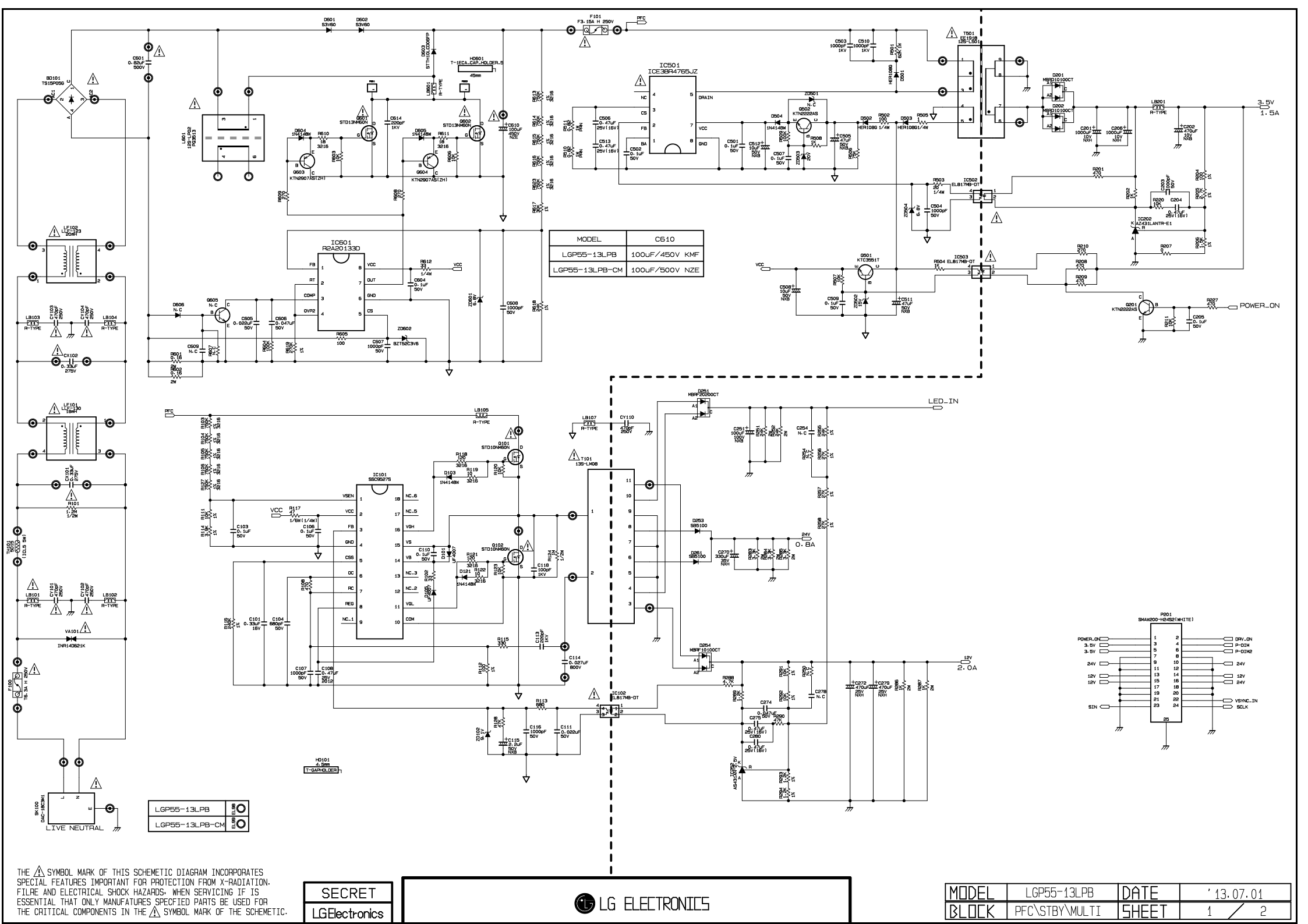
2.14 Electrical Characteristics

<table>
<tr><th>No.</th><th>Test Item</th><th>Test method</th></tr>
<tr><td>1</td><td>Intermittent Operation stability Test</td><td>The switching regulator shall ON/OFF for 20,000 time at an Interval of 10 sec at maximum load, after that electrical Characteristics shall be satisfied.</td></tr>
<tr><td>2</td><td>Low temperature operation</td><td>The switching regulator is left at the operating guarantee Minimum temperature for 2 hours without applying electricity. After that power shall be turned on, and then the electrical Characteristics shall be satisfied.</td></tr>
<tr><td>3</td><td>Low temperature Storage test Leave At low temperature</td><td>The switching regulator is left at minimum storage Temperature for 96 hours or more.
Then the switching regulator is left at a room temperature and humidity for 1 hour or more, after that electrical characteristics shall be satisfied.</td></tr>
<tr><td>4</td><td>Heat cycle storage test</td><td>The switching regulator is 10 consecutive temperature cycle that shown below is performed and then leave them at room temperature and humidity for 1 hour or more.
After that, electrical characteristics shall be satisfied.
<table>
<tr><th>Time</th><th>Temperature</th></tr>
<tr><td>30 minutes</td><td>25℃</td></tr>
<tr><td>30 minutes</td><td>25℃ -> -20℃</td></tr>
<tr><td>60 minutes</td><td>Minimum storage temperature (-20℃)</td></tr>
<tr><td>30 minutes</td><td>-20℃ -> 25℃</td></tr>
<tr><td>30 minutes</td><td>25℃</td></tr>
<tr><td>30 minutes</td><td>25℃ -> 70℃</td></tr>
<tr><td>60 minutes</td><td>Maximum storage temperature (70℃)</td></tr>
<tr><td>30 minutes</td><td>70℃ -> 25℃</td></tr>
</table></td></tr>
<tr><td>5</td><td>Heat shock test</td><td>Heat shock test performed under following conditions without applying electricity and then leave them at room temperature and humidity for 1 hour or more.
After that, electrical characteristics shall be satisfied.
Condition : -45℃(30minutes), 120℃(30minutes),
Switching time : Less than 5 minutes, 200 cycles.</td></tr>
</table>

2.15 Mechanical Characteristics

No.	Test Item	Test method
1	Appearance	There shall be no contaminant or dirt on the switching regulator which has adverse effect on electrical characteristics. There shall be no excessive unevenness or scratches on the plated or painted surface.
2	Vibration	While applying electricity : Vibration frequency : 5 ~ 100Hz Acceleration : 4.9 m/s∧2 Vibration in X,Y,Z direction for 30 minutes While applying electricity : Vibration frequency : 5 ~ 100Hz Acceleration : 14.7 m/s∧2 Vibration in X,Y,Z direction for 30 minutes After that electrical characteristics shall be satisfied. There shall be no damage to appearance and construction.
3	Shock	Shock : 98 m/s∧2 On the oak more than 10mm thickness with the flat face, raise the one side for 50mm, and it carries out each side free fail for three sides. There shall be no damage to appearance and construction.

Schematic Diagram



MODEL	C610
LGP55-13LPB	100uF/450V KMF
LGP55-13LPB-CM	100uF/500V NZE

LGP55-13LPB	EL99
LGP55-13LPB-CM	EL99

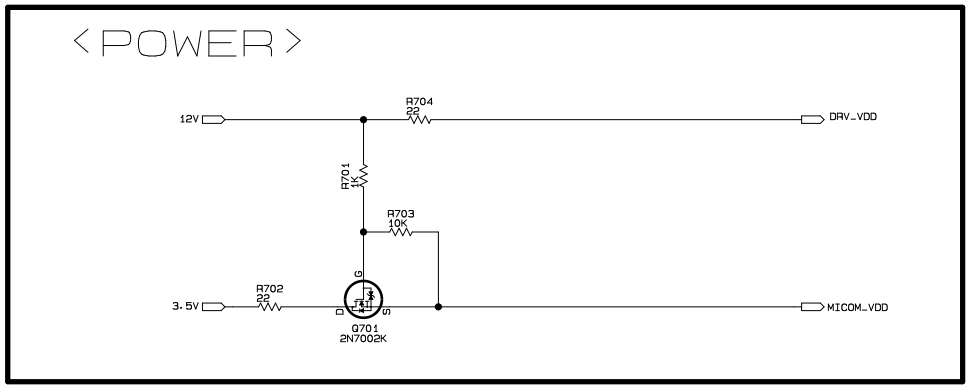
THE ⚠ SYMBOL MARK OF THIS SCHEMETIC DIAGRAM INCORPORATES SPECIAL FEATURES IMPORTANT FOR PROTECTION FROM X-RADIATION. FILRE AND ELECTRICAL SHOCK HAZARDS, WHEN SERVICING IF IS ESSENTIAL THAT ONLY MANUFATURES SPECFIED PARTS BE USED FOR THE CRITICAL COMPONENTS IN THE ⚠ SYMBOL MARK OF THE SCHEMETIC.

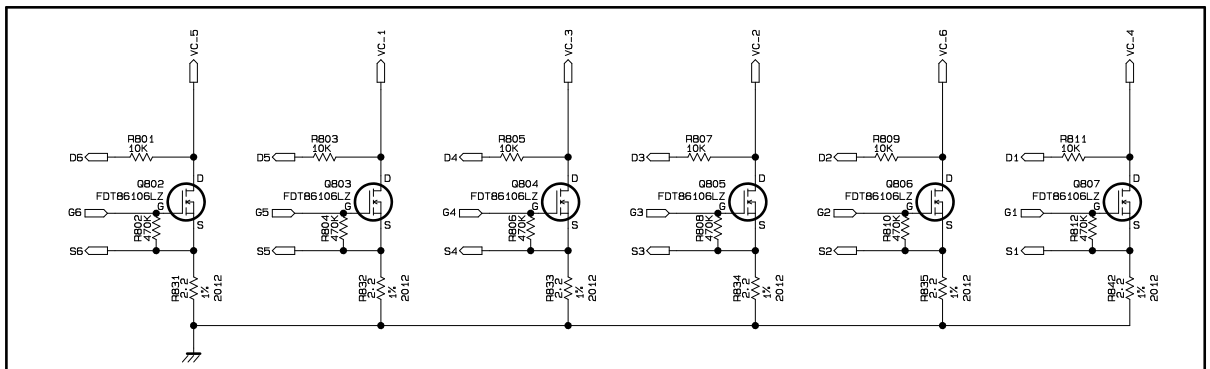
SECRET

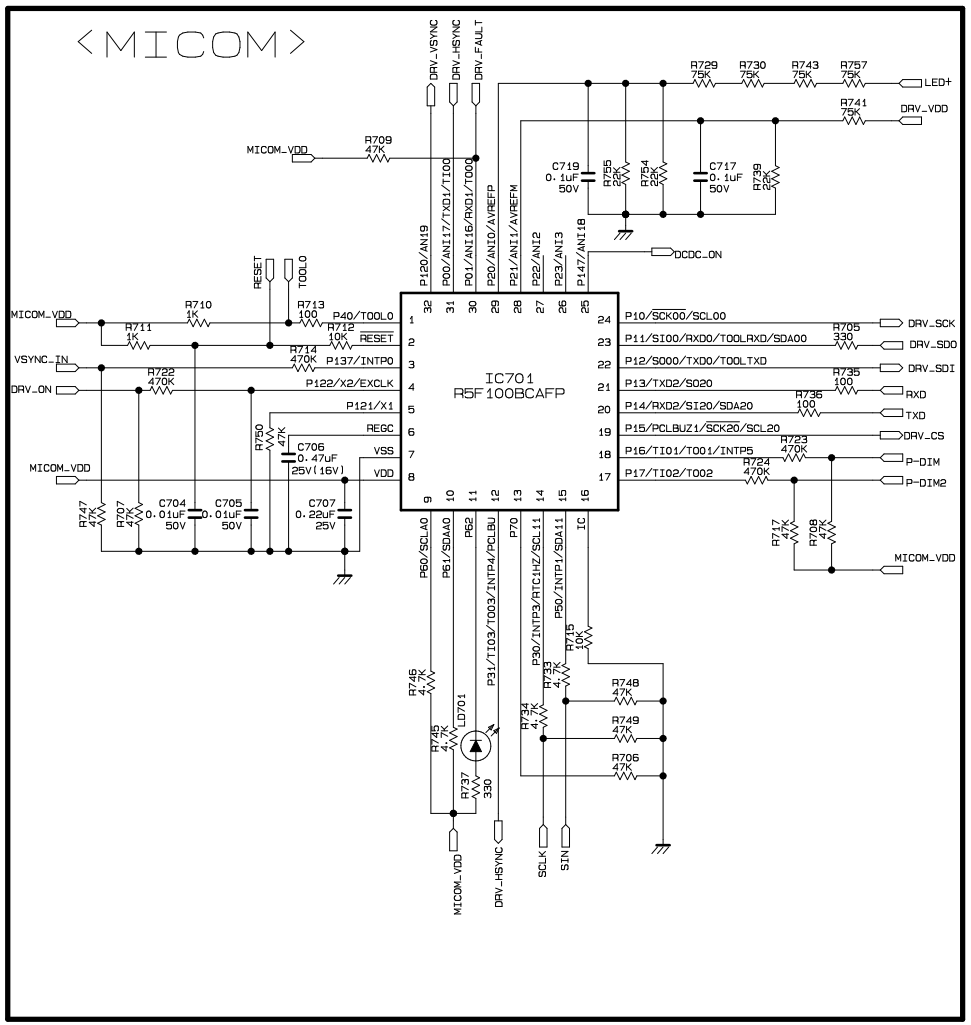
LGElectronics

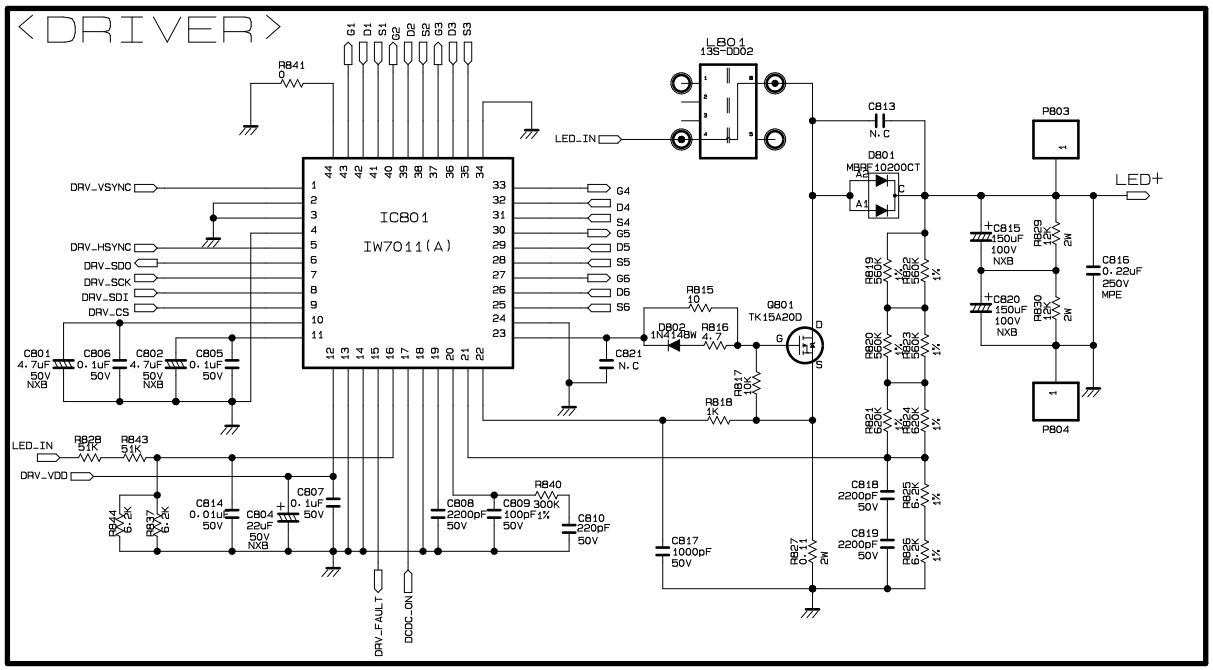
LG ELECTRONICS

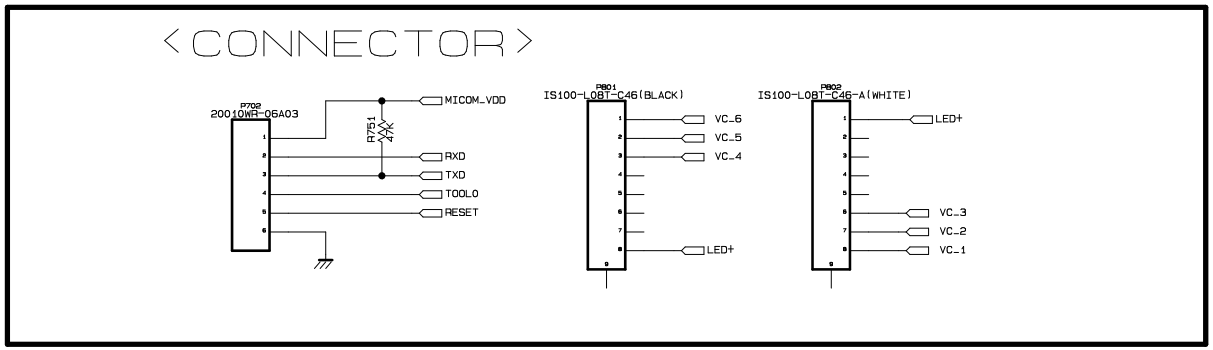
MODEL	LGP55-13LPB	DATE	'13.07.01
BLOCK	PFC\STBY\MULTI	SHEET	1 / 2











THE ⚠ SYMBOL MARK OF THIS SCHEMETIC DIAGRAM INCORPORATES SPECIAL FEATURES IMPORTANT FOR PROTECTION FROM X-RADIATION. FILRE AND ELECTRICAL SHOCK HAZARDS, WHEN SERVICING IF IS ESSENTIAL THAT ONLY MANUFATURES SPECFIED PARTS BE USED FOR THE CRITICAL COMPONENTS IN THE ⚠ SYMBOL MARK OF THE SCHEMETIC.

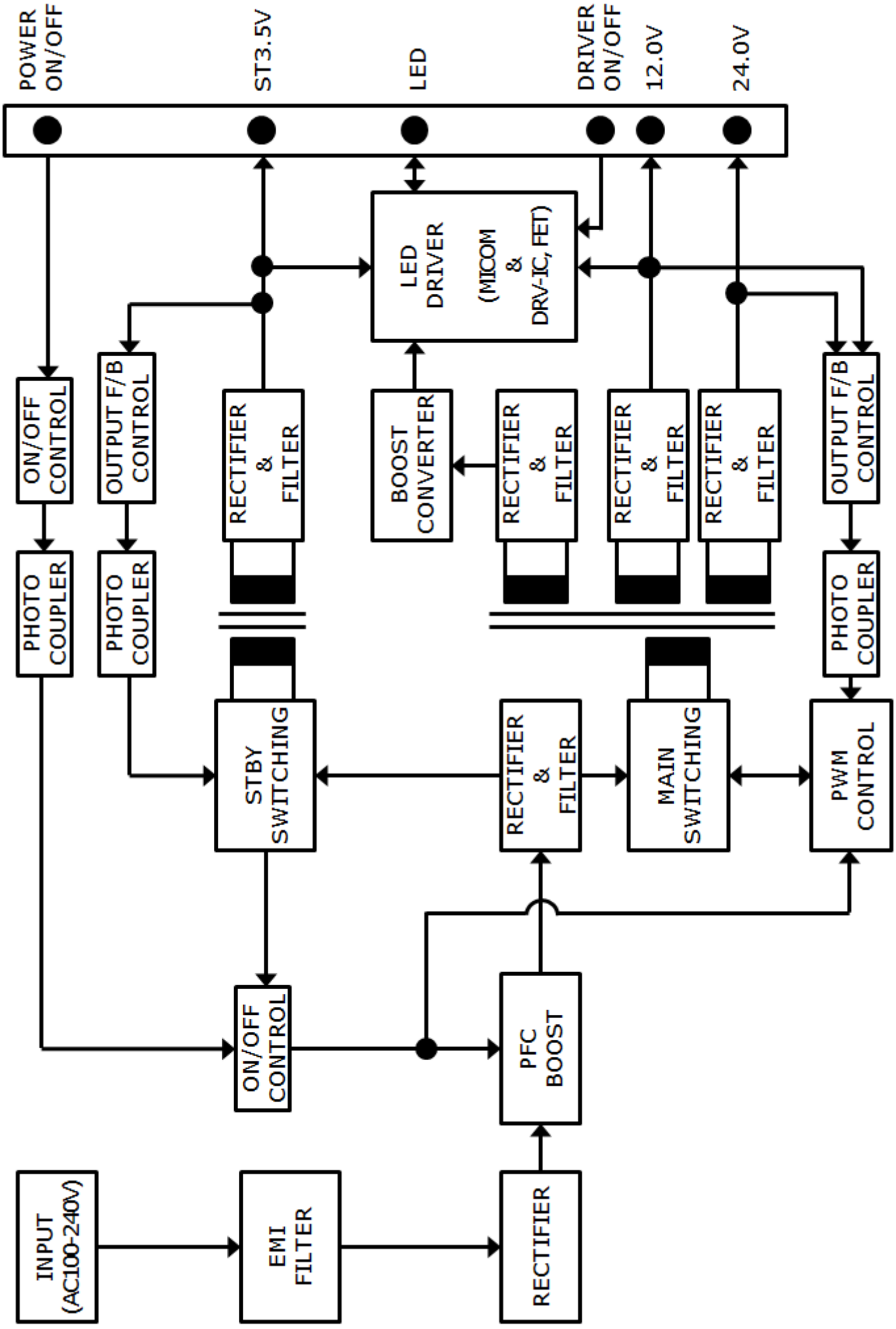
SECRET

LGElectronics

LG ELECTRONICS

MODEL	LGP55-13LPB	DATE	'13.07.01
BLOCK	DRV	SHEET	2 / 2

Block Diagram


POWER ON/OFF
ST3.5V
LED
DRIVER ON/OFF
12.0V
24.0V
LED DRIVER (MICOM & DRV-IC, FET)
ON/OFF CONTROL
OUTPUT F/B CONTROL
RECTIFIER & FILTER
BOOST CONVERTER
RECTIFIER & FILTER
RECTIFIER & FILTER
RECTIFIER & FILTER
OUTPUT F/B CONTROL
PHOTO COUPLER
PHOTO COUPLER
PHOTO COUPLER
STBY SWITCHING
RECTIFIER & FILTER
MAIN SWITCHING
PWM CONTROL
ON/OFF CONTROL
PFC BOOST
INPUT (AC100-240V)
EMI FILTER
RECTIFIER

Parts List

LGP55-13LPB (EAY62811001)

REV	P/N	Product Maker	L/V	Q'ty	UNIT	LOCATION	SPECIFICATION	DESCRIPTION	MAKER	New part history
3.0	EAY62811001	LGIT	MI				DIODE ASS'Y	HEAT SINK ASS'Y		
3.0	EAY62811001	LGIT	MI	1	EA	HS1	HS1 (63X30X11.3)	HEAT SINK	YUWON NRT	
3.0	EAY62811001	LGIT	MI	1	EA	HS1	HS1 (63X30X11.3)	HEAT SINK	HUAPENG	
3.0	EAY62811001	LGIT	MI	1	EA	HS1	HS1 (63X30X11.3)	HEAT SINK	GUOTAI	
3.0	EAY62811001	LGIT	MI	1	EA	D251	MBRF20200CT 200V 20A ITO-220AB	DIODE	SMC	
3.0	EAY62811001	LGIT	MI	1	EA	D251	MBRF20U200CT 200V 20A TO-220IS	DIODE	KEC	
3.0	EAY62811001	LGIT	MI	1	EA	D801	MBRF10200CT 200V 10A ITO-220AB	DIODE	SMC	
3.0	EAY62811001	LGIT	MI	1	EA	D801	MBRF10U200CT 200V 10A TO-220IS	DIODE	KEC	
3.0	EAY62811001	LGIT	MI	1	EA	D254	MBRF10100CT 100V 10A ITO-220AB	DIODE	SMC	
3.0	EAY62811001	LGIT	MI	1	EA	D254	MBRF10U100CT 100V 10A TO-220IS	DIODE	KEC	
3.0	EAY62811001	LGIT	MI	1	EA	Q801	STF19NF20 200V 15A TO-220FP	FET	STM	
3.0	EAY62811001	LGIT	MI	4	EA	FOR D251,D254,D801,Q801	BHM Screw , M3.0 * 6.0L, w ith Clamfix, Cr3+WH Plating	SCREW	SEOUL METAL	
3.0	EAY62811001	LGIT	MI	4	EA	FOR D251,D254,D801,Q801	BHM Screw , M3.0 * 6.0L, w ith Clamfix, Cr3+WH Plating	SCREW	ASEA BOLT	
3.0	EAY62811001	LGIT	MI	4	EA	FOR D251,D254,D801,Q801	BHM Screw , M3.0 * 6.0L, w ith Clamfix, Cr3+WH Plating	SCREW	SUNG HO METAL	
3.0	EAY62811001	LGIT	MI	0.04	GR	FOR D251,D254,D801,Q801	HC300	SILICON GREASE	CHANG AMLS	
3.0	EAY62811001	LGIT	MI	0.04	GR	FOR D251,D254,D801,Q801	DS-323	SILICON GREASE	DONGYANG SILICON	
3.0	EAY62811001	LGIT	MI				BRIDGE DIODE ASS'Y	HEAT SINK ASS'Y		
3.0	EAY62811001	LGIT	MI	1	EA	HS2	HS2 (30X25X5.5)	HEAT SINK	YUWON NRT	
3.0	EAY62811001	LGIT	MI	1	EA	HS2	HS2 (30X25X5.5)	HEAT SINK	HUAPENG	
3.0	EAY62811001	LGIT	MI	1	EA	HS2	HS2 (30X25X5.5)	HEAT SINK	GUOTAI	
3.0	EAY62811001	LGIT	MI	1	EA	BD101	GBJ1506 600V 15A L-FORMING	DIODE	LITEON	
3.0	EAY62811001	LGIT	MI	1	EA	BD101	D15SB60 600V 15A L-FORMING	DIODE	DACHANG	
3.0	EAY62811001	LGIT	MI	1	EA	FOR BD101	BHM Screw , M3.0 * 6.0L, w ith Clamfix, Cr3+WH Plating	SCREW	SEOUL METAL	
3.0	EAY62811001	LGIT	MI	1	EA	FOR BD101	BHM Screw , M3.0 * 6.0L, w ith Clamfix, Cr3+WH Plating	SCREW	ASEA BOLT	
3.0	EAY62811001	LGIT	MI	1	EA	FOR BD101	BHM Screw , M3.0 * 6.0L, w ith Clamfix, Cr3+WH Plating	SCREW	SUNG HO METAL	
3.0	EAY62811001	LGIT	MI	0.06	GR	FOR BD101	HC300	SILICON GREASE	CHANG AMLS	
3.0	EAY62811001	LGIT	MI	0.06	GR	FOR BD101	DS-323	SILICON GREASE	DONGYANG SILICON	
3.0	EAY62811001	LGIT	MI				LGP55-13LPB MI COMPONENTS	MI ASS'Y		
3.0	EAY62811001	LGIT	MI	1	EA	C610	KMF 100uF 450V M RU P7.5 Φ18x35.5	CAPACITOR, ALUMINUM	SAMYOUNG	
3.0	EAY62811001	LGIT	MI	1	EA	C610	SK 100uF 450V M RU P7.5 Φ18X35.5	CAPACITOR, ALUMINUM	SUSCON	
3.0	EAY62811001	LGIT	MI	1	EA	C251	NXB 100uF 100V M RB P5 Φ12.5x20	CAPACITOR, ALUMINUM	SAMYOUNG	
3.0	EAY62811001	LGIT	MI	1	EA	C251	MF 100uF 100V M RB P5 Φ13x21	CAPACITOR, ALUMINUM	SUSCON	
3.0	EAY62811001	LGIT	MI	2	EA	C815,C820	NXB 150uF 100V M RB P5 Φ12.5x25	CAPACITOR, ALUMINUM	SAMYOUNG	
3.0	EAY62811001	LGIT	MI	2	EA	C815,C820	MF 150uF 100V M RB P5 Φ13x25	CAPACITOR, ALUMINUM	SUSCON	
3.0	EAY62811001	LGIT	MI	1	EA	C601	MP 0.82uF 500V J P15	CAPACITOR,FILM	LUMEN	
3.0	EAY62811001	LGIT	MI	1	EA	C601	PCMP 372 0.82uF 500V J P15	CAPACITOR,FILM	PILKOR	
3.0	EAY62811001	LGIT	MI	1	EA	C601	MPHB 0.82uF 500V J P15	CAPACITOR,FILM	EUROPTRONIC	
3.0	EAY62811001	LGIT	MI	1	EA	C114	NP 0.027uF 800V J P15	CAPACITOR,FILM	LUMEN	
3.0	EAY62811001	LGIT	MI	1	EA	C114	PCMP 384 0.027uF 800V J P15	CAPACITOR,FILM	PILKOR	
3.0	EAY62811001	LGIT	MI	1	EA	C114	MPLB 0.027uF 1000V J P15	CAPACITOR,FILM	EUROPTRONIC	
3.0	EAY62811001	LGIT	MI	1	EA	C816	PCMT369 0.22uF 250V K P10	CAPACITOR, FILM	PILKOR	
3.0	EAY62811001	LGIT	MI	1	EA	C816	MT 0.22uF 250V K P10	CAPACITOR, FILM	LUMEN	
3.0	EAY62811001	LGIT	MI	2	EA	CX101,CX102	PCX2 337 0.33uF 275V P15	CAPACITOR, X-CAP	PILKOR	
3.0	EAY62811001	LGIT	MI	2	EA	CX101,CX102	MPX 0.33uF 275V P15	CAPACITOR, X-CAP	EUROPTRONIC	
3.0	EAY62811001	LGIT	MI	2	EA	D253,D261	SB5100 100V 5A P20	DIODE	LITE-ON	
3.0	EAY62811001	LGIT	MI	2	EA	D253,D261	SB5100 100V 5A P20	DIODE	DACHANG	
3.0	EAY62811001	LGIT	MI	2	EA	D601,D602	S3V60 600V 3.5A P20	DIODE	SHINDENGEN	
3.0	EAY62811001	LGIT	MI	2	EA	D601,D602	30PDA60 600V 3A P20	DIODE	NI	
3.0	EAY62811001	LGIT	MI	1	EA	D603	STTH10LCD06 600V 10A TO-220FP	DIODE	STM	
3.0	EAY62811001	LGIT	MI	1	EA	D603	BYV29FX-600 600V 9A TO-220FP	DIODE	NXP	
3.0	EAY62811001	LGIT	MI	1	EA	F100	T6.3A H 250V 215 BROWN(1-LINE)	FUSE, TIME LAG	LITTELFUSE	
3.0	EAY62811001	LGIT	MI	1	EA	F100	T6.3A H 250V 50CT BROWN(1-LINE)	FUSE, TIME LAG	Dainfuse	
3.0	EAY62811001	LGIT	MI	1	EA	F101	F3.15A H 250V 216 VIOLET(2-LINE)	FUSE, FAST ACTING	LITTELFUSE	
3.0	EAY62811001	LGIT	MI	1	EA	F101	F3.15A H 250V 50CF VIOLET(2-LINE)	FUSE, FAST ACTING	Dainfuse	
3.0	EAY62811001	LGIT	MI	1	EA	HD601	EC45CAP-A0-12	MAIN CAP HOLDER	TBI	
3.0	EAY62811001	LGIT	MI	1	EA	HD601	EC45CAP-A0-12	MAIN CAP HOLDER	LEZHI	
3.0	EAY62811001	LGIT	MI	3	EA	IC102,IC502,IC503	EL817MB(DT)	IC, PHOTO COUPLER	EVERLIGHT	
3.0	EAY62811001	LGIT	MI	3	EA	IC102,IC502,IC503	LTV817M-BN	IC, PHOTO COUPLER	LITEON	
3.0	EAY62811001	LGIT	MI	1	EA	L601	12S-LP02 220uH PQ3513	PFC CHOKE	FEELUX	
3.0	EAY62811001	LGIT	MI	1	EA	L601	12S-LP02 220uH PQ3513	PFC CHOKE	SOOJUNG	
3.0	EAY62811001	LGIT	MI	1	EA	L601	12S-LP02 220uH PQ3513	PFC CHOKE	LGIT	
3.0	EAY62811001	LGIT	MI	1	EA	L601	12S-LP02 220uH PQ3513	PFC CHOKE	TDK	
3.0	EAY62811001	LGIT	MI	1	EA	L801	13S-DD02 30uH EE1616	DCDC CHOKE	FEELUX	2013Y
3.0	EAY62811001	LGIT	MI	1	EA	L801	13S-DD02 30uH EE1616	DCDC CHOKE	SOOJUNG	2013Y
3.0	EAY62811001	LGIT	MI	1	EA	LF101	LLF-130 (20.5mH)	LINE FILTER	FEELUX	2013Y
3.0	EAY62811001	LGIT	MI	1	EA	LF101	CS615200SHA (20.5mH)	LINE FILTER	TNC	2013Y
3.0	EAY62811001	LGIT	MI	1	EA	LF101	LT6015205(20.5mH)	LINE FILTER	DONG IL TECH	2013Y
3.0	EAY62811001	LGIT	MI	1	EA	LF101	LLF-130 (20.5mH)	LINE FILTER	SOOJUNG	2013Y
3.0	EAY62811001	LGIT	MI	1	EA	LF102	LLF-123 20mH	LINE FILTER	FEELUX	2013Y
3.0	EAY62811001	LGIT	MI	1	EA	LF102	CS915200SBA 20mH	LINE FILTER	TNC	2013Y
3.0	EAY62811001	LGIT	MI	1	EA	LF102	LH9B019200 20mH	LINE FILTER	DONG IL TECH	2013Y
3.0	EAY62811001	LGIT	MI	1	EA	LF102	LLF-123 20mH	LINE FILTER	SOOJUNG	2013Y
3.0	EAY62811001	LGIT	MI	1	EA	T101	13S-LM08 440uH SRV4214	TRANSFORMER	FEELUX	2013Y
3.0	EAY62811001	LGIT	MI	1	EA	T101	13S-LM08 440uH SRV4214	TRANSFORMER	SOOJUNG	2013Y
3.0	EAY62811001	LGIT	MI	1	EA	T101	13S-LM08 440uH SRV4214	TRANSFORMER	LGIT	2013Y
3.0	EAY62811001	LGIT	MI	1	EA	T101	13S-LM08 440uH SRV4214	TRANSFORMER	TDK	2013Y
3.0	EAY62811001	LGIT	MI	1	EA	T501	12S-LS01 1.1mH EE1918	TRANSFORMER	FEELUX	
3.0	EAY62811001	LGIT	MI	1	EA	T501	12S-LS01 1.1mH EE1918	TRANSFORMER	SOOJUNG	
3.0	EAY62811001	LGIT	MI	1	EA	T501	12S-LS01 1.1mH EE1918	TRANSFORMER	CLOVER HITECH	
3.0	EAY62811001	LGIT	MI	1	EA	T501	12S-LS01 1.1mH EE1918	TRANSFORMER	TDK	
3.0	EAY62811001	LGIT	MI	1	EA	IC501	ICE3BR4765JZ DIP-8	IC	INFINEON	
3.0	EAY62811001	LGIT	MI	1	EA	TH101	ICL-5W 5R00MSMT	RESISTOR, NTC	SMART	
3.0	EAY62811001	LGIT	MI	1	EA	VA101	INR14D621K-CAP 620V Φ14 TUBE	VARISTOR	AMOTECH	
3.0	EAY62811001	LGIT	MI	1	EA	VA101	SVC621D-14ATM7 620V Φ14 TUBE	VARISTOR	SAMWHA	
3.0	EAY62811001	LGIT	MI	1	EA	P201	SMAW200-H24S2 24PIN WHITE	WAFER	YEONHO	
3.0	EAY62811001	LGIT	MI	1	EA	P702	20010WR-06A03 6PIN WHITE	WAFER	YEONHO	

3.0	EAY62811001	LGIT	MI	1	EA	P801	IS100-L08T-C46 8PIN BLACK	WAFER	UJU ELE	
3.0	EAY62811001	LGIT	MI	1	EA	P802	IS100-L08T-C46-A 8PIN WHITE	WAFER	UJU ELE	
3.0	EAY62811001	LGIT	MI	1	EA	SK100	DAC-18C3M1 BLACK	AC SOCKET	DONGIL TECH	2013Y
3.0	EAY62811001	LGIT	MI	1	EA	SK100	DAC-18C3M1C (w ith cover) BLACK	AC SOCKET	DONGIL TECH	2013Y
3.0	EAY62811001	LGIT	MI	1	EA	PG101	Rug Ground SPCC 0.4t Cusn Plating	GND REINFORCE	LEZHI	
3.0	EAY62811001	LGIT	SMT				LGP55-13LPB SMD COMPONENT	SMT ASS'Y		
3.0	EAY62811001	LGIT	SMT	2	EA	C704,C814	0.01uF 50V K 1608 X7R	CAPACITOR, CHIP	MURATA	
3.0	EAY62811001	LGIT	SMT	2	EA	C704,C814	0.01uF 50V K 1608 X7R	CAPACITOR, CHIP	SAMWHA	
3.0	EAY62811001	LGIT	SMT	2	EA	C704,C814	0.01uF 50V K 1608 X7R	CAPACITOR, CHIP	TDK	
3.0	EAY62811001	LGIT	SMT	2	EA	C704,C814	0.01uF 50V K 1608 X7R	CAPACITOR, CHIP	YAGEO	
3.0	EAY62811001	LGIT	SMT	1	EA	C810	220pF 50V J 1608 COG	CAPACITOR, CHIP	MURATA	
3.0	EAY62811001	LGIT	SMT	1	EA	C810	220pF 50V J 1608 COG	CAPACITOR, CHIP	SAMWHA	
3.0	EAY62811001	LGIT	SMT	1	EA	C810	220pF 50V J 1608 COG	CAPACITOR, CHIP	TDK	
3.0	EAY62811001	LGIT	SMT	1	EA	C810	220pF 50V J 1608 COG	CAPACITOR, CHIP	YAGEO	
3.0	EAY62811001	LGIT	SMT	2	EA	C111,C605	0.022uF 50V K 1608 X7R	CAPACITOR, CHIP	MURATA	
3.0	EAY62811001	LGIT	SMT	2	EA	C111,C605	0.022uF 50V K 1608 X7R	CAPACITOR, CHIP	SAMWHA	
3.0	EAY62811001	LGIT	SMT	2	EA	C111,C605	0.022uF 50V K 1608 X7R	CAPACITOR, CHIP	TDK	
3.0	EAY62811001	LGIT	SMT	2	EA	C111,C605	0.022uF 50V K 1608 X7R	CAPACITOR, CHIP	YAGEO	
3.0	EAY62811001	LGIT	SMT	2	EA	C274,C606	0.047uF 50V K 1608 X7R	CAPACITOR, CHIP	MURATA	
3.0	EAY62811001	LGIT	SMT	2	EA	C274,C606	0.047uF 50V K 1608 X7R	CAPACITOR, CHIP	SAMWHA	
3.0	EAY62811001	LGIT	SMT	2	EA	C274,C606	0.047uF 50V K 1608 X7R	CAPACITOR, CHIP	TDK	
3.0	EAY62811001	LGIT	SMT	2	EA	C274,C606	0.047uF 50V K 1608 X7R	CAPACITOR, CHIP	YAGEO	
3.0	EAY62811001	LGIT	SMT	15	EA	C103,C106,C110,C205,C501, C502,C507,C509,C604,C705, C717,C719,C805,C806,C807	0.1uF 50V K 1608 X7R	CAPACITOR, CHIP	MURATA	
3.0	EAY62811001	LGIT	SMT	15	EA	C103,C106,C110,C205,C501, C502,C507,C509,C604,C705, C717,C719,C805,C806,C807	0.1uF 50V K 1608 X7R	CAPACITOR, CHIP	SAMWHA	
3.0	EAY62811001	LGIT	SMT	15	EA	C103,C106,C110,C205,C501, C502,C507,C509,C604,C705, C717,C719,C805,C806,C807	0.1uF 50V K 1608 X7R	CAPACITOR, CHIP	TDK	
3.0	EAY62811001	LGIT	SMT	15	EA	C103,C106,C110,C205,C501, C502,C507,C509,C604,C705, C717,C719,C805,C806,C807	0.1uF 50V K 1608 X7R	CAPACITOR, CHIP	YAGEO	
3.0	EAY62811001	LGIT	SMT	1	EA	C707	0.22uF 16V K 1608 X7R /0.22uF 25V K 1608 X7R	CAPACITOR, CHIP	MURATA	
3.0	EAY62811001	LGIT	SMT	1	EA	C707	0.22uF 16V K 1608 X7R /0.22uF 25V K 1608 X7R	CAPACITOR, CHIP	SAMWHA	
3.0	EAY62811001	LGIT	SMT	1	EA	C707	0.22uF 16V K 1608 X7R /0.22uF 25V K 1608 X7R	CAPACITOR, CHIP	TDK	
3.0	EAY62811001	LGIT	SMT	1	EA	C707	0.22uF 16V K 1608 X7R /0.22uF 25V K 1608 X7R	CAPACITOR, CHIP	YAGEO	
3.0	EAY62811001	LGIT	SMT	1	EA	C101	0.33uF 16V K 1608 X7R /0.33uF 25V K 1608 X7R	CAPACITOR, CHIP	MURATA	
3.0	EAY62811001	LGIT	SMT	1	EA	C101	0.33uF 16V K 1608 X7R /0.33uF 25V K 1608 X7R	CAPACITOR, CHIP	SAMWHA	
3.0	EAY62811001	LGIT	SMT	1	EA	C101	0.33uF 16V K 1608 X7R /0.33uF 25V K 1608 X7R	CAPACITOR, CHIP	TDK	
3.0	EAY62811001	LGIT	SMT	1	EA	C101	0.33uF 16V K 1608 X7R /0.33uF 25V K 1608 X7R	CAPACITOR, CHIP	YAGEO	
3.0	EAY62811001	LGIT	SMT	6	EA	C506,C513,C706,C204,C275, C280	0.47uF 16V K 1608 X7R /0.47uF 25V K 1608 X7R	CAPACITOR, CHIP	MURATA	
3.0	EAY62811001	LGIT	SMT	6	EA	C506,C513,C706,C204,C275, C280	0.47uF 16V K 1608 X7R /0.47uF 25V K 1608 X7R	CAPACITOR, CHIP	SAMWHA	
3.0	EAY62811001	LGIT	SMT	6	EA	C506,C513,C706,C204,C275, C280	0.47uF 16V K 1608 X7R /0.47uF 25V K 1608 X7R	CAPACITOR, CHIP	TDK	
3.0	EAY62811001	LGIT	SMT	6	EA	C506,C513,C706,C204,C275, C280	0.47uF 16V K 1608 X7R /0.47uF 25V K 1608 X7R	CAPACITOR, CHIP	YAGEO	
3.0	EAY62811001	LGIT	SMT	1	EA	C108	0.47uF 25V K 2012 X7R	CAPACITOR, CHIP	MURATA	
3.0	EAY62811001	LGIT	SMT	1	EA	C108	0.47uF 25V K 2012 X7R	CAPACITOR, CHIP	SAMWHA	
3.0	EAY62811001	LGIT	SMT	1	EA	C108	0.47uF 25V K 2012 X7R	CAPACITOR, CHIP	TDK	
3.0	EAY62811001	LGIT	SMT	1	EA	C108	0.47uF 25V K 2012 X7R	CAPACITOR, CHIP	YAGEO	
3.0	EAY62811001	LGIT	SMT	7	EA	C107,C116,C203,C504,C607, C608,C817	1000pF 50V K 1608 X7R	CAPACITOR, CHIP	MURATA	
3.0	EAY62811001	LGIT	SMT	7	EA	C107,C116,C203,C504,C607, C608,C817	1000pF 50V K 1608 X7R	CAPACITOR, CHIP	SAMWHA	
3.0	EAY62811001	LGIT	SMT	7	EA	C107,C116,C203,C504,C607, C608,C817	1000pF 50V K 1608 X7R	CAPACITOR, CHIP	TDK	
3.0	EAY62811001	LGIT	SMT	7	EA	C107,C116,C203,C504,C607, C608,C817	1000pF 50V K 1608 X7R	CAPACITOR, CHIP	YAGEO	
3.0	EAY62811001	LGIT	SMT	3	EA	C808,C818,C819	2200pF 50V J 1608 X7R	CAPACITOR, CHIP	MURATA	
3.0	EAY62811001	LGIT	SMT	3	EA	C808,C818,C819	2200pF 50V J 1608 X7R	CAPACITOR, CHIP	SAMWHA	
3.0	EAY62811001	LGIT	SMT	3	EA	C808,C818,C819	2200pF 50V J 1608 X7R	CAPACITOR, CHIP	TDK	
3.0	EAY62811001	LGIT	SMT	3	EA	C808,C818,C819	2200pF 50V J 1608 X7R	CAPACITOR, CHIP	YAGEO	
3.0	EAY62811001	LGIT	SMT	1	EA	C809	100pF 50V J 1608 COG	CAPACITOR, CHIP	MURATA	
3.0	EAY62811001	LGIT	SMT	1	EA	C809	100pF 50V J 1608 COG	CAPACITOR, CHIP	SAMWHA	
3.0	EAY62811001	LGIT	SMT	1	EA	C809	100pF 50V J 1608 COG	CAPACITOR, CHIP	TDK	
3.0	EAY62811001	LGIT	SMT	1	EA	C809	100pF 50V J 1608 COG	CAPACITOR, CHIP	YAGEO	
3.0	EAY62811001	LGIT	SMT	1	EA	C104	680pF 50V J 1608 COG	CAPACITOR, CHIP	MURATA	
3.0	EAY62811001	LGIT	SMT	1	EA	C104	680pF 50V J 1608 COG	CAPACITOR, CHIP	SAMWHA	
3.0	EAY62811001	LGIT	SMT	1	EA	C104	680pF 50V J 1608 COG	CAPACITOR, CHIP	TDK	
3.0	EAY62811001	LGIT	SMT	1	EA	C104	680pF 50V J 1608 COG	CAPACITOR, CHIP	YAGEO	
3.0	EAY62811001	LGIT	SMT	1	EA	ZD601	BZT52C6V8S 6.8V SOD-323	DIODE, ZENER	DIODES	
3.0	EAY62811001	LGIT	SMT	1	EA	ZD601	MMSZ5235BS 6.8V SOD-323	DIODE, ZENER	RECTRON	
3.0	EAY62811001	LGIT	SMT	1	EA	ZD601	MM3Z6V8ST1G 6.8V SOD-323	DIODE, ZENER	ONSEMI	
3.0	EAY62811001	LGIT	SMT	1	EA	ZD601	KDZ6.8V 6.8V SOD-323	DIODE, ZENER	KEC	
3.0	EAY62811001	LGIT	SMT	1	EA	ZD602	BZT52C3V6 3.6V SOD-123	DIODE, ZENER	DIODES	2013Y
3.0	EAY62811001	LGIT	SMT	1	EA	ZD602	SDZ3V6G 3.6V SOD-123	DIODE, ZENER	AUK	2013Y
3.0	EAY62811001	LGIT	SMT	1	EA	ZD602	MMSZ5227B 3.6V SOD-123	DIODE, ZENER	RECTRON	2013Y
3.0	EAY62811001	LGIT	SMT	6	EA	D103,D121,D504,D604,D605, D802	1N4148W 100V 150mA SOD-123	DIODE	RECTRON	
3.0	EAY62811001	LGIT	SMT	6	EA	D103,D121,D504,D604,D605, D802	1N4148W 100V 150mA SOD-123	DIODE	DIODES	
3.0	EAY62811001	LGIT	SMT	6	EA	D103,D121,D504,D604,D605, D802	MMSD4148T1 100V 200mA SOD-123	DIODE	ONSEMI	
3.0	EAY62811001	LGIT	SMT	6	EA	D103,D121,D504,D604,D605, D802	SDS4148G 100V 150mA SOD-123	DIODE	AUK	

3.0	EAY62811001	LGIT	SMT	2	EA	D201,D202	MBRD10100CT 100V 10A D-PAK	DIODE	SMC	
3.0	EAY62811001	LGIT	SMT	2	EA	D201,D202	MBRD10U100CT 100V 10A D-PAK	DIODE	KEC	
3.0	EAY62811001	LGIT	SMT	2	EA	D201,D202	SPEN-210A 100V 10A D-PAK	DIODE	SANKEN	
3.0	EAY62811001	LGIT	SMT	1	EA	Q501	BCW66GLT SOT-23 NPN	FET	ONSEMI	
3.0	EAY62811001	LGIT	SMT	1	EA	Q501	KTC3551T 80V 1A TSM NPN	FET	KEC	
3.0	EAY62811001	LGIT	SMT	1	EA	Q501	2SC5865 SOT-23 NPN	FET	ROHM	
3.0	EAY62811001	LGIT	SMT	6	EA	Q802,Q803,Q804,Q805,Q806, Q807	FDT86106LZ 100V 3.2A SOT-223	FET	FAIRCHILD	
3.0	EAY62811001	LGIT	SMT	6	EA	Q802,Q803,Q804,Q805,Q806, Q807	PF610BL 100V 0.9A SOT-223	FET	NIKO-SEM	2013Y
3.0	EAY62811001	LGIT	SMT	6	EA	Q802,Q803,Q804,Q805,Q806, Q807	STN4NF20L 200V 1A SOT-223	FET	STM	
3.0	EAY62811001	LGIT	SMT	6	EA	Q802,Q803,Q804,Q805,Q806, Q807	MDHT4N20Y 200V 0.85A SOT-223	FET	MAGNACHIP	
3.0	EAY62811001	LGIT	SMT	2	EA	Q101,Q102	STD10NM60N 600V 10A D-PAK	FET	STM	
3.0	EAY62811001	LGIT	SMT	2	EA	Q101,Q102	FCD600N60Z 600V 7.4A D-PAK	FET	FAIRCHILD	2013Y
3.0	EAY62811001	LGIT	SMT	2	EA	Q101,Q102	TK8P60V 600V 8A D-PAK	FET	TOSHIBA	
3.0	EAY62811001	LGIT	SMT	2	EA	Q101,Q102	IPD60R600E6 600V 7.3A D-PAK	FET	INFINEON	
3.0	EAY62811001	LGIT	SMT	2	EA	Q601,Q602	STD13NM60N 600V 11A D-PAK	FET	STM	
3.0	EAY62811001	LGIT	SMT	1	EA	IC801	IW7011 QFP44	IC	IWATT	2013Y
3.0	EAY62811001	LGIT	SMT	1	EA	IC601	R2A20133D, SOIC-8	IC	RENESAS	2013Y
3.0	EAY62811001	LGIT	SMT	1	EA	IC701	R5F100BCAFP	IC	RENESAS	
3.0	EAY62811001	LGIT	SMT	1	EA	IC101	SSC9527S, SOIC-18	IC	SANKEN	2013Y
3.0	EAY62811001	LGIT	SMT	1	EA	IC202	SJ432BS 1.24V ±0.5% SOT-23	IC	AUK	
3.0	EAY62811001	LGIT	SMT	1	EA	IC202	TLV431BSN1T1G 1.24V±0.5% SOT-23	IC	ON SEMI	
3.0	EAY62811001	LGIT	SMT	1	EA	IC202	AZ431LANTR-E1 1.24V±0.5% SOT-23	IC	BCD	
3.0	EAY62811001	LGIT	SMT	1	EA	IC252	SNF431BS 2.5V ±0.5% SOT-23	IC	AUK	
3.0	EAY62811001	LGIT	SMT	1	EA	IC252	AS431ANTR-E1 2.5V ±0.5% SOT-23	IC	BCD	
3.0	EAY62811001	LGIT	SMT	1	EA	IC252	KIA431BM 2.5V ±0.5% SOT-23	IC	KEC	
3.0	EAY62811001	LGIT	SMT	1	EA	Q701	2N7002K 60V 300mA SOT-23	FET	DIODES	
3.0	EAY62811001	LGIT	SMT	1	EA	Q701	2N7002K 60V 380mA SOT-23	FET	ONSEMI	
3.0	EAY62811001	LGIT	SMT	1	EA	Q701	RK7002 60V 250mA SOT-23	FET	ROHM	
3.0	EAY62811001	LGIT	SMT	1	EA	Q701	SSM3K7002F 60V 200mA SOT-23	FET	TOSHIBA	
3.0	EAY62811001	LGIT	SMT	2	EA	Q201,Q502	MMBT2222A 40V 600mA SOT-23 NPN	TRANSISTOR	ONSEMI	
3.0	EAY62811001	LGIT	SMT	2	EA	Q201,Q502	KTN2222AS 40V 600mA SOT-23 NPN	TRANSISTOR	KEC	
3.0	EAY62811001	LGIT	SMT	2	EA	Q201,Q502	SBT2222A 40V 600mA SOT-23 NPN	TRANSISTOR	AUK	
3.0	EAY62811001	LGIT	SMT	2	EA	Q603,Q604	MMBT2907A -60V -600mA SOT-23 PNP	TRANSISTOR	ONSEMI	
3.0	EAY62811001	LGIT	SMT	2	EA	Q603,Q604	KTN2907AS -60V -600mA SOT-23 PNP	TRANSISTOR	KEC	
3.0	EAY62811001	LGIT	SMT	2	EA	Q603,Q604	SBT2907A -60V -600mA SOT-23 PNP	TRANSISTOR	AUK	
3.0	EAY62811001	LGIT	SMT	2	EA	R207,R841	0Ω J 1608	RESISTOR, CHIP	KAMAYA	
3.0	EAY62811001	LGIT	SMT	2	EA	R207,R841	0Ω J 1608	RESISTOR, CHIP	PILKOR	
3.0	EAY62811001	LGIT	SMT	2	EA	R207,R841	0Ω J 1608	RESISTOR, CHIP	YAGEO	
3.0	EAY62811001	LGIT	SMT	3	EA	J12,J32,J37	0Ω J 3216	RESISTOR, CHIP	KAMAYA	
3.0	EAY62811001	LGIT	SMT	3	EA	J12,J32,J37	0Ω J 3216	RESISTOR, CHIP	PILKOR	
3.0	EAY62811001	LGIT	SMT	3	EA	J12,J32,J37	0Ω J 3216	RESISTOR, CHIP	YAGEO	
3.0	EAY62811001	LGIT	SMT	2	EA	R293,R294	1.2KΩ F 1608	RESISTOR, CHIP	KAMAYA	
3.0	EAY62811001	LGIT	SMT	2	EA	R293,R294	1.2KΩ F 1608	RESISTOR, CHIP	PILKOR	
3.0	EAY62811001	LGIT	SMT	2	EA	R293,R294	1.2KΩ F 1608	RESISTOR, CHIP	YAGEO	
3.0	EAY62811001	LGIT	SMT	1	EA	R289	1.2KΩ J 1608	RESISTOR, CHIP	KAMAYA	
3.0	EAY62811001	LGIT	SMT	1	EA	R289	1.2KΩ J 1608	RESISTOR, CHIP	PILKOR	
3.0	EAY62811001	LGIT	SMT	1	EA	R289	1.2KΩ J 1608	RESISTOR, CHIP	YAGEO	
3.0	EAY62811001	LGIT	SMT	1	EA	R206	1.5KΩ F 1608	RESISTOR, CHIP	KAMAYA	
3.0	EAY62811001	LGIT	SMT	1	EA	R206	1.5KΩ F 1608	RESISTOR, CHIP	PILKOR	
3.0	EAY62811001	LGIT	SMT	1	EA	R206	1.5KΩ F 1608	RESISTOR, CHIP	YAGEO	
3.0	EAY62811001	LGIT	SMT	2	EA	R821,R824	620KΩ F 1608	RESISTOR, CHIP	KAMAYA	
3.0	EAY62811001	LGIT	SMT	2	EA	R821,R824	620KΩ F 1608	RESISTOR, CHIP	PILKOR	
3.0	EAY62811001	LGIT	SMT	2	EA	R821,R824	620KΩ F 1608	RESISTOR, CHIP	YAGEO	
3.0	EAY62811001	LGIT	SMT	1	EA	R509	100KΩ J 1608	RESISTOR, CHIP	KAMAYA	
3.0	EAY62811001	LGIT	SMT	1	EA	R509	100KΩ J 1608	RESISTOR, CHIP	PILKOR	
3.0	EAY62811001	LGIT	SMT	1	EA	R509	100KΩ J 1608	RESISTOR, CHIP	YAGEO	
3.0	EAY62811001	LGIT	SMT	1	EA	R840	300KΩ F 1608	RESISTOR, CHIP	KAMAYA	
3.0	EAY62811001	LGIT	SMT	1	EA	R840	300KΩ F 1608	RESISTOR, CHIP	PILKOR	
3.0	EAY62811001	LGIT	SMT	1	EA	R840	300KΩ F 1608	RESISTOR, CHIP	YAGEO	
3.0	EAY62811001	LGIT	SMT	2	EA	R112,R204	100Ω F 1608	RESISTOR, CHIP	KAMAYA	
3.0	EAY62811001	LGIT	SMT	2	EA	R112,R204	100Ω F 1608	RESISTOR, CHIP	PILKOR	
3.0	EAY62811001	LGIT	SMT	2	EA	R112,R204	100Ω F 1608	RESISTOR, CHIP	YAGEO	
3.0	EAY62811001	LGIT	SMT	4	EA	R605,R713,R735,R736	100Ω J 1608	RESISTOR, CHIP	KAMAYA	
3.0	EAY62811001	LGIT	SMT	4	EA	R605,R713,R735,R736	100Ω J 1608	RESISTOR, CHIP	PILKOR	
3.0	EAY62811001	LGIT	SMT	4	EA	R605,R713,R735,R736	100Ω J 1608	RESISTOR, CHIP	YAGEO	
3.0	EAY62811001	LGIT	SMT	3	EA	R111,R291,R292	10KΩ F 1608	RESISTOR, CHIP	KAMAYA	
3.0	EAY62811001	LGIT	SMT	3	EA	R111,R291,R292	10KΩ F 1608	RESISTOR, CHIP	PILKOR	
3.0	EAY62811001	LGIT	SMT	3	EA	R111,R291,R292	10KΩ F 1608	RESISTOR, CHIP	YAGEO	
3.0	EAY62811001	LGIT	SMT	17	EA	R120,R123,R211,R220,R507, R603,R606,R703,R712,R715, R817,R801,R803,R805,R807, R809,R811	10KΩ J 1608	RESISTOR, CHIP	KAMAYA	
3.0	EAY62811001	LGIT	SMT	17	EA	R120,R123,R211,R220,R507, R603,R606,R703,R712,R715, R817,R801,R803,R805,R807, R809,R811	10KΩ J 1608	RESISTOR, CHIP	PILKOR	
3.0	EAY62811001	LGIT	SMT	17	EA	R120,R123,R211,R220,R507, R603,R606,R703,R712,R715, R817,R801,R803,R805,R807, R809,R811	10KΩ J 1608	RESISTOR, CHIP	YAGEO	
3.0	EAY62811001	LGIT	SMT	1	EA	R815	10Ω J 1608	RESISTOR, CHIP	KAMAYA	
3.0	EAY62811001	LGIT	SMT	1	EA	R815	10Ω J 1608	RESISTOR, CHIP	PILKOR	
3.0	EAY62811001	LGIT	SMT	1	EA	R815	10Ω J 1608	RESISTOR, CHIP	YAGEO	
3.0	EAY62811001	LGIT	SMT	2	EA	R119,R122	10Ω J 3216	RESISTOR, CHIP	KAMAYA	
3.0	EAY62811001	LGIT	SMT	2	EA	R119,R122	10Ω J 3216	RESISTOR, CHIP	PILKOR	
3.0	EAY62811001	LGIT	SMT	2	EA	R119,R122	10Ω J 3216	RESISTOR, CHIP	YAGEO	
3.0	EAY62811001	LGIT	SMT	2	EA	R118,R121	120Ω J 3216	RESISTOR, CHIP	KAMAYA	
3.0	EAY62811001	LGIT	SMT	2	EA	R118,R121	120Ω J 3216	RESISTOR, CHIP	PILKOR	
3.0	EAY62811001	LGIT	SMT	2	EA	R118,R121	120Ω J 3216	RESISTOR, CHIP	YAGEO	

3.0	EAY62811001	LGIT	SMT	2	EA	R610,R611	18Ω J 3216	RESISTOR, CHIP	KAMAYA	
3.0	EAY62811001	LGIT	SMT	2	EA	R610,R611	18Ω J 3216	RESISTOR, CHIP	PILKOR	
3.0	EAY62811001	LGIT	SMT	2	EA	R610,R611	18Ω J 3216	RESISTOR, CHIP	YAGEO	
3.0	EAY62811001	LGIT	SMT	7	EA	R202,R504,R508,R701,R710, R711,R818	1KΩ J 1608	RESISTOR, CHIP	KAMAYA	
3.0	EAY62811001	LGIT	SMT	7	EA	R202,R504,R508,R701,R710, R711,R818	1KΩ J 1608	RESISTOR, CHIP	PILKOR	
3.0	EAY62811001	LGIT	SMT	7	EA	R202,R504,R508,R701,R710, R711,R818	1KΩ J 1608	RESISTOR, CHIP	YAGEO	
3.0	EAY62811001	LGIT	SMT	1	EA	R205	2.7KΩ F 1608	RESISTOR, CHIP	KAMAYA	
3.0	EAY62811001	LGIT	SMT	1	EA	R205	2.7KΩ F 1608	RESISTOR, CHIP	PILKOR	
3.0	EAY62811001	LGIT	SMT	1	EA	R205	2.7KΩ F 1608	RESISTOR, CHIP	YAGEO	
3.0	EAY62811001	LGIT	SMT	1	EA	R619	270KΩ F 1608	RESISTOR, CHIP	KAMAYA	
3.0	EAY62811001	LGIT	SMT	1	EA	R619	270KΩ F 1608	RESISTOR, CHIP	PILKOR	
3.0	EAY62811001	LGIT	SMT	1	EA	R619	270KΩ F 1608	RESISTOR, CHIP	YAGEO	
3.0	EAY62811001	LGIT	SMT	1	EA	R604	100KΩ J 1608	RESISTOR, CHIP	KAMAYA	
3.0	EAY62811001	LGIT	SMT	1	EA	R604	100KΩ J 1608	RESISTOR, CHIP	PILKOR	
3.0	EAY62811001	LGIT	SMT	1	EA	R604	100KΩ J 1608	RESISTOR, CHIP	YAGEO	
3.0	EAY62811001	LGIT	SMT	3	EA	R754,R755,R739	22KΩ J 1608	RESISTOR, CHIP	KAMAYA	
3.0	EAY62811001	LGIT	SMT	3	EA	R754,R755,R739	22KΩ J 1608	RESISTOR, CHIP	PILKOR	
3.0	EAY62811001	LGIT	SMT	3	EA	R754,R755,R739	22KΩ J 1608	RESISTOR, CHIP	YAGEO	
3.0	EAY62811001	LGIT	SMT	2	EA	R702,R704	22Ω J 1608	RESISTOR, CHIP	KAMAYA	
3.0	EAY62811001	LGIT	SMT	2	EA	R702,R704	22Ω J 1608	RESISTOR, CHIP	PILKOR	
3.0	EAY62811001	LGIT	SMT	2	EA	R702,R704	22Ω J 1608	RESISTOR, CHIP	YAGEO	
3.0	EAY62811001	LGIT	SMT	1	EA	R116	240KΩ F 1608	RESISTOR, CHIP	KAMAYA	
3.0	EAY62811001	LGIT	SMT	1	EA	R116	240KΩ F 1608	RESISTOR, CHIP	PILKOR	
3.0	EAY62811001	LGIT	SMT	1	EA	R116	240KΩ F 1608	RESISTOR, CHIP	YAGEO	
3.0	EAY62811001	LGIT	SMT	2	EA	R618,R255	24KΩ F 1608	RESISTOR, CHIP	KAMAYA	
3.0	EAY62811001	LGIT	SMT	2	EA	R618,R255	24KΩ F 1608	RESISTOR, CHIP	PILKOR	
3.0	EAY62811001	LGIT	SMT	2	EA	R618,R255	24KΩ F 1608	RESISTOR, CHIP	YAGEO	
3.0	EAY62811001	LGIT	SMT	3	EA	R210,R608,R609	270Ω J 1608	RESISTOR, CHIP	KAMAYA	
3.0	EAY62811001	LGIT	SMT	3	EA	R210,R608,R609	270Ω J 1608	RESISTOR, CHIP	PILKOR	
3.0	EAY62811001	LGIT	SMT	3	EA	R210,R608,R609	270Ω J 1608	RESISTOR, CHIP	YAGEO	
3.0	EAY62811001	LGIT	SMT	3	EA	R256,R257,R258	27KΩ F 1608	RESISTOR, CHIP	KAMAYA	
3.0	EAY62811001	LGIT	SMT	3	EA	R256,R257,R258	27KΩ F 1608	RESISTOR, CHIP	PILKOR	
3.0	EAY62811001	LGIT	SMT	3	EA	R256,R257,R258	27KΩ F 1608	RESISTOR, CHIP	YAGEO	
3.0	EAY62811001	LGIT	SMT	6	EA	R831,R832,R833,R834,R835, R842	2.2Ω F 2012	RESISTOR, CHIP	KAMAYA	
3.0	EAY62811001	LGIT	SMT	6	EA	R831,R832,R833,R834,R835, R842	2.2Ω F 2012	RESISTOR, CHIP	PILKOR	
3.0	EAY62811001	LGIT	SMT	6	EA	R831,R832,R833,R834,R835, R842	2.2Ω F 2012	RESISTOR, CHIP	YAGEO	
3.0	EAY62811001	LGIT	SMT	1	EA	R114	3.9KΩ F 1608	RESISTOR, CHIP	KAMAYA	
3.0	EAY62811001	LGIT	SMT	1	EA	R114	3.9KΩ F 1608	RESISTOR, CHIP	PILKOR	
3.0	EAY62811001	LGIT	SMT	1	EA	R114	3.9KΩ F 1608	RESISTOR, CHIP	YAGEO	
3.0	EAY62811001	LGIT	SMT	1	EA	R617	30KΩ F 1608	RESISTOR, CHIP	KAMAYA	
3.0	EAY62811001	LGIT	SMT	1	EA	R617	30KΩ F 1608	RESISTOR, CHIP	PILKOR	
3.0	EAY62811001	LGIT	SMT	1	EA	R617	30KΩ F 1608	RESISTOR, CHIP	YAGEO	
3.0	EAY62811001	LGIT	SMT	3	EA	R115,R705,R737	330Ω J 1608	RESISTOR, CHIP	KAMAYA	
3.0	EAY62811001	LGIT	SMT	3	EA	R115,R705,R737	330Ω J 1608	RESISTOR, CHIP	PILKOR	
3.0	EAY62811001	LGIT	SMT	3	EA	R115,R705,R737	330Ω J 1608	RESISTOR, CHIP	YAGEO	
3.0	EAY62811001	LGIT	SMT	1	EA	R102	33Ω J 1608	RESISTOR, CHIP	KAMAYA	
3.0	EAY62811001	LGIT	SMT	1	EA	R102	33Ω J 1608	RESISTOR, CHIP	PILKOR	
3.0	EAY62811001	LGIT	SMT	1	EA	R102	33Ω J 1608	RESISTOR, CHIP	YAGEO	
3.0	EAY62811001	LGIT	SMT	5	EA	R288,R733,R734,R745,R746	4.7KΩ J 1608	RESISTOR, CHIP	KAMAYA	
3.0	EAY62811001	LGIT	SMT	5	EA	R288,R733,R734,R745,R746	4.7KΩ J 1608	RESISTOR, CHIP	PILKOR	
3.0	EAY62811001	LGIT	SMT	5	EA	R288,R733,R734,R745,R746	4.7KΩ J 1608	RESISTOR, CHIP	YAGEO	
3.0	EAY62811001	LGIT	SMT	4	EA	R819,R820,R822,R823	560KΩ F 1608	RESISTOR, CHIP	KAMAYA	
3.0	EAY62811001	LGIT	SMT	4	EA	R819,R820,R822,R823	560KΩ F 1608	RESISTOR, CHIP	PILKOR	
3.0	EAY62811001	LGIT	SMT	4	EA	R819,R820,R822,R823	560KΩ F 1608	RESISTOR, CHIP	YAGEO	
3.0	EAY62811001	LGIT	SMT	1	EA	R816	4.7Ω J 1608	RESISTOR, CHIP	KAMAYA	
3.0	EAY62811001	LGIT	SMT	1	EA	R816	4.7Ω J 1608	RESISTOR, CHIP	PILKOR	
3.0	EAY62811001	LGIT	SMT	1	EA	R816	4.7Ω J 1608	RESISTOR, CHIP	YAGEO	
3.0	EAY62811001	LGIT	SMT	2	EA	R825,R826	6.2KΩ F 1608	RESISTOR, CHIP	KAMAYA	
3.0	EAY62811001	LGIT	SMT	2	EA	R825,R826	6.2KΩ F 1608	RESISTOR, CHIP	PILKOR	
3.0	EAY62811001	LGIT	SMT	2	EA	R825,R826	6.2KΩ F 1608	RESISTOR, CHIP	YAGEO	
3.0	EAY62811001	LGIT	SMT	2	EA	R837,R844	6.2KΩ J 1608	RESISTOR, CHIP	KAMAYA	
3.0	EAY62811001	LGIT	SMT	2	EA	R837,R844	6.2KΩ J 1608	RESISTOR, CHIP	PILKOR	
3.0	EAY62811001	LGIT	SMT	2	EA	R837,R844	6.2KΩ J 1608	RESISTOR, CHIP	YAGEO	
3.0	EAY62811001	LGIT	SMT	10	EA	R714,R722,R723,R724,R802, R804,R806,R808,R810,R812	470KΩ J 1608	RESISTOR, CHIP	KAMAYA	
3.0	EAY62811001	LGIT	SMT	10	EA	R714,R722,R723,R724,R802, R804,R806,R808,R810,R812	470KΩ J 1608	RESISTOR, CHIP	PILKOR	
3.0	EAY62811001	LGIT	SMT	10	EA	R714,R722,R723,R724,R802, R804,R806,R808,R810,R812	470KΩ J 1608	RESISTOR, CHIP	YAGEO	
3.0	EAY62811001	LGIT	SMT	5	EA	R108,R201,R208,R209,R227	470Ω J 1608	RESISTOR, CHIP	KAMAYA	
3.0	EAY62811001	LGIT	SMT	5	EA	R108,R201,R208,R209,R227	470Ω J 1608	RESISTOR, CHIP	PILKOR	
3.0	EAY62811001	LGIT	SMT	5	EA	R108,R201,R208,R209,R227	470Ω J 1608	RESISTOR, CHIP	YAGEO	
3.0	EAY62811001	LGIT	SMT	12	EA	R128,R290,R706,R707,R708, R709,R717,R747,R748,R749, R750,R751	47KΩ J 1608	RESISTOR, CHIP	KAMAYA	
3.0	EAY62811001	LGIT	SMT	12	EA	R128,R290,R706,R707,R708, R709,R717,R747,R748,R749, R750,R751	47KΩ J 1608	RESISTOR, CHIP	PILKOR	
3.0	EAY62811001	LGIT	SMT	12	EA	R128,R290,R706,R707,R708, R709,R717,R747,R748,R749, R750,R751	47KΩ J 1608	RESISTOR, CHIP	YAGEO	
3.0	EAY62811001	LGIT	SMT	1	EA	R113	680Ω J 1608	RESISTOR, CHIP	KAMAYA	
3.0	EAY62811001	LGIT	SMT	1	EA	R113	680Ω J 1608	RESISTOR, CHIP	PILKOR	
3.0	EAY62811001	LGIT	SMT	1	EA	R113	680Ω J 1608	RESISTOR, CHIP	YAGEO	

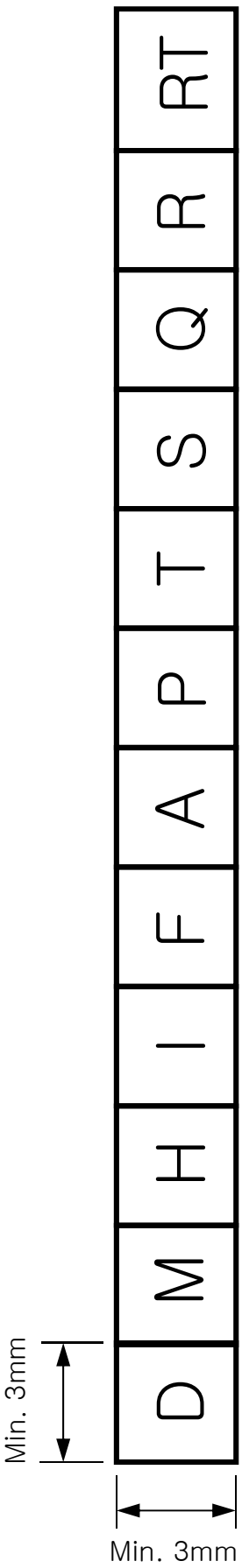
3.0	EAY62811001	LGIT	SMT	10	EA	R103,R104,R105,R106,R127, R613,R614,R615,R616,R623	750KΩ F 3216	RESISTOR, CHIP	KAMAYA	
3.0	EAY62811001	LGIT	SMT	10	EA	R103,R104,R105,R106,R127, R613,R614,R615,R616,R623	750KΩ F 3216	RESISTOR, CHIP	PILKOR	
3.0	EAY62811001	LGIT	SMT	10	EA	R103,R104,R105,R106,R127, R613,R614,R615,R616,R623	750KΩ F 3216	RESISTOR, CHIP	YAGEO	
3.0	EAY62811001	LGIT	SMT	6	EA	R506,R729,R730,R741,R743, R757	75KΩ J 1608	RESISTOR, CHIP	KAMAYA	
3.0	EAY62811001	LGIT	SMT	6	EA	R506,R729,R730,R741,R743, R757	75KΩ J 1608	RESISTOR, CHIP	PILKOR	
3.0	EAY62811001	LGIT	SMT	6	EA	R506,R729,R730,R741,R743, R757	75KΩ J 1608	RESISTOR, CHIP	YAGEO	
3.0	EAY62811001	LGIT	SMT	2	EA	R828,R843	51KΩ J 1608	RESISTOR, CHIP	KAMAYA	
3.0	EAY62811001	LGIT	SMT	2	EA	R828,R843	51KΩ J 1608	RESISTOR, CHIP	PILKOR	
3.0	EAY62811001	LGIT	SMT	2	EA	R828,R843	51KΩ J 1608	RESISTOR, CHIP	YAGEO	
3.0	EAY62811001	LGIT	SMT	0.5	GR		HT-130A-106	BOND	HITECH KOREA	
3.0	EAY62811001	LGIT	SMT	0.5	GR		HT-130D-7	BOND	HITECH KOREA	
3.0	EAY62811001	LGIT	SMT	0.5	GR		TB-2217H	BOND	Three Bond	
3.0	EAY62811001	LGIT	AI				LGP55-13LPB AI COMPONENTS	AI ASS'Y		
3.0	EAY62811001	LGIT	AI	5	EA	CY101,CY102,CY103, CY104,CY110	CT81 470pF 250V K P10 ,Y1	CAPACITOR, CERAMIC	YINANDON	
3.0	EAY62811001	LGIT	AI	5	EA	CY101,CY102,CY103, CY104,CY110	SD 470pF 250V K P10 ,Y1	CAPACITOR, CERAMIC	SAMWHA	
3.0	EAY62811001	LGIT	AI	1	EA	C118	CT81 100pF 1KV K P5 125℃	CAPACITOR, CERAMIC	YINANDON	
3.0	EAY62811001	LGIT	AI	1	EA	C118	EK R 3A 100pF 1KV K P5 125 ℃	CAPACITOR, CERAMIC	SAMWHA	
3.0	EAY62811001	LGIT	AI	2	EA	C113,C614	CT81 220pF 1KV K P5 125℃	CAPACITOR, CERAMIC	YINANDON	
3.0	EAY62811001	LGIT	AI	2	EA	C113,C614	EK R 3A 220pF 1KV K P5 125 ℃	CAPACITOR, CERAMIC	SAMWHA	
3.0	EAY62811001	LGIT	AI	2	EA	C503,C510	CT81 1000pF 1KV K P5 125℃	CAPACITOR, CERAMIC	YINANDON	
3.0	EAY62811001	LGIT	AI	2	EA	C503,C510	EK R 3A 1000pF 1KV K P5 125 ℃	CAPACITOR, CERAMIC	SAMWHA	
3.0	EAY62811001	LGIT	AI	2	EA	C201,C206	NXH 1000uF 10V M P5 Φ10X12.5	CAPACITOR, ALUMINUM	SAMYOUNG	
3.0	EAY62811001	LGIT	AI	2	EA	C201,C206	MG 1000uF 10V M P5 Φ10X13	CAPACITOR, ALUMINUM	SUSCON	
3.0	EAY62811001	LGIT	AI	1	EA	C202	NXB 470uF 10V M P5 Φ8X11.5	CAPACITOR, ALUMINUM	SAMYOUNG	
3.0	EAY62811001	LGIT	AI	1	EA	C202	SG 470uF 10V M P5 Φ8X12	CAPACITOR, ALUMINUM	SUSCON	
3.0	EAY62811001	LGIT	AI	1	EA	C270	NXH 330uF 35V M P5 Φ10X12.5	CAPACITOR, ALUMINUM	SAMYOUNG	
3.0	EAY62811001	LGIT	AI	1	EA	C270	MG 330uF 35V M P5 Φ10X13	CAPACITOR, ALUMINUM	SUSCON	
3.0	EAY62811001	LGIT	AI	2	EA	C272,C279	NXH 470uF 25V M P5 Φ10X12.5	CAPACITOR, ALUMINUM	SAMYOUNG	
3.0	EAY62811001	LGIT	AI	2	EA	C272,C279	MG 470uF 25V M P5 Φ10X13	CAPACITOR, ALUMINUM	SUSCON	
3.0	EAY62811001	LGIT	AI	2	EA	C505,C511	NXB 47uF 50V M P5 Φ6.3X11	CAPACITOR, ALUMINUM	SAMYOUNG	
3.0	EAY62811001	LGIT	AI	2	EA	C505,C511	SG 47uF 50V M P5 Φ6.3X11	CAPACITOR, ALUMINUM	SUSCON	
3.0	EAY62811001	LGIT	AI	1	EA	C804	NXB 22uF 50V M P5 Φ5X11	CAPACITOR, ALUMINUM	SAMYOUNG	
3.0	EAY62811001	LGIT	AI	1	EA	C804	SG 22uF 50V M P5 Φ5X11	CAPACITOR, ALUMINUM	SUSCON	
3.0	EAY62811001	LGIT	AI	2	EA	C508,C512	NXB 10uF 50V M P5 Φ5X11	CAPACITOR, ALUMINUM	SAMYOUNG	
3.0	EAY62811001	LGIT	AI	2	EA	C508,C512	SG 10uF 50V M P5 Φ5X11	CAPACITOR, ALUMINUM	SUSCON	
3.0	EAY62811001	LGIT	AI	2	EA	C801,C802	NXB 4.7uF 50V M P5 Φ5X11	CAPACITOR, ALUMINUM	SAMYOUNG	
3.0	EAY62811001	LGIT	AI	2	EA	C801,C802	SG 4.7uF 50V M P5 Φ5X11	CAPACITOR, ALUMINUM	SUSCON	
3.0	EAY62811001	LGIT	AI	1	EA	C115	NXB 2.2uF 50V M P5 Φ5X11	CAPACITOR, ALUMINUM	SAMYOUNG	2013Y
3.0	EAY62811001	LGIT	AI	5	EA	D101,D105,D501,D502,D503	HER108G 1KV 1A DO-41	DIODE	RECTRON	
3.0	EAY62811001	LGIT	AI	5	EA	D101,D105,D501,D502,D503	UF4007 1KV 1A DO-41	DIODE	TSC	
3.0	EAY62811001	LGIT	AI	5	EA	D101,D105,D501,D502,D503	UF4007 1KV 1A DO-41	DIODE	DACHANG	
3.0	EAY62811001	LGIT	AI	5	EA	D101,D105,D501,D502,D503	UF1007 1KV 1A DO-41	DIODE	DIODES	
3.0	EAY62811001	LGIT	AI	26	EA	EL3,EL4,EL7,EL8,EL13, EL14,EL21,EL22,EL27,EL28, EL29,EL30,EL35,EL36,EL37, EL38,EL41,EL42,EL43,EL44, EL51,EL58,EL59,EL60,EL61, EL98	1.6X3.0	EYELET	LEZHI	
3.0	EAY62811001	LGIT	AI	21	EA	EL1,EL2,EL5,EL9,EL10, EL11,EL12,EL15,EL16,EL17, EL18,EL19,EL20,EL23,EL24, EL25,EL26,EL31,EL32,EL33, EL34	2.0X3.0	EYELET	LEZHI	
3.0	EAY62811001	LGIT	AI	45	EA	J1,J2,J4,J7,J8, J9,J10,J11,J15,J21, J22,J24,J25,J26,J29, J30,J39,J40,J41,J42, J44,J46,J47,J49,J50, J51,J57,J56,J60,J62, J64,J65,J66,J67,J69, J70,J71,J72,J74,J75, J76,J77,J78,J79,J80	Φ0.6	JUMPER WIRE	TPI	
3.0	EAY62811001	LGIT	AI	45	EA	J1,J2,J4,J7,J8, J9,J10,J11,J15,J21, J22,J24,J25,J26,J29, J30,J39,J40,J41,J42, J44,J46,J47,J49,J50, J51,J57,J56,J60,J62, J64,J65,J66,J67,J69, J70,J71,J72,J74,J75, J76,J77,J78,J79,J80	Φ0.6	JUMPER WIRE	ILKWANG	
3.0	EAY62811001	LGIT	AI	45	EA	J1,J2,J4,J7,J8, J9,J10,J11,J15,J21, J22,J24,J25,J26,J29, J30,J39,J40,J41,J42, J44,J46,J47,J49,J50, J51,J57,J56,J60,J62, J64,J65,J66,J67,J69, J70,J71,J72,J74,J75, J76,J77,J78,J79,J80	Φ0.6	JUMPER WIRE	Seungw on	
3.0	EAY62811001	LGIT	AI	45	EA	J1,J2,J4,J7,J8, J9,J10,J11,J15,J21, J22,J24,J25,J26,J29, J30,J39,J40,J41,J42, J44,J46,J47,J49,J50, J51,J57,J56,J60,J62, J64,J65,J66,J67,J69, J70,J71,J72,J74,J75, J76,J77,J78,J79,J80	Φ0.6	JUMPER WIRE	LEAN TECH	
3.0	EAY62811001	LGIT	AI	4	EA	P601,P603,P803,P804	SSJS236-6-3 (6mm Under)	GT PIN	LEZHI	
3.0	EAY62811001	LGIT	AI	8	EA	LB101,LB102,LB103, LB104,LB105,LB107, LB201,LB601	BFS3550R2F SINGLE RADIAL	INDUCTOR, BEAD FILTER LEAD	SAMWHA	

3.0	EAY62811001	LGIT	AI	1	EA	LD701	LTL-1CHY-001A, 5mm Pitch Type (Yellow)	LED	LITE-ON	
3.0	EAY62811001	LGIT	AI	1	EA	LD701	204-10UYC-S530, 5mm Pitch Type (Yellow)	LED	EVERLIGHT	
3.0	EAY62811001	LGIT	AI	1	EA	R505	CRS 1Ω 1/4W J SMALL	RESISTOR, CARBON FILM	ABCO	
3.0	EAY62811001	LGIT	AI	1	EA	R505	RDM94 1Ω 1/4W J SMALL	RESISTOR, CARBON FILM	SMART	
3.0	EAY62811001	LGIT	AI	1	EA	R505	SFR25 1Ω 1/4W J SMALL	RESISTOR, CARBON FILM	PILKOR	
3.0	EAY62811001	LGIT	AI	1	EA	R117	CRS 47Ω 1/4W J SMALL / CR 47Ω 1/6W J	RESISTOR, CARBON FILM	ABCO	
3.0	EAY62811001	LGIT	AI	1	EA	R117	RDM94 47Ω 1/4W J SMALL / RD 47Ω 1/6W J	RESISTOR, CARBON FILM	SMART	
3.0	EAY62811001	LGIT	AI	1	EA	R117	SFR25 47Ω 1/4W J SMALL / SFR 47Ω 1/6W J	RESISTOR, CARBON FILM	PILKOR	
3.0	EAY62811001	LGIT	AI	1	EA	R612	CRS 33Ω 1/4W J SMALL	RESISTOR, CARBON FILM	ABCO	
3.0	EAY62811001	LGIT	AI	1	EA	R612	RDM94 33Ω 1/4W J SMALL	RESISTOR, CARBON FILM	SMART	
3.0	EAY62811001	LGIT	AI	1	EA	R612	SFR25 33Ω 1/4W J SMALL	RESISTOR, CARBON FILM	PILKOR	
3.0	EAY62811001	LGIT	AI	1	EA	R503	CRS 20Ω 1/4W J SMALL	RESISTOR, CARBON FILM	ABCO	
3.0	EAY62811001	LGIT	AI	1	EA	R503	RDM94 20Ω 1/4W J SMALL	RESISTOR, CARBON FILM	SMART	
3.0	EAY62811001	LGIT	AI	1	EA	R503	SFR25 20Ω 1/4W J SMALL	RESISTOR, CARBON FILM	PILKOR	
3.0	EAY62811001	LGIT	AI	1	EA	R502	CRS 100Ω 1/4W J SMALL	RESISTOR, CARBON FILM	ABCO	
3.0	EAY62811001	LGIT	AI	1	EA	R502	RDM94 100Ω 1/4W J SMALL	RESISTOR, CARBON FILM	SMART	
3.0	EAY62811001	LGIT	AI	1	EA	R502	SFR25 100Ω 1/4W J SMALL	RESISTOR, CARBON FILM	PILKOR	
3.0	EAY62811001	LGIT	AI	1	EA	R124	MSR37 1MΩ 1/2W J SURGE	RESISTOR, FIXED CARBON COMPOSITION	PILKOR	
3.0	EAY62811001	LGIT	AI	1	EA	R124	PRC 1MΩ 1/2W J SURGE	RESISTOR, FIXED CARBON COMPOSITION	SMART	
3.0	EAY62811001	LGIT	AI	1	EA	R101	MSR37 1.2MΩ 1/2W J SURGE	RESISTOR, FIXED CARBON COMPOSITION	PILKOR	
3.0	EAY62811001	LGIT	AI	1	EA	R101	PRC 1.2MΩ 1/2W J SURGE	RESISTOR, FIXED CARBON COMPOSITION	SMART	
3.0	EAY62811001	LGIT	AI	1	EA	R501	MORS 62KΩ 1W J SMALL	RESISTOR, METAL OXIDE FILM	ABCO	
3.0	EAY62811001	LGIT	AI	1	EA	R501	RSD01 62KΩ 1W J SMALL	RESISTOR, METAL OXIDE FILM	SMART	
3.0	EAY62811001	LGIT	AI	1	EA	R501	PR01 62KΩ 1W J SMALL	RESISTOR, METAL OXIDE FILM	PILKOR	
3.0	EAY62811001	LGIT	AI	2	EA	R286,R287	MORS 1KΩ 2W J SMALL	RESISTOR, METAL OXIDE FILM	ABCO	
3.0	EAY62811001	LGIT	AI	2	EA	R286,R287	RSD02 1KΩ 2W J SMALL	RESISTOR, METAL OXIDE FILM	SMART	
3.0	EAY62811001	LGIT	AI	2	EA	R286,R287	PR02 1KΩ 2W J SMALL	RESISTOR, METAL OXIDE FILM	PILKOR	
3.0	EAY62811001	LGIT	AI	3	EA	R283,R284,R285	MORS 3.3KΩ 2W J SMALL	RESISTOR, METAL OXIDE FILM	ABCO	
3.0	EAY62811001	LGIT	AI	3	EA	R283,R284,R285	RSD02 3.3KΩ 2W J SMALL	RESISTOR, METAL OXIDE FILM	SMART	
3.0	EAY62811001	LGIT	AI	3	EA	R283,R284,R285	PR02 3.3KΩ 2W J SMALL	RESISTOR, METAL OXIDE FILM	PILKOR	
3.0	EAY62811001	LGIT	AI	2	EA	R829,R830	MORS 12KΩ 2W J SMALL	RESISTOR, METAL OXIDE FILM	ABCO	
3.0	EAY62811001	LGIT	AI	2	EA	R829,R830	RSD02 12KΩ 2W J SMALL	RESISTOR, METAL OXIDE FILM	SMART	
3.0	EAY62811001	LGIT	AI	2	EA	R829,R830	PR02 12KΩ 2W J SMALL	RESISTOR, METAL OXIDE FILM	PILKOR	
3.0	EAY62811001	LGIT	AI	2	EA	R251,R252	MORS 24KΩ 2W J SMALL	RESISTOR, METAL OXIDE FILM	ABCO	
3.0	EAY62811001	LGIT	AI	2	EA	R251,R252	RSD02 24KΩ 2W J SMALL	RESISTOR, METAL OXIDE FILM	SMART	
3.0	EAY62811001	LGIT	AI	2	EA	R251,R252	PR02 24KΩ 2W J SMALL	RESISTOR, METAL OXIDE FILM	PILKOR	
3.0	EAY62811001	LGIT	AI	2	EA	R510,R511	WNPS 0.82Ω 1W J SMALL	RESISTOR,WIRE WOUND	ABCO	
3.0	EAY62811001	LGIT	AI	2	EA	R510,R511	PRN 0.82Ω 1W J SMALL	RESISTOR,WIRE WOUND	SMART	
3.0	EAY62811001	LGIT	AI	2	EA	R601,R602	WNPS 0.16Ω 2W J SMALL	RESISTOR,WIRE WOUND	ABCO	
3.0	EAY62811001	LGIT	AI	2	EA	R601,R602	PRN 0.16Ω 2W J SMALL	RESISTOR,WIRE WOUND	SMART	
3.0	EAY62811001	LGIT	AI	1	EA	R827	WNPS 0.11Ω 2W J SMALL	RESISTOR,WIRE WOUND	ABCO	
3.0	EAY62811001	LGIT	AI	1	EA	R827	PRN 0.11Ω 2W J SMALL	RESISTOR,WIRE WOUND	SMART	
3.0	EAY62811001	LGIT	AI	1	EA	ZD102	1N5239B 9.1V DO-35	DIODE, ZENER	VISHAY	
3.0	EAY62811001	LGIT	AI	1	EA	ZD102	1N5239B 9.1V DO-35	DIODE, ZENER	RECTRON	
3.0	EAY62811001	LGIT	AI	1	EA	ZD502	1N5245B 15V DO-35	DIODE, ZENER	VISHAY	
3.0	EAY62811001	LGIT	AI	1	EA	ZD502	1N5245B 15V DO-35	DIODE, ZENER	RECTRON	
3.0	EAY62811001	LGIT	AI	1	EA	ZD503	1N5250B 20V DO-35	DIODE, ZENER	VISHAY	
3.0	EAY62811001	LGIT	AI	1	EA	ZD503	1N5250B 20V DO-35	DIODE, ZENER	RECTRON	
3.0	EAY62811001	LGIT	AI	1	EA	ZD504	1N5235B 6.8V DO-35	DIODE, ZENER	VISHAY	
3.0	EAY62811001	LGIT	AI	1	EA	ZD504	1N5235B 6.8V DO-35	DIODE, ZENER	RECTRON	
3.0	EAY62811001	LGIT	AI	1	EA	PCB	LGP55-13LPB (159X270X1.6T) FR-1 KB,DS,L, 1oz CTI-600	PCB	SHANGHAI WANZHENG	
3.0	EAY62811001	LGIT	AI	1	EA	PCB	LGP55-13LPB (159X270X1.6T) FR-1 KB,DS,L, 1oz CTI-600	PCB	SHANGHAI WANZHENG(WYT)	
3.0	EAY62811001	LGIT	AI	1	EA	PCB	LGP55-13LPB (159X270X1.6T) FR-1 KB,DS,L, 1oz CTI-600	PCB	CHENG HO	
3.0	EAY62811001	LGIT	ETC				SUBSIDIARY MATERIALS			
3.0	EAY62811001	LGIT	ETC	1	EA		BARCODE LABEL (40*8)	BAR CODE	SERVEONE	
3.0	EAY62811001	LGIT	ETC	1	EA		BARCODE LABEL (40*8)	BAR CODE	Hansung Color	
3.0	EAY62811001	LGIT	ETC	15	GR		H-828W	BOND (RTV)	OKONG	
3.0	EAY62811001	LGIT	ETC	15	GR		EA-4100	BOND (RTV)	DOW CORNING	
3.0	EAY62811001	LGIT	ETC	15	GR		SR-9000	BOND (RTV)	DAEHEUNG CHEMICAL	

3.0	EAY62811001	LGIT	ETC	0.05	EA		506 X 344 X 190 8t	BOX CARTON	TAILI PACKING	
3.0	EAY62811001	LGIT	ETC	0.05	EA		506 X 344 X 190 8t	BOX CARTON	HUAXING PACK	
3.0	EAY62811001	LGIT	ETC	0.05	EA		506 X 344 X 190 8t	BOX CARTON	Haier Fungchoi	
3.0	EAY62811001	LGIT	ETC	0.10	EA		506 X 341 8t	BOX PAD	TAILI PACKING	
3.0	EAY62811001	LGIT	ETC	0.10	EA		506 X 341 8t	BOX PAD	HUAXING PACK	
3.0	EAY62811001	LGIT	ETC	0.10	EA		506 X 341 8t	BOX PAD	Haier Fungchoi	
3.0	EAY62811001	LGIT	ETC	0.55	EA		341 X 166 8t	BOX PARTITION	TAILI PACKING	
3.0	EAY62811001	LGIT	ETC	0.55	EA		341 X 166 8t	BOX PARTITION	HUAXING PACK	
3.0	EAY62811001	LGIT	ETC	0.55	EA		341 X 166 8t	BOX PARTITION	Haier Fungchoi	
3.0	EAY62811001	LGIT	ETC	0.20	EA		506 X 166 8t	BOX PARTITION	TAILI PACKING	
3.0	EAY62811001	LGIT	ETC	0.20	EA		506 X 166 8t	BOX PARTITION	HUAXING PACK	
3.0	EAY62811001	LGIT	ETC	0.20	EA		506 X 166 8t	BOX PARTITION	Haier Fungchoi	
3.0	EAY62811001	LGIT	ETC	1.00	EA		350 X 180	BUBBLE SHEET	SERVEONE	
3.0	EAY62811001	LGIT	ETC	1.00	EA		350 X 180	BUBBLE SHEET	KELIN	
3.0	EAY62811001	LGIT	ETC	25	GR		EF-9301(g)	FLUX	ALPHA	
3.0	EAY62811001	LGIT	ETC	25	GR		ILF-714(kg)	FLUX	ION ELEC	
3.0	EAY62811001	LGIT	ETC	25	GR		DF-234U	FLUX	DOOSUNG	
3.0	EAY62811001	LGIT	ETC	25	GR		ILF-710	FLUX	ION ELEC	
3.0	EAY62811001	LGIT	ETC	15	GR		HSE-11 B20 BAR (SN:99%,AG:0.3%,CU:0.7%)	SOLDER BAR	HEESUNG METAL	
3.0	EAY62811001	LGIT	ETC	15	GR		SN–CU–NI–P (HSE16(P)-B20)	SOLDER BAR	HEESUNG METAL	
3.0	EAY62811001	LGIT	ETC	15	GR		SN:99%, AG:0.3%, CU:0.7% BAR	SOLDER BAR	Alpha Metal	
3.0	EAY62811001	LGIT	ETC	5	GR		HSE-11 B20 BAR (SN:99%,AG:0.3%,CU:0.7%)	SOLDER WIRE	HEESUNG METAL	
3.0	EAY62811001	LGIT	ETC	5	GR		SN–CU–NI–P (HSE16(P)-B20)	SOLDER WIRE	HEESUNG METAL	
3.0	EAY62811001	LGIT	ETC	5	GR		SN:99%, AG:0.3%, CU:0.7% wire	SOLDER WIRE	Alpha Metal	

Process Marking

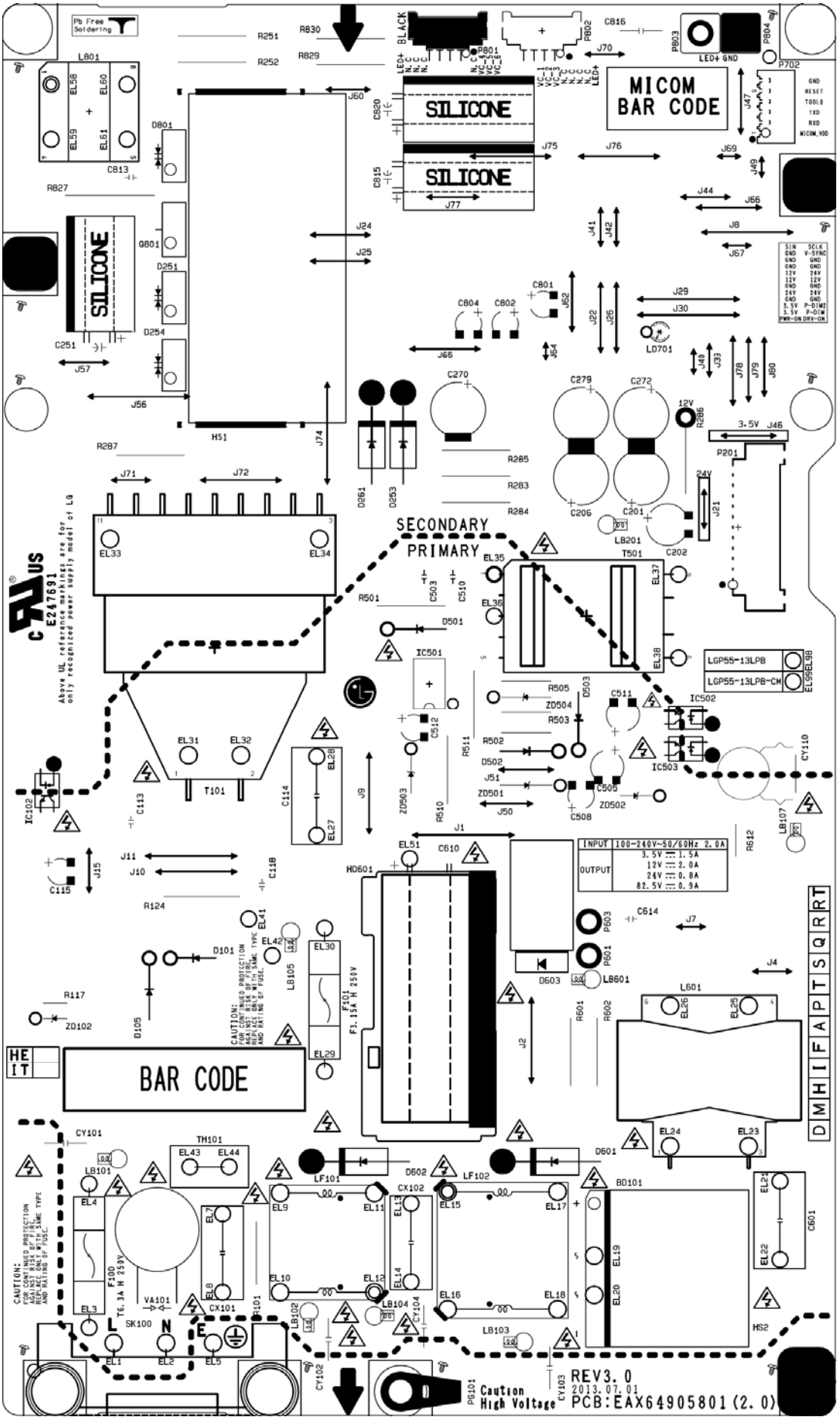
공정표시 MARK (PCB SILK)



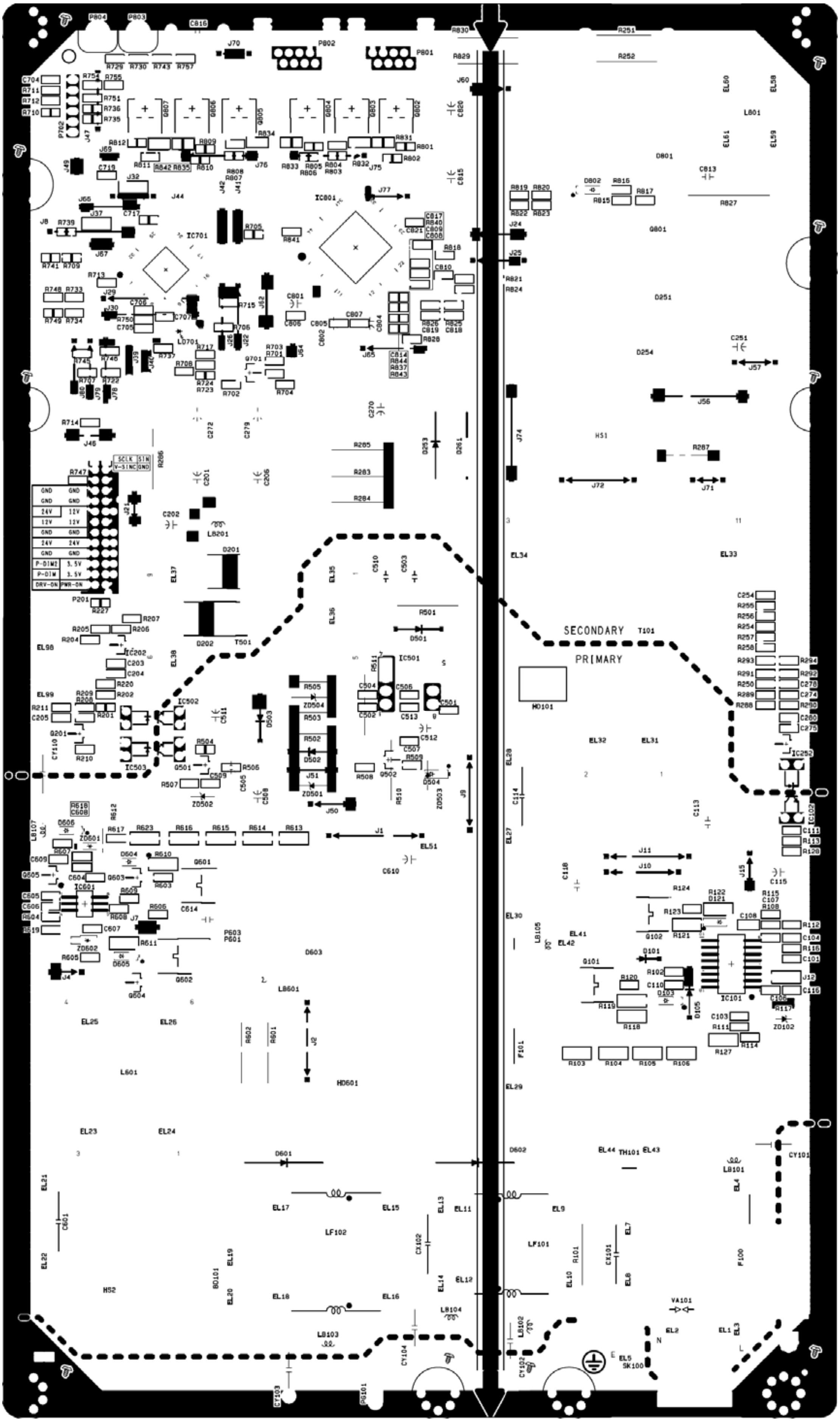
D : 자삽
M : SMD
H : 수삽 취출
I : ICT
F : 1차 성능
A : AGING
P : HI-POT
T : 취출 검사 (ATE)
S : SET 검사
Q : QC 검사
R : 불량 수리
RT : 양산 보증 시험

PCB Layout

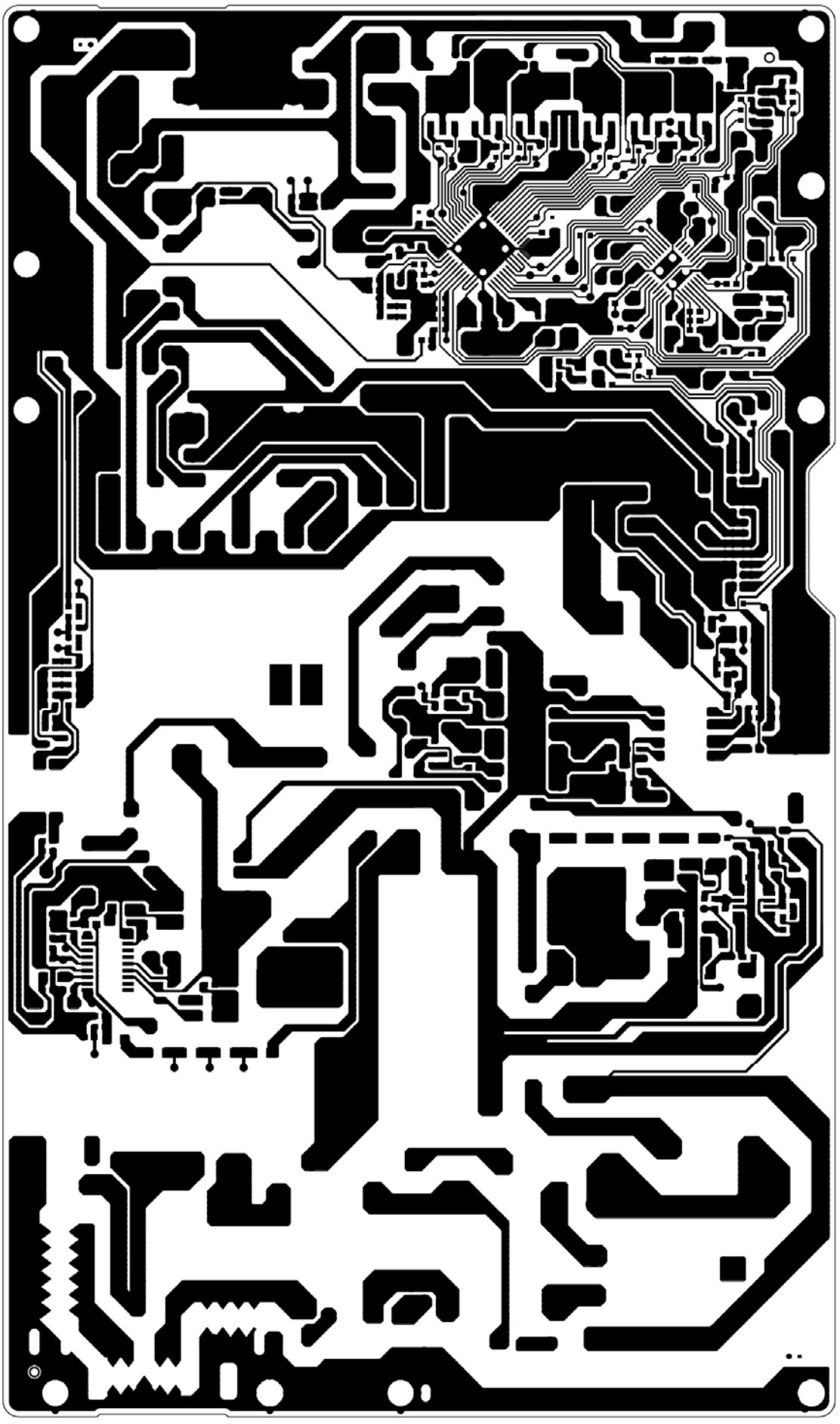
Top Silk


MICOM
BAR CODE
SILICONE
SILICONE
SILICONE
SECONDARY
PRIMARY
BAR CODE
LGP55-13LPB
LGP55-13LPB-CM
REV3. 0
2013. 07. 01
PCB:EAX64905801 (2. 0)
Caution
High Voltage

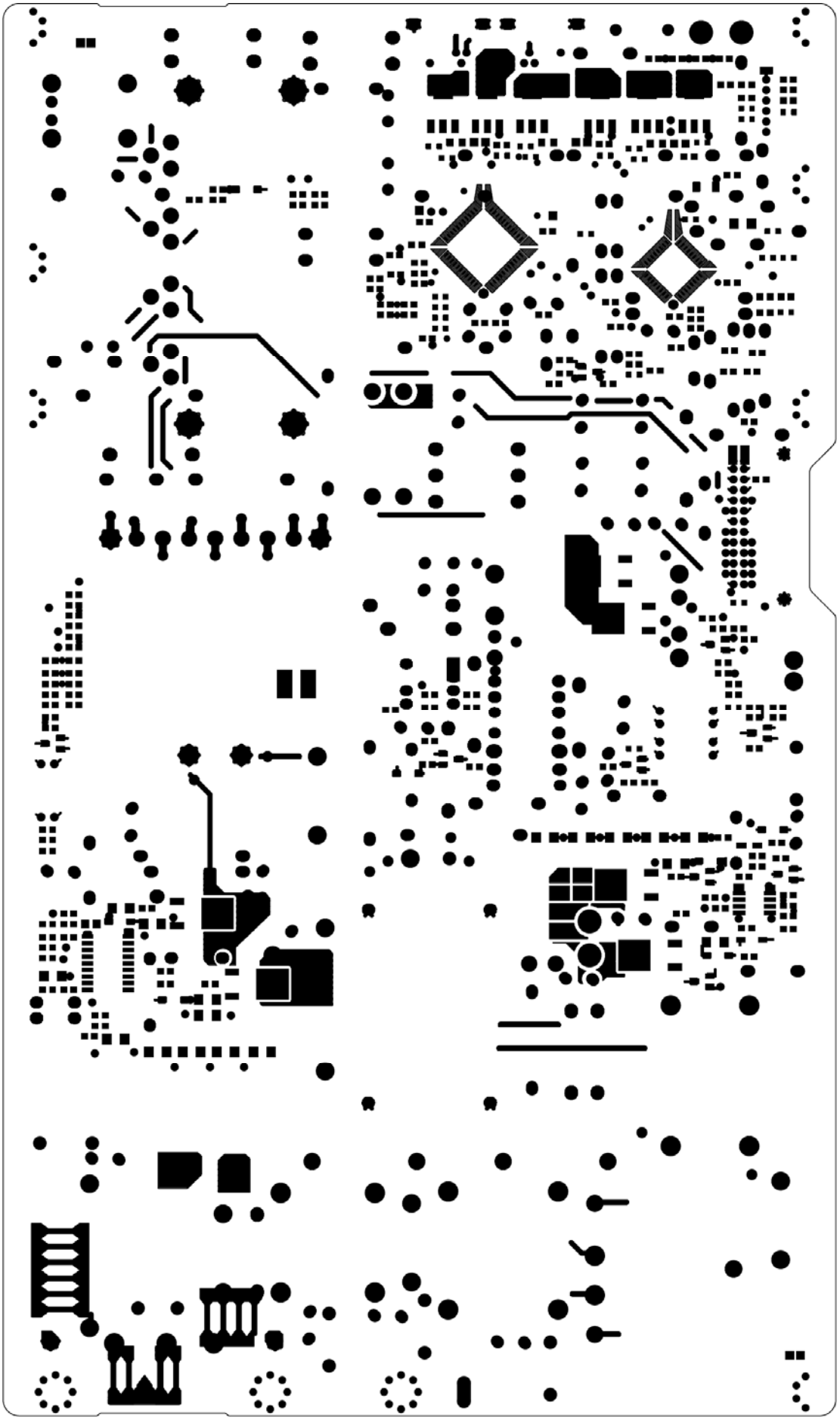
Bottom Silk



Bottom Pattern



Bottom Solder mask



Safety Parts

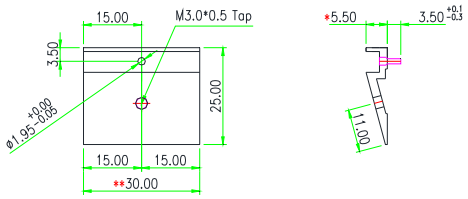
Object/part No.	Manufacturer / Trademark	Type / Model	Value / Rating	Parts Marking (實物)	standard	mark(s) of conformity1)
AC input connector, (SK100)	Dongil Tech	DAC-18C3M1	250V / 2.5A	DAC-18C3M1	IEC 60320-1	
Alt	Dongil Tech	DAC-18C3M1C	250V / 2.5A	DAC-18C3M1	IEC 60320-1	
Fuse, (F100)	Littelfuse Inc.	215 Series	T6.3A H / 250V	LF.T6.3AH250VP	IEC 60127-2	
	WALTER FUSE	TSC		TSC6.3A250V(P)	IEC 60127	
	BUSSMANN	S505		T6.3AH250V	IEC 60127-2	
	Dainfuse	50CT		T6.3AH 250V	IEC 60127	
	CONQURE	UDA-A		UDA-A T6.3A H 250V	IEC 60127-3-5	
Fuse, (F101)	Littelfuse Inc.	216.XXXX	F3.15A H / 250V	LF.F3.15AH250VP	IEC 60127-2	
	WALTER FUSE	FSC		FSC3.15A250V(P)	IEC 60127	
	Dainfuse	50CF		F3.15AH250V	IEC 60127	
	CONQURE	UBM-A		UBM-A 3.15A 250V	IEC 60127-2-1	
Line Filter, (LF101)	TNC	CS615200SHA	Rated 130℃	615200S	IEC 60065	Test in appliance
	Dongil Tech	LT6015205		015205		
	FEELUX	LLF-130		LLF-130		
	JIANGSU CHANNELON ELECTRONIC GROUP					
	SOOJUNG					
	ZHONGTAI					
	NAMYANG					
Base material of Linefilter (LF101)	MOMENTIVE SPECIALTY CHEMICALS GMBH	PF 2736	V-0, 150℃		UL, E61040	UL
Alt	Chang Chun Plastics Co., Ltd	T375HF, T375J	V-0, 150℃		UL, E59481	UL
Alt	NAN YA PLASTICS CORP PLASTICS 4TH DIV	1403G3, 1403G6	V-0, 130℃		UL, E130155	UL
Alt	POLY PLASTICS CO., LTD	1140A66	V-0, 130℃		UL, E109088	UL
Alt	Rhodia Enginnering plastics	PA66, A50H1	V-0		UL, E44716	UL
Alt	Sabic Innovative Plastics japan LLC	420SE0	V-0, 130℃		UL, E45587	UL
Alt	Toray Industrial INC	A604 E604	V-0 200℃		UL E41797	UL
Alt	SAMYANG CORPORATION	1500GN-30	V-0 130℃		UL, E121254	UL
Alt	SUMITOMO BAKELITE CO LTD	PM-9820	V-0, 150℃		UL, E41429	UL
Line Filter, (LF102)	TNC	CS915200SBA	Rated 130℃	915200S	IEC 60065	Test in appliance
	Dongil Tech	LH9B019200		019200		
	FEELUX	LLF-123		LLF-123		
	JIANGSU CHANNELON ELECTRONIC GROUP					
	SOOJUNG					
	ZHONGTAI					
	JIANGSU TAICHANG ELECTRONICS Co.,LTD.					
	NAMYANG					
	DONG YANG TELECOM CO., LTD					
Base material of Linefilter (LF102)	MOMENTIVE SPECIALTY CHEMICALS GMBH	PF 2736	V-0, 150℃		UL, E61040	UL
Alt	Chang Chun Plastics Co., Ltd	T375HF, T375J	V-0, 150℃		UL, E59481	UL
Alt	NAN YA PLASTICS CORP PLASTICS 4TH DIV	1403G3, 1403G6	V-0, 130℃		UL, E130155	UL
Alt	POLY PLASTICS CO., LTD	1140A66	V-0, 130℃		UL, E109088	UL
Alt	LG CHEMICAL LTD	LUPOX GP-2306F	V-0, 130℃		UL, E67171	UL
Alt	SK CHEMICALS CO., LTD	Ecotran 1040G	V-0, 130℃		UL, E215991	UL
Alt	Rhodia Enginnering plastics	PA66, A50H1	V-0		UL, E44716	UL
Alt	SUMITOMO BAKELITE CO LTD	PM-9820	V-0, 150℃		UL, E41429	UL
Varistor, (VA101)	Samwha	SVC621D-14A	Climatic category: 40/085/21 Maximum continuous voltage:385Va.c. Current pulse rating: 6 kV/3 kA	SVC 621-14	CECC 42000 CECC 42200 CECC 42201 IEC 60065 Clause 14.12 and IEC 60950-1 Annex Q	
	Amotech Co., Ltd.	INR 14D621K	Climatic category: 40/085/56 Maximum continuous voltage: 385Va.c. Current pulse rating: 6 kV/3 Ka	INR 14D621	CECC42000/A1 CECC42200/A1 CECC 42201-001 IEC 61051-1 IEC 61051-2 IEC 61051-2-2 IEC 60065 Clause 14.12 and IEC 60950-1 Annex Q	
	Xiamen Wanming Electronics Co.,Ltd	WMR14D621K	Climatic category: 40/85/56 Maximum continuous voltage: 750Va.c. Current pulse rating: 6 kV/3 kA	WMR 14D621K	IEC 61051-1 IEC 61051-2 IEC 61051-2-2 IEC 60950-1 Annex Q	
	Guangxi New Future Information Industry Co.,Ltd	NFC 14D621K	Climatic category: 40/085/21 Maximum continuous voltage:385Va.c. Current pulse rating: 6 kV/3 kA	NFC 14D621K	IEC 61051-1 IEC 61051-2 IEC 61051-2-2 IEC 60950-1 Annex Q	
Bridge Diode, (BD101)	Lite-on	GBJ1506	Min 600V / 15A	GBJ1506		Test in appliance
	DACHANG	D15SB60		D15SB60		
	RECTRON	RS1507M		RS1507M		
	TSC	TS15P05G		TS15P05G	E96005	
	GULF	G15XB60		G15XB60		
	SHINDENGEN	D15XB60		D15XB60	E142422	
X-cap.(CX101,CX102)	Pilkor	PCX2 337	Min 275V~ / (CX101= Max 0.33uF, CX102= Max 0.33uF)	PCX2 337 MKP	IEC 60384-14 UL1414	
	Okaya	LE		LE	IEC 60384-14 UL1414	
	EUROPTRONIC	MPX		MPX	E199061/ E311052 IEC 60384-14-3'nd edition	
	CHENGTUNG	CTX		CTX	IEC 60384-14 UL1414	

Thermistor. (TH101)	DSC	DSC 5D-15	5ohm at 25 °C	DSC 5D-15	IEC 60065	
	Xiamen Wanming Electronics Co.,Ltd	WTR15D050M		WTR15D050		
	JIANGSU XINGSHUN ELECTRONICS CO., LTD	5D2-15		5D2-15		
	Smart	ICL-5W		ICL-05 5R00MSMT		
	NANJING SHIHENG ELECTRONICS CO., LTD	MF72-5D15		MF72 5D15		
Elec.Cap.(C610)	SAMYOUNG	KMF	450V / Max 100uF / 105℃	KMF450V100uF	IEC 60950-1	Test in appliance
	SUSCON	SK		SK450V100uF		
	SAMYOUNG	NZE	500V / Max 100uF / 105℃	NZE500V100uF	IEC 60950-1	Test in appliance
	SUSCON	SK		SK500V100uF		
Switching TR,(Q601,Q602)	STMICRO	STD13NM60N	Min. 600V / Min 8A	13NM60N	IEC 60950-1	Test in appliance
	FAIRCHILD	FCD380N60E		FCD380N60E		
	TOSHIBA	TK10P60W		K10P60W		
	INFINEON	IPD60R450E6		6R450E6		
Switching TR,(Q101,Q102)	STMICRO	STD10NM60N	Min. 600V / Min 6A	10NM60N	IEC 60950-1	Test in appliance
	FAIRCHILD	FCD600N60Z		FCD600N60Z		
	TOSHIBA	TK8P60V		K8P60V		
	INFINEON	IPD60R600E6		6R600E6		
Flyback IC, (IC501)	INFINEON	ICE3BR4765JZ	Min. 650 V / Min 1.67A	3BR4765JZ	IEC 60950-1	Test in appliance
Y Cap. (CY101,CY102,CY103,CY104)	Kunshan Wansheng	Y1 / CT7	Min 250V / (CY101= Max 470pF, CY102= Max 470pF, CY103= Max 470pF, CY104= Max 470pF)	CT7 471K	IEC 60384-14	
	Apex intec	Y1 / NK		NK471K		
	DONG IL	Y1 / DA		DA471K		
	YINANDON	Y1 / CT81		CT81 471K		
	SAMWHA	Y1 / SD		SD471K		
	JYA-NAY	Y1 / JN		JN471K		
	GUANGDONG SOUTH HONGMING	Y1 / F		F471K		
	TDK	Y1 / CD		CD471K		
Y Cap. (CY110)	Kunshan Wansheng	Y1 / CT7	Min 250V / CY103= Max 470pF	CT7 471K	IEC 60384-14	
	Apex intec	Y1 / NK		NK471K		
	DONG IL	Y1 / DA		DA471K		
	YINANDON	Y1 / CT81		CT81 471K		
	SAMWHA	Y1 / SD		SD471K		
	JYA-NAY	Y1 / JN		JN471K		
	GUANGDONG SOUTH HONGMING	Y1 / F		F471K		
	TDK	Y1 / CD		CD471K		
PFC Coil,(L601)	FEELUX	12S-LP02	Class B 130℃	12S-LP02	IEC 60950-1	Test in appliance
	JIANGSU CHANNELON ELECTRONIC GROUP					
	SOOJUNG					
	TDK					
	LG Innotek					
	ZHONGTAI					
	H&E CO LTD					
	JIANGSU TAICHANG ELECTRONICS Co.,LTD.					
	NAMYANG					
Bobbin material of transformer (L601)	SUMITOMO BAKELITE CO LTD	PM-9820	V-0, 150℃		UL, E41429	UL
Switching Transformer, (T101)	FEELUX	13S-LM08	Class B 130℃	13S-LM08	IEC 60950-1	Test in appliance
	JIANGSU CHANNELON ELECTRONIC GROUP					
	SOOJUNG					
	TDK					
	LG Innotek					
	H&E CO LTD					
	NAMYANG					
Bobbin material of transformer (T101)	SUMITOMO BAKELITE CO LTD	PM-9820, PM-9630	V-0, 150℃		UL, E41429	UL
Alt	EI DUPONT DE NEMOURS & CO INC	FR530	V-0, 155℃		UL, E41938	UL
Switching Transformer, (T501)	FEELUX	12S-LS01	Class B 130℃	12S-LS01	IEC 60065	Test in appliance
	JIANGSU CHANNELON ELECTRONIC GROUP					
	SOOJUNG					
	TDK					
	ZHONGTAI					
	JIANGSU TAICHANG ELECTRONICS Co.,LTD.					
	H&E CO LTD					
	Clover hi-tech Co., Ltd.					
	NAMYANG					
	DONG YANG TELECOM CO., LTD					
Bobbin material of transformer (T501)	SUMITOMO BAKELITE CO LTD	PM-9820/PM-9630	V-0, 150℃		UL, E41429	UL
Insulating Tape of transformer (T501)	DUCK SUNG HITECH CO LTD	DTS-204	130℃		UL, E105147	UL
Alt	METAL LINE CO LTD	800(a)	130℃		UL, E162848	UL
Alt	JINGJIANG YAHUA PRESSURE SENSITIVE GLUE FTY	CT, PZ	130℃		UL, E165111	UL
Alt	JINGJIANG JINGYI ADHESIVE PRODUCT CO LTD	WF310, JY25-A	130℃		UL, E246950	UL
Alt	CHANG SHU LIANG YI TAPE INDUSTRY CO LTD	LY-XX,	130℃		UL, E246820	UL
Alt	3M Company	No.1318 series, No.1350 serises	130℃		UL, E17385	UL
Reinforced insulation wire of transformer (T501)	COSMOLINK CO LTD	TIW-M	Class B, 130℃		UL, E213764	UL
Alt	YOUNG CHANG SILICONE CO.,LTD.	STW-B	Class B, 130℃		UL, E242198	UL
Alt	GREAT LEOFLON INDUSTRIAL CO.,LTD	TRW(B)	Class B, 130℃		UL, E211989	UL
Alt	FURUKAWA ELECTRIC CO., LTD	TEX-E, TEX-BS	Class B, 130℃		UL, E206440	UL
Opto-coupler, (IC102,IC502,IC503)	Everlight	EL817	External cr: 7.7 mm, Internal cr: 6.0 mm DTI: 0.5 mm / 6000 Vrms	EL817	IEC 60065 UL 1577	
	Lite-on	LTV817...	External cr: 7.8 mm, Internal cr: 5.2 mm DTI: 0.8 mm / 6000 Vrms	817BN		
Discharge Resistor, (R101)	Smart	PRC	1/2W, 1.2Mohm, 5%		IEC 60065	
	UNIROYAL ELECTRONICS INDUSTRY CO., LTD	MGR0W2J****A10			IEC 60065	
	Pilkor	SR37,MSR37			IEC 60065	
Capacitor, (C601)	Pilkor	PCMP 372 (box)	0.82uF / 500V	820nJ 500V 372 MKP	IEC60384-1	
	LUMEN	MP (Film)	0.82uF / 500V	M 824J MP 500V		
	EUROPTRONIC	MPHB (Box)	0.82uF / 500V	MPHB 824 J 500		
	CHENG TUNG	CTH (Box)	0.82uF / 500V	CTH 824 J 500V		
Capacitor, (C114)	Pilkor	PCMP 384(Box)	0.027uF / 800V	27nJ 800V 384 MMKP	IEC60384-1	
	LUMEN	NP (Film)	0.027uF / 800V	M 273J NP 800V		
	EUROPTRONIC	MPLB (Box)	0.027uF / 1000V	MPLB 273J 1000		
PCB, FR-1	SHANGHAI WANZHENG	SWZ-2	94V-0			
	SHANGHAI WANZHENG (WYT)	SWZ-2	94V-0			
	CHENG HO POWER CORP	4B-5 4B-1, 4B-2, 4D	94V-0			
	SAMHAN	SH7	94V-0			

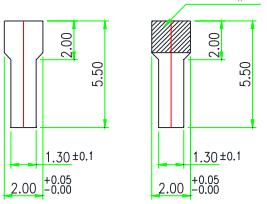
1) an asterisk indicates a mark which assures the agreed level of surveillance
Remarks: *) Large volume capacitors exceeding volume 1750㎣

Mechanical Drawing

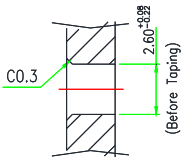
Ass'y Drawing
(Scale 1:1)



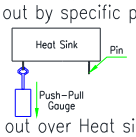
Pin Drawing
(Scale 5:1)



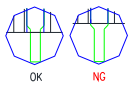
Hole Detail
(Scale: 5:1)



NOTE
1. Unspecified tolerance is ±0.2.
2. Flatness and warpage should be less than 0.15
3. The electric connection must be secured between heat sink and pin.
   (Electric resistance between pins in end of H/S: under 0.5 Ohm)
4. Cutting planes shouldn't be remained any sharp burrs could injure worker.
5. Any metallic particles, contaminations, scratches, dents and marks
   in surface of it couldn't be allowed
6. Pin shouldn't be taken out by specific pulling force is less than 3kgf.
   (Refer to below details)

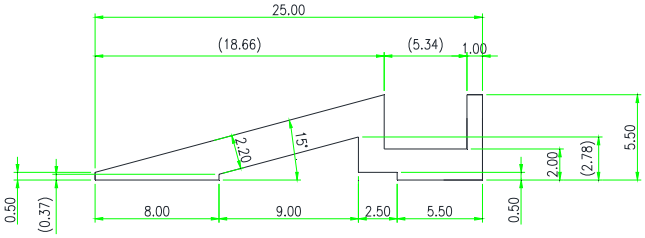


7. Lugs should not be jut out over Heat sink Body boundary



8. "*" : CTQ(critical to quality point)
9. "**" : Critical point to control the dimension
10. All parts don't have to contain prohibited substances including RoHS
    hazardous substances(Pb,Cd,Hg,Cr+6,PBB,PBDE) and for more details
    refer to LGIT's Eco-SCM standard, LGIT(30)-K-029.

Extruding Drawing
(Scale 4:1)

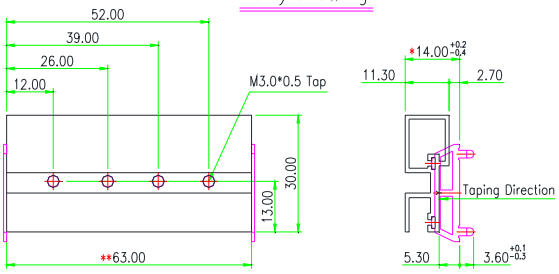


———	Pin	SPCC, ø 1.3	5.5(L)x2.0(D)	Tin Plating (Cu:1~6um,Sn:2~8um)
———	Heat Sink	Al6063, Purity: more than 98%	30(L)x25(W)x5.5(H)	Anodizing 2~12um
Part No.	Name	Raw Material	Specification	Plating/Finish

ZONE	SYMB	DATE OR NO.	APPD	CHKD	DSGD	APPD.	CHKD.	DSGD.	DRAW.	UNIT	SCALE	
						2012.10.15 Kim Chang Sung			2012.10.15 Jeon Sung Ho	mm	1 : 1	13Y LPB 42"47"55"

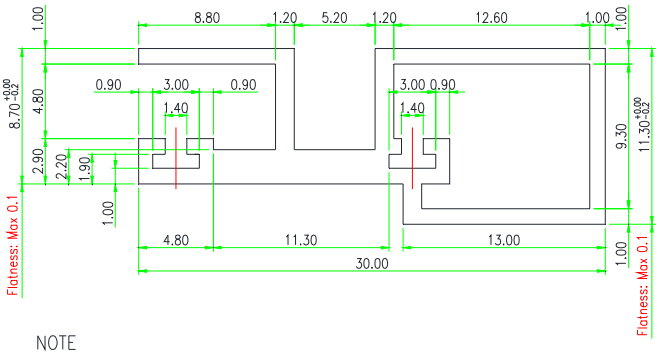
TITLE Heat Sink-1 (3HEAZA0367A-R)
DOCUMENT NO. (1/2)

Ass'y Drawing



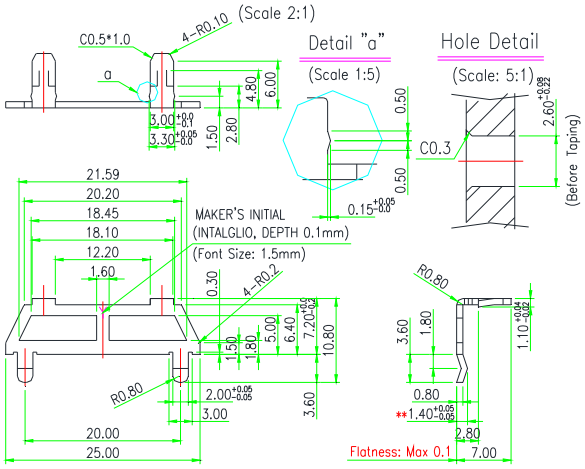
Extruding Drawing

(Scale 4:1)



Lug Drawing

(Scale 2:1)



Detail "a"

(Scale 1:5)

Hole Detail

(Scale: 5:1)

NOTE

1. Unspecified tolerance is ±0.15
2. Flatness and warpage should be less than 0.15
3. The electric connection must be secured between heat sink and lugs. (Electric resistance between lugs in end of H/S: under 0.5 Ohm)
4. Cutting planes shouldn't be remained any sharp burrs could injure worker.
5. Any metallic particles, contaminations, scratches, dents and marks in surface of it couldn't be allowed
6. Lug shouldn't be taken out by specific pulling force is less than 3kgf.

7. "*" : CTQ(critical to quality point)
8. "**" : Critical point to control the dimension
9. All parts don't have to contain prohibited substances including RoHS hazardous substances(Pb,Cd,Hg,Cr+6,PBB,PBDE) and for more details refer to LGIT's Eco-SCM standard, LGIT(30)-K-029.

Part No.	Name	Raw Material	Specification	Plating/Finish
———	Lug	SPCC, 0.8t	7.0(L)x25.0(W)x10.8(H)	Tin Plating (Cu:1~6um,Sn:2~8um)
———	Heat Sink	Al6063, Purity: more than 98%	63(L)x30(W)x14.0(H)	Anodizing 2~12um

ZONE	SYMB	DATE OR NO.	APPD	CHKD	DSGD

APPD.	CHKD.	DSGD.	DRAW.
2012.10.15 Kim Chang Sung			2012.10.15 Jeon Sung Ho

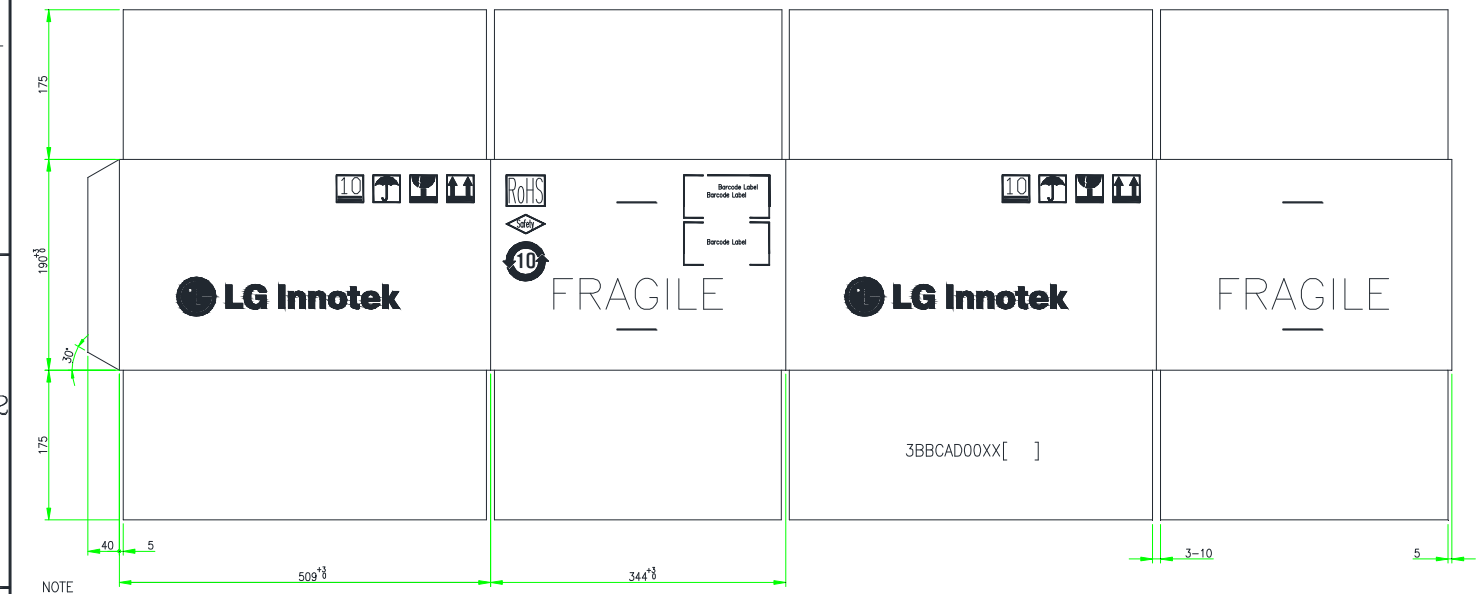
UNIT: mm | SCALE: 1 : 1

TITLE: 13Y LPB 42"47"55" Heat Sink-2 (3HEAZA0367B-R)

DOCUMENT NO. (2/2)

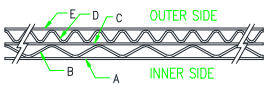
Packing Drawing

OUT BOX (SCALE 1:5)



NOTE
1. General tolerance : ±3
2. Compressed Strength(압축강도): Min 450Kgf/m^2
3. Demensions show internal size of box after assembled.
4. All parts don't have to contain prohibited substances including RoHS Hazardous substances(Pb, Cd, Hg, Cr+6, PBB, PBDE) and for more details refer to LGIT's Eco-SCM standard, LGIT(30)-K-029.
5. Adhesive side : adhere with glue and stapler
6. Material

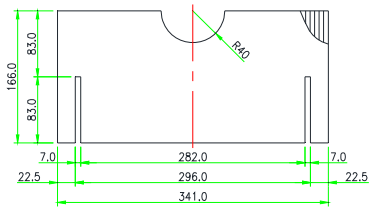
No.	PART NO.	MATERIAL					THICKNESS	TYPE	REMARK
		A	B	C	D	E			
1	3BBCAD00XXA-R	SK180g/m²	S120g/m²	S120g/m²	S120g/m²	K200g/m²	T=8	BA Flute Double-wall	DOMESTIC(GWANGJU)
2	3BBCAD00XXA-R	SK200g/m²	S150g/m²	S130g/m²	S150g/m²	K200g/m²	T=8	BA Flute Double-wall	LOCAL(YANTAI)



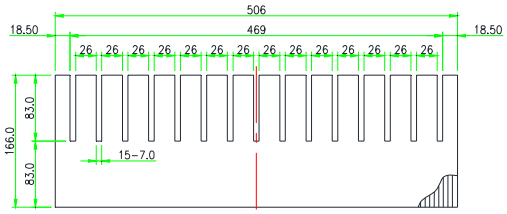
ZONE	SYMB	DATE OR NO.	APPD	CHKD	DSGD	ZONE	SYMB	DATE OR NO.	APPD	CHKD	DSGD

PART NO.	NAME	MATERIAL	SPEC.	FINISH	SIZE
	UNIT mm	SCALE 1 : 5	Part no. 3BBCAD0202A-R		
APPD. 2012.08.27 Kim Chang Sung	CHKD.	DSGD.	DRAW. 2012.08.27 Jeon Sung Ho	TITLE –	
				DOCUMENT NO. 1/4	

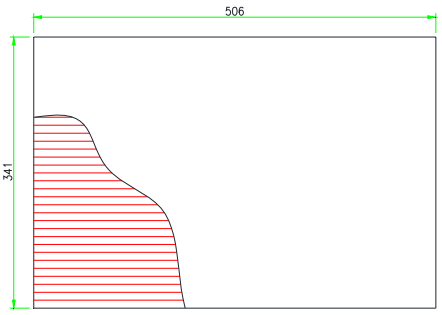
Cross Board A (341*166)



Cross Board B (506*166)

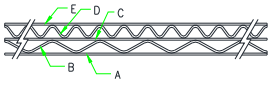


Tray Board (506*341)



NOTE
1. General tolerance : ±2
2. Demensions show internal size of box after assembled.
3. All parts must not contain prohibited substances including RoHS Hazardous substances(Pb, Cd, Hg, Cr+6, PBB, PBDE) and for more details refer to LGIT's Eco-SCM standard, LGIT(30)-K-029.
4. MATERIAL

No.	PART NO.	MATERIAL							REMARK
		A	B	C	D	E	THICKNESS	TYPE	
1	XXXXXXX	SK180g/m²	S120g/m²	S120g/m²	S120g/m²	K200g/m²	T=8	BA Flute Double-wall	DOMESTIC(GWANGJU)
2	XXXXXXX	SK150g/m²	S150g/m²	S130g/m²	S130g/m²	K150g/m²	T=8	BA Flute Double-wall	LOCAL(YANTAI)



ZONE	SYMB	DATE OR NO.	APPD	CHKD	DSGD

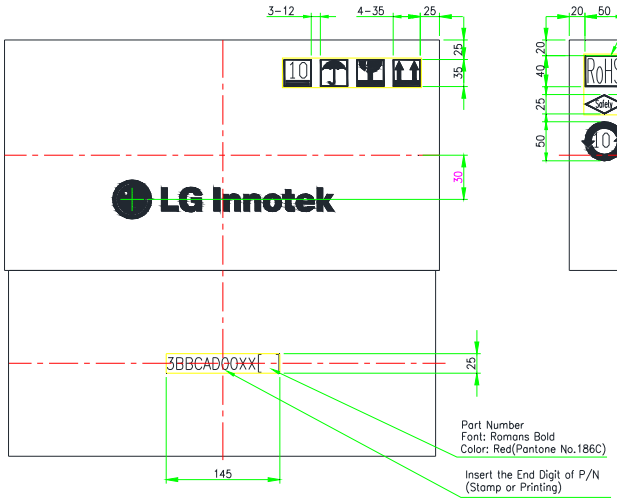
PART NO.	NAME	MATERIAL	SPEC.	FINISH	SIZE

UNIT	SCALE	Part no.
mm	1 : 5	3BBCAD0202A-R

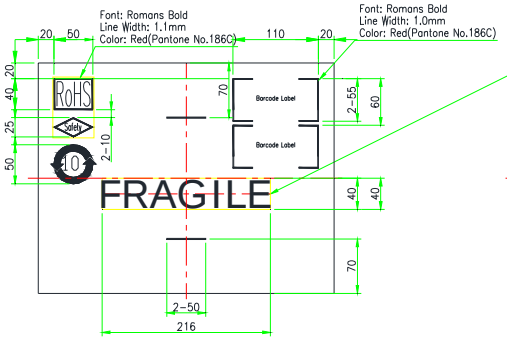
APPD.	CHKD.	DSGD.	DRAW.	TITLE
2012.08.27 Kim Chang Sung			2012.08.27 Jeon Sung Ho	-

DOCUMENT NO. 2/4

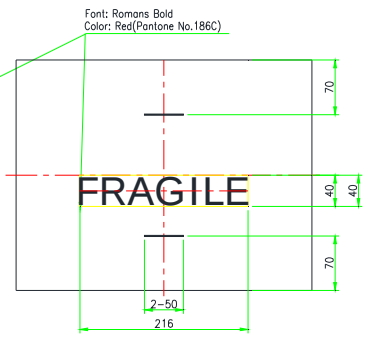
FRONT AND REAR SIDE



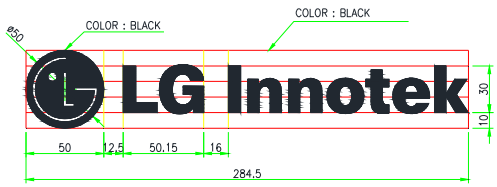
RIGHT SIDE



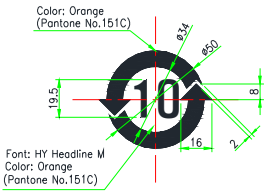
LEFT SIDE



DETAIL AND DRAWING OF SYMBOL AND LOGOTYPE (SCALE 2:1)



DETAIL OF E-MARK(SCALE 2:1)



NOTE
1. All parts don't have to contain prohibited substances including RoHS Hazardous substances(Pb, Cd, Hg, Cr+6, PBB, PBDE) and for more details refer to LGIT's Eco-SCM standard, LGIT(30)-K-029.

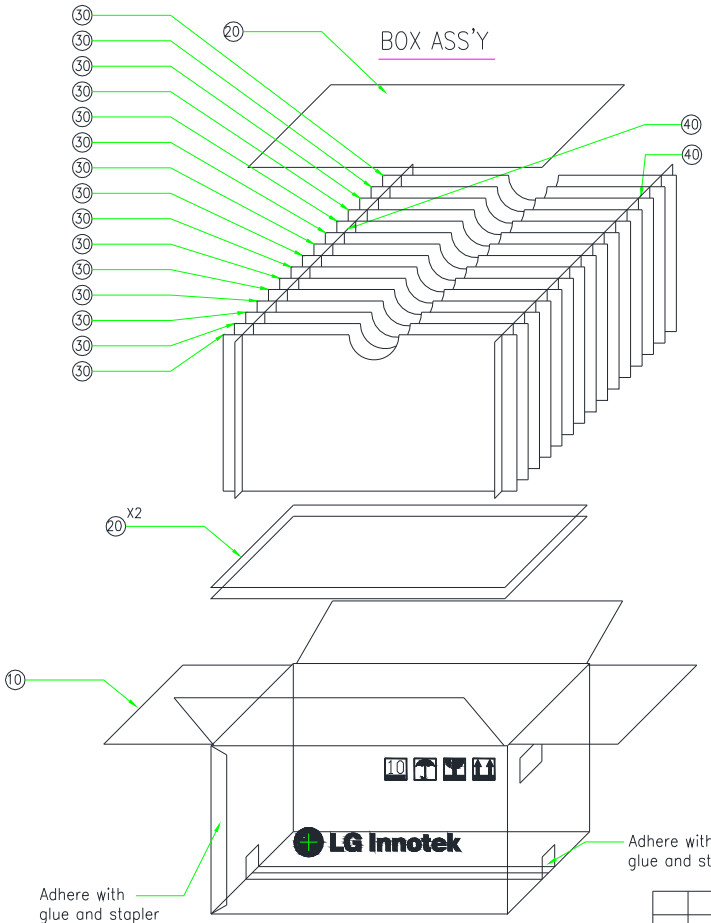
PART NO.	NAME	MATERIAL	SPEC.	FINISH	SIZE

UNIT	SCALE	Part no.
mm	1 : 5	3BBCAD0202A-R

APPD.	CHKD.	DSGD.	DRAW.	TITLE
2012.08.27 Kim Chang Sung			2012.08.27 Jeon Sung Ho	-

DOCUMENT NO. 3/4

ZONE	SYMB	DATE OR NO.	APPD	CHKD	DSGD
3-A	X1	2013.07.11 Change logo design	KHY		PBJ

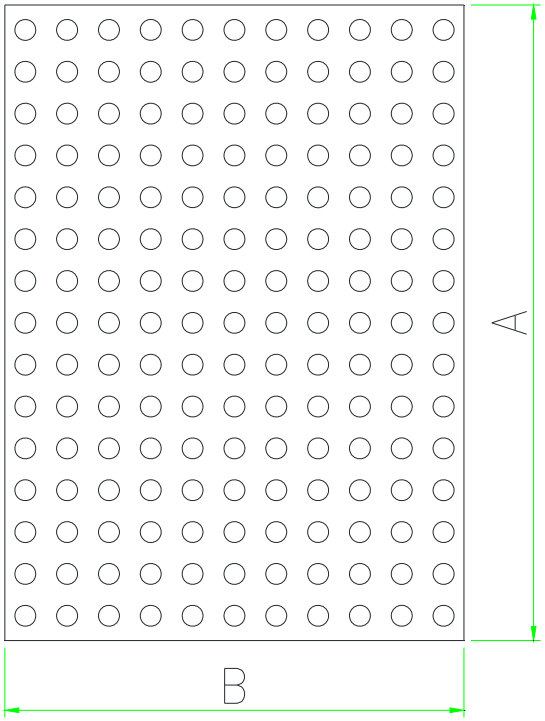


PART LIST

No.	PART NAME	QUANTITY	REMARK
10	OUT BOX	1	
20	Tray Board (506*341)	3	
30	Cross Board A (341*166)	15	
40	Cross Board B (506*166)	2	

PART NO.	NAME	MATERIAL	SPEC.	FINISH	SIZE
		UNIT mm	SCALE N/S	Part no. 3BBCAD0202A-R	
APPD. 2012.08.27 Kim Chang Sung	CHKD.	DSGD.	DRAW. 2012.08.27 Jeon Sung Ho	TITLE –	
				DOCUMENT NO. 4/4	

ZONE	SYMB	DATE OR NO.	APPD	CHKD	DSGD



NOTE
1. Material : LDPE
2. General tolerance :
3. COLOR : PINK
4. Antistatic finishing $^{+5}_{-5}$
5. Surface Resistance : 10^{6}~10^{11} Ohm/SQ
   All parts must not contain prohibited substances including RoHS azardous substances (Pb, Cd, Hg,Cr+6, PBB, PBDE) and for more details refer to LGIT's Eco-SCM standard,
6. LGIT (30)-K-029.

Part NO.	Thickness	"A"	"B"	Application Model	LGIT PCB Part Number
A	4 ±1.5	350	180	Pola 32", EPSU 32"39"42"	3EBECA0003A-R
B	4 ±1.5	350	220	Pola 37"39"42"	3EBECB0003A-R
C	4 ±1.5	350	280	Pola 47"50"55", LPB, EPSU47"55"	3EBECB0004A-R

PART NO.	NAME	MATERIAL	SPEC.	FINISH	SIZE

ZONE	SYMB	DATE OR NO.	APPD	CHKD	DSGD

UNIT mm | SCALE NS

APPD. 12.08.27 Kim Chang Sung | CHKD. | DSGD. | DRAW. 12.08.27 Jeon Sung Ho

TITLE: Air Vinyl for 13Y

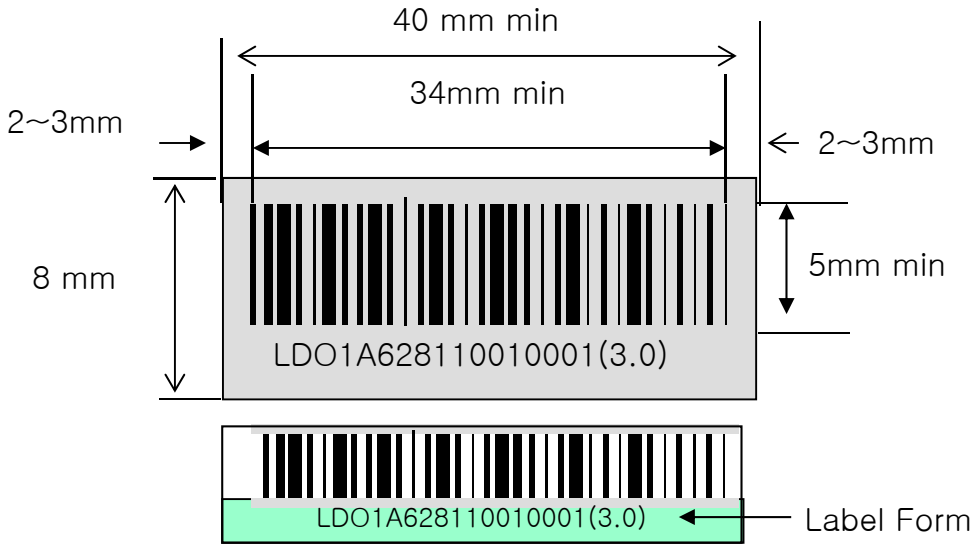
DOCUMENT NO. ———

LG Innotek Co., Ltd.

Bar-Code
Label Drawing

1. BARCODE Specification

1.1 Power Board Barcode specification



※ Bar Code Size는 그림의 size가 최소size이며, 업체 기준 및 PCB공간에 따라 변경 할 수 있으나, 그림의 size보다 줄일 수 는 없음.

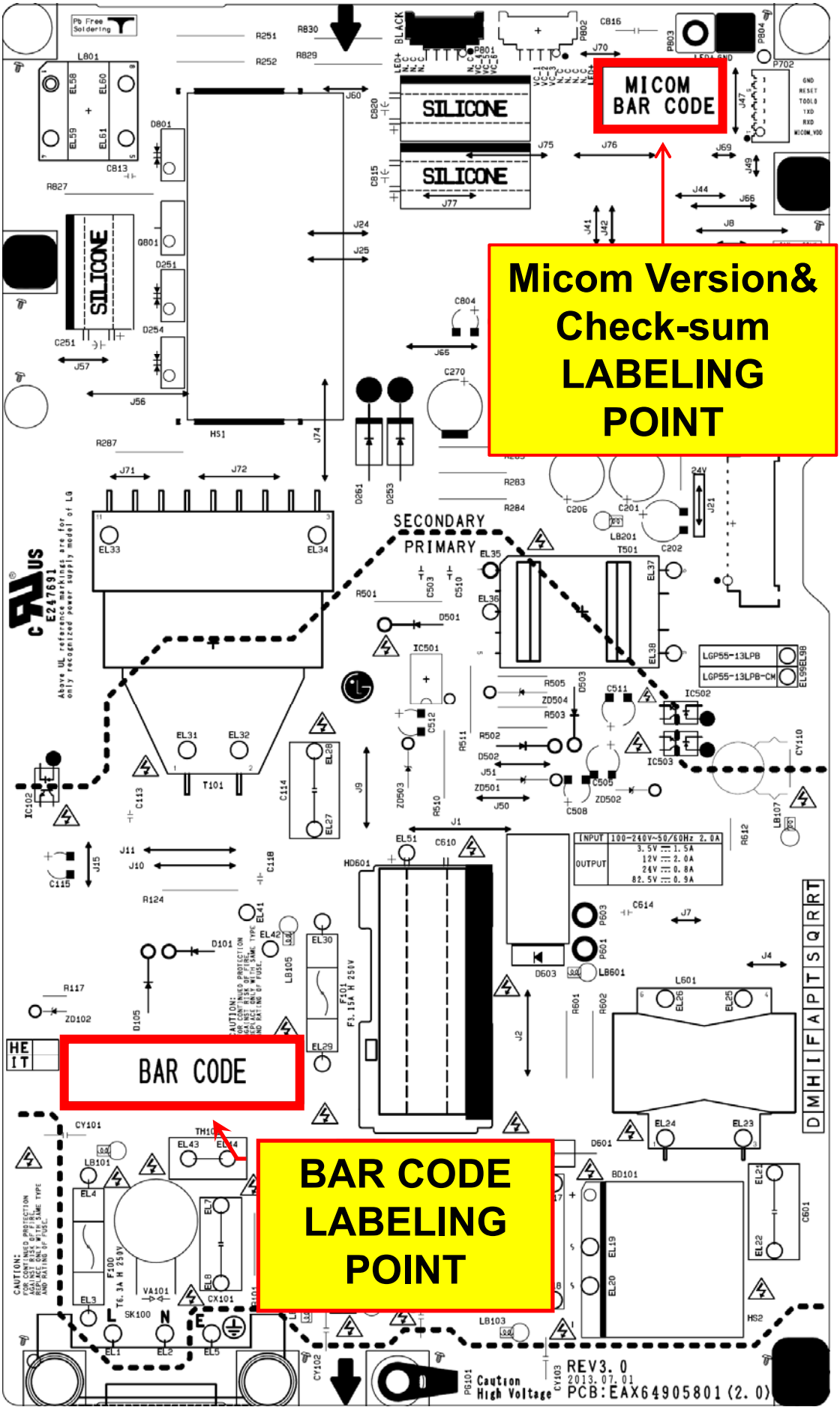
Code	Barcode Specification	Remark
Manufacturing code	L (L : LGIT)	
Manufacturing Year	D (D : 2013)	
Manufacturing Month	O (1,2,3,... 10:O, 11:N, 12:D)	
Manufacturing Date	1 (1~9,... A:10, B:11, C:12, ...X) * Don't USE : "I" ,"O" Character	
Manufacturing Line	A~D : Gwangju , E~N / 0~9 : Yantai , O~V : Indonesia , X~Z : Poland	
LG Part No.	62811001 (EAY62811001)	
Serial. No.	0001 (10Digit, 0001~9999)	
Rev. No	Approval Sheet Revision Number	
Barcode type : 93 code Barcode length : 17 digit Label size : 8 X 36 mm (minimize)		

※ BARCODE PRINTING : DO NOT ERASE, WHEN RUB BY HAND.

※ Label P/N : 3320KE0008B
Ribbon Black R300 P/N : 5250KR0011A

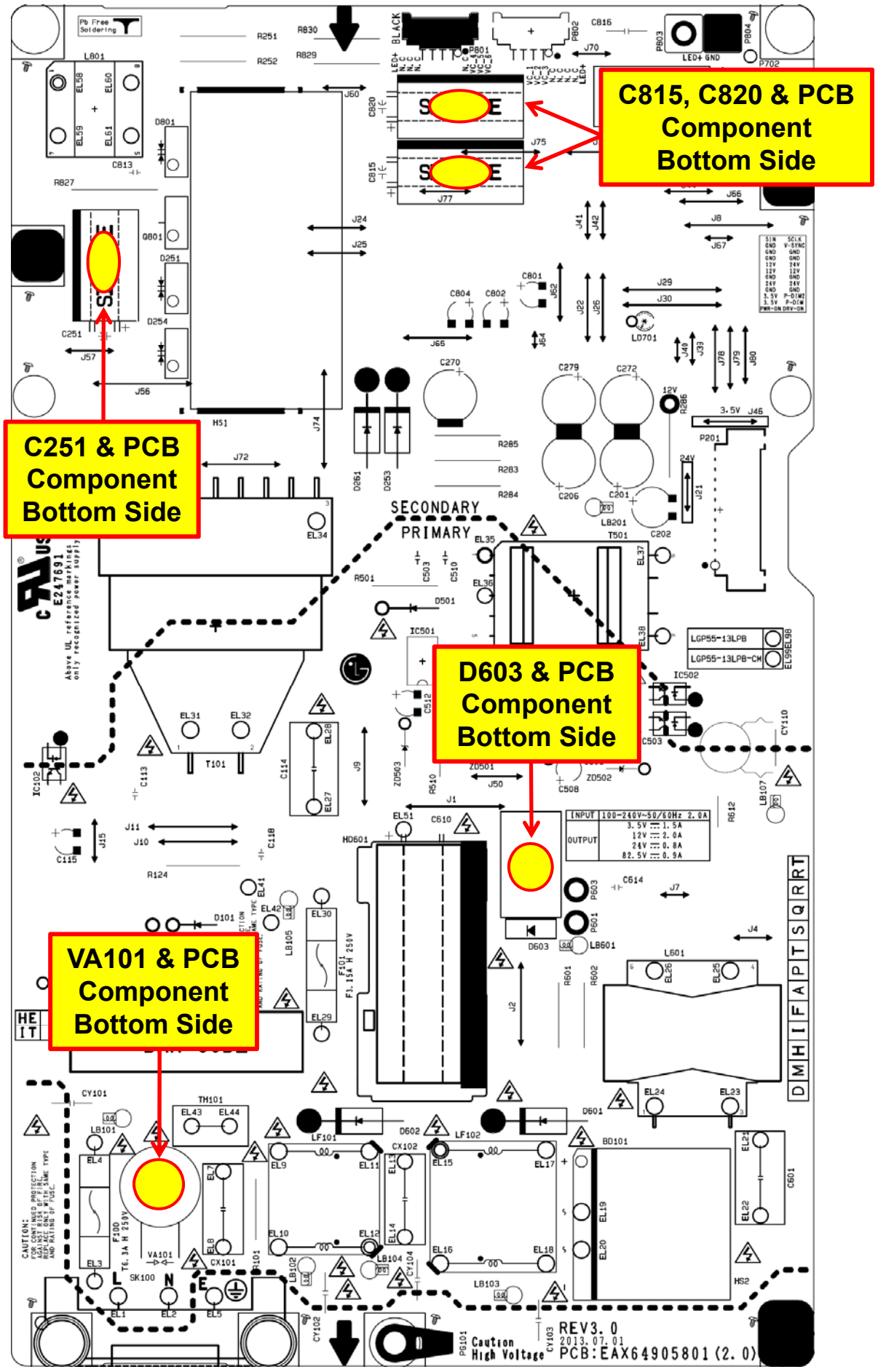
Labeling Point

LABELING POINT



Workmanship Point

Silicone Bonding Point ( )



Manufacturing Process

제/개정	일자	개정사유	개정No.
	11.08.24	최초제정	0

4M QC 공정도

작 성	검 토	승 인
/	/	/

관리 No. :
모델명 : PLDC-L203A, PLDC-L203B, PLDC-L231A, PLDC-L231B, PLDD-L204A, PLDF-L205A, PLDF-L205B
PLDF-L232A, PLDF-L233A, PLDH-L206A, PLDK-L208A, PLDF-L211A, PLDK-L212A

품목 :

제조사 : LGIT
작성자

작성일 : 12.04.24

공정번호		공정 흐름도	공정명	작업내용	4M				
					MAN (사람)	Machine (장비)	Material (재료)	Method (방법)	
자삽공정	1	▽	Incoming matrial]	[자재 준비] 해당 모델의 부품 부번과 수량을 확인하고 Box 해제 후 Tray에 적치		작업대, 이동대차, 라벨 프린터, 스캐너	부품	수량, 포장상태, 부번, Lot 상태, 일자	제조 정규 요청 리스트 월별 입출고 관리 리스트
	2	○	[Eyelet]	PCB에 Eyelet, GT Pin을 삽입		Eyelet M/C	Eyelet	Program명, 모델명 확인, 삽입 좌표 조정 에어압력: 5.0Kgf/㎠ ~ 이상	일상점검표 기종전환 Sheet 초품검사일지 수리일표
	3	○	[Jump Wire]	PCB에 Jump Wire를 삽입 후 클린칭		Jump Wire M/C 비전 검사(AOI) 버니어 캘리퍼스 각도 측정 지그	Jump Wire	Clinching 길이:1.5±0.3mm Clinching 각도:15~35° 중복 삽입, 미삽 없을 것	일상점검표 수리일보
	4	○	[Sequence]	Axial 자재를 순서와 극성에 맞게 Tape로 연결		Sequence M/C 버니어캘리퍼스	Axial 부품	테이핑 치수 : 54.5~55mm 부품 치우침 : 0.3mm 이하 부품 간격: 5mm	일상점검표 초품검사일지
	5	○	[Axial]	PCB에 Axial 부품을 삽입 후 클린칭		Axial M/C 비전 검사(AOI) 각도 측정 지그 버니어 캘리퍼스	부품 Seqence	Clinching 길이:1.2~1.5mm Clinching 각도:15~35° 탈삽, 미삽 발생하지 않을 것	일상점검표 초품검사일지 기종전환 Sheet 수리일보
	6	○	[이형 자삽]	PCB에 이형 부품을 삽입 후 클린칭		M10 M/C 버니어 캘리퍼스	이형 부품	Clinching 길이:1.2~1.5mm Clinching 각도:15~35° 부품 거리 : 6~6.5mm 탈삽, 미삽 발생하지 않을 것	일상점검표 초품검사일지 기종전환 Sheet 수리일보
	7	○	[Radial]	PCB에 Radial 부품을 삽입 후 클린칭		Radial M/C 버니어 캘리퍼스 비전 검사(AOI)	Radial 부품	투입 부품 부번, 용량, 방향, 위치 확인 Clinching 길이:1.2~1.5mm Clinching 각도:35° PCB와 극성 일치 탈삽, 미삽 발생하지 않을 것	BOM 일상점검표 기종전환 Sheet 수리일보

* Process Symbols : ▽(Incoming), ○ (Working Flow Chart), ◇ (Inspection), □ (Packing), ▷(Delivery)

제/개정	일자	개정사유	개정No.
	11.08.24	최초제정	0

4M QC 공정도

작 성	검 토	승 인
/	/	/

관리 No. :
모델명 : PLDC-L203A, PLDC-L203B, PLDC-L231A, PLDC-L231B, PLDD-L204A, PLDF-L205A, PLDF-L205B
PLDF-L232A, PLDF-L233A, PLDH-L206A, PLDK-L208A, PLDF-L211A, PLDK-L212A
품목 :
제조사 : LGIT
작성자
작성일 : 12.04.24

공정번호		공정 흐름도	공정명	작업내용	4M				
					MAN (사람)	Machine (장비)	Material (재료)	Method (방법)	
SMT	1	▽	[자재준비]	[자재 준비] 해당 모델의 부품 부번과 수량을 확인하고 Box 해제 후 Tray에 적치		입고도장 제습함 부품보관대/이동대차 바코드 스캔	부품	수량, 포장상태, 부번, Lot 상태, 일자 LGIT P/N Label 확인 BOM/MSD Level	제조 정규 요청 리스트 월별 입출고 관리 리스트
	2	○	[Solder Cream]	Solder Cream 보관 및 사용		냉장고 Thermometer	Almit (LFM-48W TM-HP(L)) :Sn-Ag3.0-Cu0.5	온도 관리 한계 : 1~10℃ ~(미개봉시) 생산일시 6개월가지 사용가능 상온방치 2시간이상 교반시간 60초 ~120초	냉장 온도 관리 Sheet 관리라벨 사용 이력 관리
	3	○	[Chip Bond]	Chip bond 보관 및 사용		냉장고 Thermometer	Chip Bond	온도 관리 한계 : 1~10℃ 상온방치 2시간이상	일상점검표 수리일보
	4	○	[본드 인쇄]	Stencil Mask를 Printer에 장착하고 그위에 Bond를 투입한 후 PCB를 Loader로부터 공급 받아 Squeegee로 칩접착제를 정위치에 인쇄		Mask Bond 인쇄기 Squeegee	Chip Bond	마스크 번호 Mask 두께: 3.0T 2012 홀 사이즈 : 0.8mm 3216 홀 사이즈 : 1.2mm	마스크 입고시 확인
								접합착제 모델명 : PT-130DL 초도 생산시 투입량 : 300g 2Hr마다 양 체크 후 보충 : 100g~250g	투입 Check Sheet
								스퀴즈의 압력과 속도 조정 (조건표) 인쇄 상태 확인 Squeegee No. (조건표) 마스크 세척	모델별 조건표 교대/기종전환 Check Sheet Manual 세척 이력 관리 Sheet
	5	○	[Chip Mount]	칩 본딩된 PCB 위에 Chip 장착		Chip Mounter	부품	BOM, 도면 확인 자재 교환 Check Mounting 상태 확인 Pick-up 상태 확인	초품검사일지 MES PDA 교대/기종전환 Check Sheet 부품 Loss율 기록표 일상점검표
	6	○	[이형 Mount]	칩 본딩된 PCB 위에 이형 부품 장착 PCB에 장착된 부품 삽입 상태 검사(AOI)		Multi Mounter AOI	부품	BOM, 도면 확인 자재 교환 Check Mounting 상태 확인 Pick-up 상태 확인 OK, NG Sample로 장비 검증	초품검사일지 MES PDA 교대/기종전환 Check Sheet 부품 Loss율 기록표 AOI 검사 불량 관리 Sheet 일상점검표
	6	○	[Reflow]	PCB에 부착된 부품을 고정하기 위해 접착제를 경화		Reflow M/C Profile Jig Push/Pull Gage		생산 모델과 프로그램을 일치 할 것. 프로파일 온도 조건표와 프로파일을 확인한다. 최고 온도 : 140도 이하 / 120Overtime:70~100초	작업지도서 온도 프로파일 일상점검표 교대/기종전환 Check Sheet
								Chip 접합 강도 1608 : 1.0kgf 이상 2012 : 1.3kgf 이상 3216 : 1.5kgf 이상	접합 강도 측정 Sheet

* Process Symbols : ▽(Incoming), ○ (Working Flow Chart), ◇ (Inspection), □ (Packing), ▷(Delivery)

제/개정	일자	개정사유	개정No.
	11.08.24	최초제정	0

4M QC 공정도

작 성	검 토	승 인
/	/	/

관리 No. :

모델명 : PLDC-L203A, PLDC-L203B, PLDC-L231A, PLDC-L231B, PLDD-L204A, PLDF-L205A, PLDF-L205B PLDF-L232A, PLDF-L233A, PLDH-L206A, PLDK-L208A, PLDF-L211A, PLDK-L212A	품목 :	제조사 : LGIT 작성자	작성일 : 12.04.24

공정번호		공정 흐름도	공정명	작업내용	4M				
					MAN (사람)	Machine (장비)	Material (재료)	Method (방법)	
수삽 / 포장	1	▽	[자재준비]	[자재 준비] 해당 모델의 부품 부번과 수량을 확인하고 Box 에제 후 Tray 에 적치		입고도장 제습함 부품보관대 이동대차	부품	수량,포장상태, 부번, Lot 상태, 일자 LGIT P/N Label 확인	제조 정규 요청 리스트 릴별 입출고 관리 리스트
	2	○	[Manual Insertion]	바코드 라벨 발행		PC Barcode 라벨 프린터 스캐너	라벨	라벨 검증	MES 작업지도서
	3	○	[수삽공정]	PCB에 부품 삽입		수삽 컨베이어 납땜지그 부품적치대/부품대차 매거진 PC/스캐너	부품 실리콘	납땜 지그 화살표와 PCB 진행 화살표 일치 PCB 부번 확인 부품 삽입 상태 확인 라벨 실크 Box 내 삽입 실리콘 규격 도포 실시	작업지도서 외관 검사 기준서 일상점검표 표준샘플 초품검사일지
	4	○	[Flux공정]	PCB 하단에 Flux 분사		Flux M/C 비중계	Flux	Flux 비중: 0.823±0.005 Flux 분포 및 노즐 상태 확인	일상점검표
	5	○	[WaveSoldering 공정]	Soldering		Wave Soldering M/C Solder 자동 공급기 Wave Checker	Solder	Preheater온도: 110±10℃ Pot 1차: 257±3℃ Pot 2차: 257±3℃ 납조 성분 Check -Cu: 12,000 ppm -Pb : 800ppm 이내 DPU 관리	Soldering 일상 점검 일지 작업지도서 ICP 성분 Data 납조 변경 이력 관리대장 Solder 투입 관리표
	6	○	[납땜 검사 및 수정 공정]	Soldering 된 제품 납 땜 상태 검사 및 수정		인두기 인두 온도 측정기 수정 컨베이어	제품	외관검사 기준을 참고 하여 전면 검사 실시 인두기 온도: 330±20℃ 인두기 누설전압: 10mV 이하	외관 검사 기준서 인두 일상 점검표 작업지도서
	7	◇	[ICT 공정]	PCB에 장착된 부품 상태 검사		ICT M/C (AT-01) Fixture PC	제품	모델명, 프로그램 확인 부품 규격 확인	일상점검표 작업지도서 BOM
	8	◇	[동작검사]	제품 동작 검사		Fixture 계측기 Inline 설비, PC Barcode Scanner	제품	모델명, 공정 확인 Program Version 확인 Check Sum값 확인 (Check sum:0xBEA5C) 제품 전기적 특성 측정 표준 샘플로 OK/NG 확인	MES Program 자동 확인 승인원(전기적 특성 Spec) 일상점검표
	9	◇	[내압검사]	제품 내압 검사		Fixture 내압기 Inline 설비	제품	표준 샘플로 OK/NG 확인 내압 검사 실시	승인원(내압 Spec) 일상점검표
	10	○	[실리콘도포]	실리콘 도포		Dispenser	실리콘	제품별 도포위치	작업지도서 일상점검표
	11	◇	[Aging공정]	제품 Aging 검사		Aging M/C Select Card 유사부하 Cable	제품	온도, 시간 확인 합격 기준 확인	MES 작업지도서 일상점검표
	12	◇	[최종외관검사]	제품 외관 검사			제품	외관검사 기준을 참고 하여 검사	외관 검사 기준서 작업지도서
	13	◇	[특성검사]	제품 특성 검사		Fixture 계측기 Inline 설비, PC Barcode Scanner	제품	모델명, 공정 확인 Program Version 확인 제품 전기적 특성 측정 표준 샘플로 OK/NG 확인	MES Program 자동 확인 승인원(전기적 특성 Spec) 일상점검표
		□	[포장]	제품 포장		Barcode Scanner PC	제품 Box 에어비닐	모델명, Barcode 확인	MES 작업지도서

* Process Symbols : ▽(Incoming), ○ (Working Flow Chart), ◇ (Inspection), □ (Packing), ▷(Delivery)

Appendix List

No.	Contents	Total Page number
1	Power Check list	9 Page
2	Warranty letter	2 page

Appendix 1.

POWER CHECK LIST

	Revision History	Rev	DATE	REMARK
1	기존 PCB Check Sheet Ver1.9 에서 신규 Power Check Sheet Ver1.0 으로 개정 함	1.0	2011.06.02	
2	1. 필수 Marking사항 - 14번 항목 추가 2심일 경우 PSU 2심 기기 규격마크 체크항목 추가 2. Component - 13번 항목 추가 누운 type의 choke coil일 경우 유동에 따른 lead 설삽 발생 방지를 위해 중점 검사 항목 지정 관리함	1.1	2012.05.23	
3	1. PCB pattern 간격 - 9번 항목 추가 IT / TV PCB 공용을 위해 GND pattern 두께 8.5mm or Jump wire 삽입 내용 추가	1.2	2012.10.30	

Details Check Item		RESULT		REMARK
▶ 부품 LOCATION NO.		OK	NG	
1	Power 1차측 회로 Location No.가 100번대 일 것 (Multi 1차측 포함)	OK		
2	Power 2차측 회로 Location No.가 200번대 일 것 (Stand by 2차측,Multi 2차 포함)	OK		
3	Inverter 1차측 회로 Location No.가 300번대 일 것	OK		
4	Inverter 2차측 회로(F/B,OVP회로부 포함) Location No.가 400번대 일 것	OK		
5	Stand by 1차측은 Location No.가 500번대 일 것	OK		
6	PFC단은 Location No.가 600번대 일 것	OK		
7	MICOM 주위는 Location No.가 700번대 일 것	OK		
8	LCD : LED Driver 단은 Location No.가 800번대 일 것	OK		LCD 에만 적용함
9	PDP : STBY 1,2차단은 Location No.가 300번대 일 것	OK		PDP 에만 적용함
10	PDP : Va 2차단은 Location No.가 500번대 일 것	OK		PDP 에만 적용함
11	PDP : Vs 2차단은 Location No.가 900번대 일 것	OK		PDP 에만 적용함
12	PDP : Vs,Va 1차단은 Location No.가 800번대 일 것	OK		PDP 에만 적용함
13	CTV : Power Block은 Location No. 800번대 일 것	OK		CTV 에만 적용함
14	Resistor의 회로Location No.는 R***로 시작할 것	OK		
15	Capacitor의 회로Location No.는 C***로 시작할 것	OK		
16	Diode의 회로Location No.는 D***로 시작할 것	OK		
17	Zener Diode의 회로Location No는 ZD***로 시작할 것	OK		
18	Coil의 회로Location No.는 L***로 시작할 것 (PFC 포함)	OK		
19	Transformer의 회로Location No.는 T***로 시작할 것(Drive Trans 포함)	OK		
20	Bead의 회로Location No.는 LB***로 시작할 것	OK		
21	Fuse의 회로Location No.는 F***로 시작할 것	OK		
22	TR/FET/Thyristor의 회로Location No.는 Q***로 시작할 것	OK		
23	Varistor의 회로Location No.는 VA***로 시작할 것	OK		
24	Volume Resistor의 회로Location No.는 VR***로 시작할 것	OK		
25	Jumper의 회로Location No.는 J***로 시작할 것	OK		
26	H/S의 회로Location No.는 HS***로 시작할 것	OK		
27	IC의 회로Location No.는 IC***로 시작할 것	OK		2007.04.16 DDC 표준

	Details Check Item	RESULT		REMARK
	▶ 부품 LOCATION NO.	OK	NG	
28	Connector wafer / Ass`y (Board in type)의 회로 Location No.는 P***로 시작할 것	OK		
29	Eyelet의 회로Location No.는 EL***로 시작할 것	OK		
30	Gripper의 회로Location No.는 G***로 시작할 것	OK		
31	Holder의 회로Location No.는 HD***로 시작할 것	OK		
32	Thermistor의 회로Location No는 TH***로 시작할 것	OK		
33	Metal Ground의 회로Location No.는 PG***로 시작할 것	OK		
34	Line Filter의 회로Location No.는 LF***로 시작할 것	OK		
35	AC Socket(Inlet)의 회로 Location No.는 SK***로 시작할 것 **(AC전원 Docking용 Wafer 포함)**	OK		2007.04.16 DDC 표준
36	Photo Coupler의 회로Location No는 IC***로 시작할 것	OK		2007.04.16 DDC 표준
37	Relay의 회로 Location No.는 RL***로 시작할 것	OK		
38	Y-Capacitor의 회로Location No는 CY***로 시작할 것	OK		
39	X-Capacitor의 회로Location No는 CX***로 시작할 것	OK		
40	Fuseble Resistor의 회로Location No는 R***로 시작 할 것	OK		
	▶ PCB Pattern 간격	OK	NG	
1	Primary ⇔ Secondary(GND,Y-Cap,Photo Coupler) 간격이 **Creepage 기준을 만족할 것.(규격Gr. 안전규격 Check List 참조.Note 0)** (단, Working Voltage가 350V이상일 때 규격 요청 거리에 따른다.)	OK		첨부화일 참조. (Creepage) NOTE 0  Creepage
2	Primary(L,N) ⇔ Safety GND 간격이 3mm이상일 것 **(단, 2심일 경우 6mm 이상 일 것)**	OK		
3	Live ⇔ Neutral 간격이 **3mm** 이상일 것	OK		
4	Primary ⇔ Secondary 부품간 공간 거리는 **6mm**이상일 것 (6mm 이하일 경우에는 insulation sheet 추가)	OK		
5	1차측 Main Current loop는 Pattern 두께 3mm 이상일 것 **(BD ↔ 1차 평활 Cap까지 중점 Check)**	OK		
6	PFC Coil 밑으로 소신호 Line이 지나가지 말 것. DC는 문제 없음	OK		
7	주 GND(AC 평활 Cap. GND) 에서 IC GND 연결 시 Pattern Impedance 를 고려하여 pattern을 분리 할 것.	OK		
8	DIP Type St-By IC 일 경우 고압Pin과 근접Pin 간의 이격거리 확보 할 것. - Drain pin과 인접된 pin은 N.A나 공 pin 일 것.	OK		
9	FG GND 접지 연속성(40A/2분) test 만족 시킬것. →TV PSU 설계 단계에서 IT Safety 기준으로 설계. (GND pattern 두께 8.5mm 설계 or Jump wire 삽입, **EMI 문제 발생시 Skip 할수 있음**)	OK		

	Details Check Item	RESULT		REMARK
▶ Component		OK	NG	
1	Surge Test 시 1~2차간 간격이 **6.0mm**㈜ 이상일 것 (safety GND와 2차 GND의 구별 주의 (절연 Y-Cap사용) 공간확보 주의, 절연Sheet)	OK		(주) 3심:3.0mm 이상 (내압 test 必) 2심:6.0mm 이상 (Y-cap 포함)
2	전해 Cap(전수) 부품 주위 **발열 부품**과 **3mm**이상 이격 시킬 것 **(공간거리)**	OK		
3	1차 평활 전해 Cap 부품 upper 영역은 1mm이상 Bottom 영역은 5mm 이상 이격 시킬 것 (Vertical type Capacitor에 한함) (Note 1)	OK		PSU가 수직 장착 모델에 한함.
4	1차 평활 Cap 3mm 영역 내 아래로 Pattern이 지나가지는 않을 것 (양면 PCB 상측 Pattern에 한함)	OK		
5	높이가 낮은 코어를 사용할 경우 절연 tape를 사용할 것 (PCB와의 이격거리 확보)	OK		1,2차 절연형 Trans 에 한함
6	Trans의 경우 300V 기준으로 Barrier 8mm이상 사용하고 있을 것 (Note 0) (Barrier를 줄이기 위해 Wire에 Tube 사용가능, **규격 GR. 필 확인 사항)**	OK		첨부화일 참조. (Creepage)
7	AC Inlet의 경우 Yellow - Green wire의 Screw 3.5Φ 이상일 것. * Y/G wire를 사용하지 않을 경우, PCB Pattern으로만 대응 시엔 200A Test통과할 것 * Safety GND는 독립적으로 GND역할만 하도록 할 것. UL Test의뢰 *** Pattern 대응 시엔 반드시 규격 확인을 할 것**	OK		
8	부품에 힘을 가했을 때 1~2차 부품간 6mm 공간 거리 확보할 것. Core에 절대로 부품이 접촉되면 안됨	OK		
9	Box type Capacitor 사용 시 Forming type이 적용할 것. RTV Bond가 되어 있을 것 (X-capacitor 포함.) **단, PDP Sony 모델에 한함**	OK		
10	CORE(Trans류 All 포함) 주위에는 2mm 이상 전 부품을 이격 시킨다. * 유기전압 1kV (peak to peak) 이상 시엔 4mm 이상 (1000:1 Probe 기준)	OK		
11	Inverter Trans와 Metal Frame(shield)과 4mm 이상 이격을 시킨다. (적용이 어려울 경우, 반드시 Insulation sheet 추가한다.)	OK		
12	2차 측 출력 Wafer 는 고정 PIN 추가 TYPE 적용 할 것 (단, LPB 일 경우 Micom Deberging 용 Wafer 는 제외)	OK		
13	누운 type의 choke coil일 경우 유동에 따른 lead 설삽 발생 방지를 위해 중점 검사 항목 지정관리를 한다.	OK		첨부화일 참조. (choke coil)

NOTE 0  Creepage

NOTE 1  CAPACITOR

NOTE 2  Choke coil

Details Check Item		RESULT		REMARK
▶ 필수 Marking 사항		OK	NG	
1	AC Socket, AC입력용 Wafer에 L/N표시는 되어 있을 것. (Docking Type도 L/N 표시(QA 요청), 상,하측 모두 표시) 특히, Socket B/D-in type의 경우, AC socket 자체에 L/N 표기가 되어 있으므로, 반드시 PCB L/N 마킹과 동일한지 확인한다. (Note 3-2)	OK		Fuse 는 Live 단에 위치 할 것
2	Safety GND는 Chassis로 부터 분리될 때 작업자가 확인 가능한 위치일 것. (Note 2) * **추후, PCB 상,하면에 모두 표기, 상세한 내용은 하단의 유첨 파일 참조 요망, 그리고, 반드시 규격에 최종 확인 받을 것.**	OK		2심은 제외함
3	Fuse rating(전압,T,전류,H), caution(규격 문구), UL Mark는 입력되어 있을 것 Ex) T5A H 250V 형식으로 표시함 *** caution: UL에 등록되어있는 문구가 그대로** 입력되어야 함 **(For ~ , Replace ~)**	OK		
4	Fuse가 보이는 곳에 위치할 것 (Fuse Marking도 보이는 곳에.)	OK		
5	High Voltage warning mark가 입력되어 있을 것. - Inverter 출력부 : LIPS에 한함 Inverter 출력부 영역 표시하고 Warning mark 추가. - Primary측 Metal.(H/Sink), High Voltage가 open된 곳.(Fuse) : 공통	OK		
6	입력/출력 전압, 전류 Spec표기는 되어 있을 것 (Note 3)	OK		
7	1차측과 2차측 구분하는 Marking 표시할 것. (상측면 / 하측면)	OK		
8	각 부품의 회로No.가 부품에 가려지지 않을 것	OK		
9	Solder pattern에 하측 회로No./부품 형상 등 겹쳐지지 말 것	OK		
10	기구 Dead Space가 고려되어 PCB Marking할 것. PCB 고정용 Metal 영역 표시할 것.	OK		
11	PCB 사양서에 CTI Spec 이 있는지 확인하고, PCB 에 마킹 되었는지 확인 할 것. - 표기 값 : 600V 이상 (CTI 600)	OK		
12	Critical Component List 기준으로 회로도에 Caution 마크 넣을 것 ⚠	OK		
13	PCB 에 Screw 마크 넣을 것	OK		
14	PCB 에 2심 기기 규격 마크 넣을 것	OK		단, 2심 일 경우에만 적용함

NOTE 2 Safety GND 규정

NOTE 3 Input/Output

NOTE 3-2 B/D-in socket

	Details Check Item	RESULT		REMARK
▶ EMI		OK	NG	
1	Lightning Surge가 L/N Test 시 Varistor를 14Φ 620V 이상 사용할 것	OK		
2	Lightning Surge가 L/G, G/N간 : 3KV이상 시 Y-Cap. Y1급 사용할 것	OK		
3	Lightning Surge 로 인해 Fuse Dead시만 OK. (대책 : arcing을 방지,Varistor는 Fuse와 가까운 곳에 위치할 것)	OK		
4	GND Arcing pattern Slit은 1.2mm일 것 Arcing Pattern 양단 거리는 safety규정은 최소 3.0mm 이상 일 것 (L/N 사이)	OK		
5	Conducted Emission 측정조건 : 110Vac/220Vac & 50Hz/60Hz TV Model : GND 有/無, Vivid/Standard, HDMI/Antenna	OK		
▶ INVERTER (LIPS에 한함)		OK	NG	
1	Ballaster capacitor 사용할 것			
2	Inverter Trans로 부터 주변 4mm 이내에 소신호 AC pattern이 지나갈 시에는 OVP/OLP 등 Worst 상태를 반드시 확인하여 이상이 없을 것 (Feed Back Line 포함) [AC입력으로 부터 Inverter에 간섭 되는 noise 를 줄이기 위해 POWER FET의 Heat Sink 를 형상 변경하여 AC 입력부와 Inverter Trans 간 Shield로 사용. (CE 규제사항) - Design 상 고려되어야 함.]	-		
3	Inverter 출력부에 적용한 고압 Capacitor의 Lead는 인위적 힘을 가하여도 주변 부품과 Touch 되지 않도록 절연 거리 확보 or Bodning 적용할 것. (특히, 다른 고압 Capacitor의 body와 touch 되지 않도록 할 것)	-		
4	Inverter Trans Gripper 및 Eyelet 부위 Size 확인할 것. - Pin 동박 Size : 5.5mm - Pattern Size 확대 : 6mm (단, 32인치 이상 LIPS 에만 적용함)	-		
5	고압 Inverter wafer 는 수평 Type 일 것.	-		

Details Check Item		RESULT		REMARK
▶ 기타		OK	NG	
1	Fuse 깡통(CAN)Type 을 사용하지 말 것.	OK		
2	Main Board/Power Board(LIPS 포함) 연결 Connector의 Housing과 Wafer의 Maker가 일치할 것. *일치가 안될 경우, Spec.확인 및 QA 인증 시험이 요구됨.(특히,Board in connector는 Terminal도 확인)	OK		
3	Litz Wire 사용하지 말 것.	OK		USTC
4	PFC Bypass Diode가 적용되어 있을 것. (Note 4)	OK		첨부화일 참조(Bypass)
5	Inrush 제어용 Relay 적용 모델인 경우, Fusing Resistor 적용 확인할 것.(Note 5) (단, Fusing Resister 미적용 시 Relay Open Test 확인 하여, PL 조건 만족할 것)	OK		첨부화일 참조(Relay)
6	1차 Control IC의 IC Vcc 정류Cap.은 High Ripple, Low Impedance Cap. 사용할 것.	OK		
7	RN Type (Metal Film Type) Resistor는 100kohm이상 사용하지 말 것.	OK		08년 6월 26"MNT ND 분 양산 문제 발생. (여러 차례 재발됨)
8	TO-220, TO-3P type FET, Diode, IC 적용 시, Forming type 을 적용했을 때 forming 후 cutting을 하기 때문에 길이가 짧아진다. 따라서 반드시 Heatsink 와 PDM 등록 승인원, 부품 현물을 3자 확인 후 lead 길이, pitch 확인할 것. (LGEAZ, LGEND 관련하여 사전 협의 필요 LGEND 에서는 forming type 을 전수 원함)	OK		08년 3월 LGEAZ CKD 분 PQ 이전 문제 발생하여 지급 조처 한 이력 있음.
9	PCB하측 lead 길이 special 관리 모델의 경우 (예를 들어 2.0mm 관리 품) H/Sink, wafer, 각종 부품 도면 받아서 lead 길이 check 할 것	OK		
10	Critical Component List 의 부품인 경우 실물에서 형명 마킹 제대로 되어 있는지 확인 할 것	OK		
11	일본향 모델에 사용되는 방전저항은 규격 인증된 Dip Type 저항만 사용 할 것. (단, 일본향 모델에 한 함)	OK		

NOTE 4  Bypass-Diode

NOTE 5  Relay

Details Check Item		RESULT		REMARK
▶ Attachment		OK	NG	
1	PL check List  안정성 :L_LGP55-13LPB(EAY62811001)_MP	OK		

Appendix 2.

WARRANTY LETTER

비사용 증명서

구분	☐ 승인용 ☑ 양산용	제출일자	2012 . 12 . 17

협력회사				
회사명	LG 이노텍	결재	담당자	부서장
연락처	Tel 062-950-0232	성명	김 인 재	김 형 성
e-mail	ijkim@lginnotek.com	서명		

부품정보			
LG전자 P/No.	EAY62811001	부품제조일자	
Maker P/No.	PLDK-L212A	생산 공장	LGIT Yantai, Poland
부품명(품명)	LGP55-13LPB		

당사가 납품하는 납입품 및 당사 제조 공정상 사용되는 물질이 아래 Check 항목에 대해 만족함을 증명합니다.

——— 아 래 ———

☑ ROHS 규제 6대 물질(Pb, Cd, Cr^{6+}, Hg, PBBs, PBDEs)이 LG전자 Display 사업부 기준을 만족함

※ 아래 항목은 PCB(Printed Circuit Board)에 장착되는 부품일 경우 기록 요망

Soldering Type : ☑ Flow ☐ Reflow

최대 내열성 온도 : 260 ℃ 최대 내열성 시간 : 10 sec.

☑ Pb-Free Soldering (Solder Cream, Bar, Wire 모두 포함) 적용이 가능함

Note.

1. 본 자료 상의 모든 기재 내용은 사실에 근거하여 작성하여야 하며, LG전자가 근거 자료를 요구 시, 관련 Data를 제출하여야 한다.

2. 본 자료가 승인용으로 사용될 경우 Sample과 함께 제출하고, 양산용으로 사용될 경우 초품 입고시 제출하여야 한다.

3. LG 전자 Display 사업부에 공급되는 PCB 장착 부품의 내열 기준은 다음과 같음.
   Flow 부품 : 260℃/10 sec , Reflow 부품 : 250℃/10 sec

LG Electronics